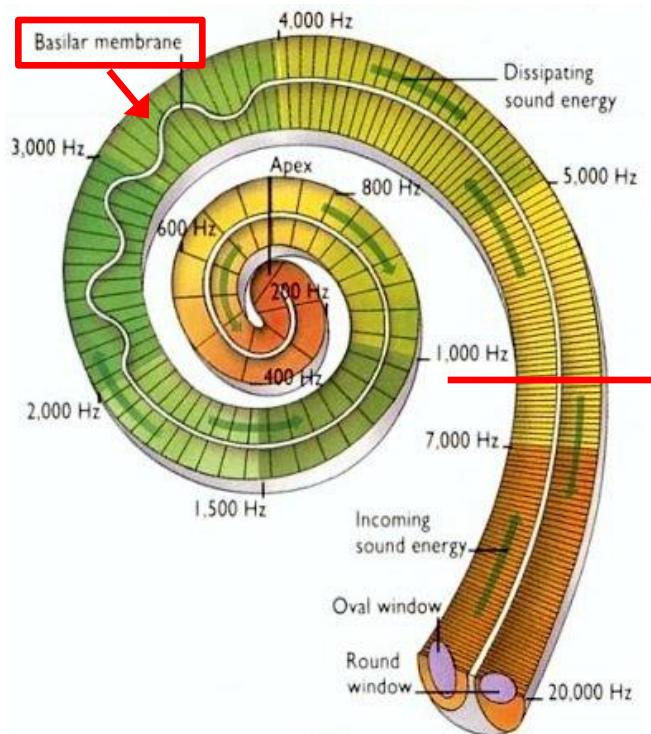
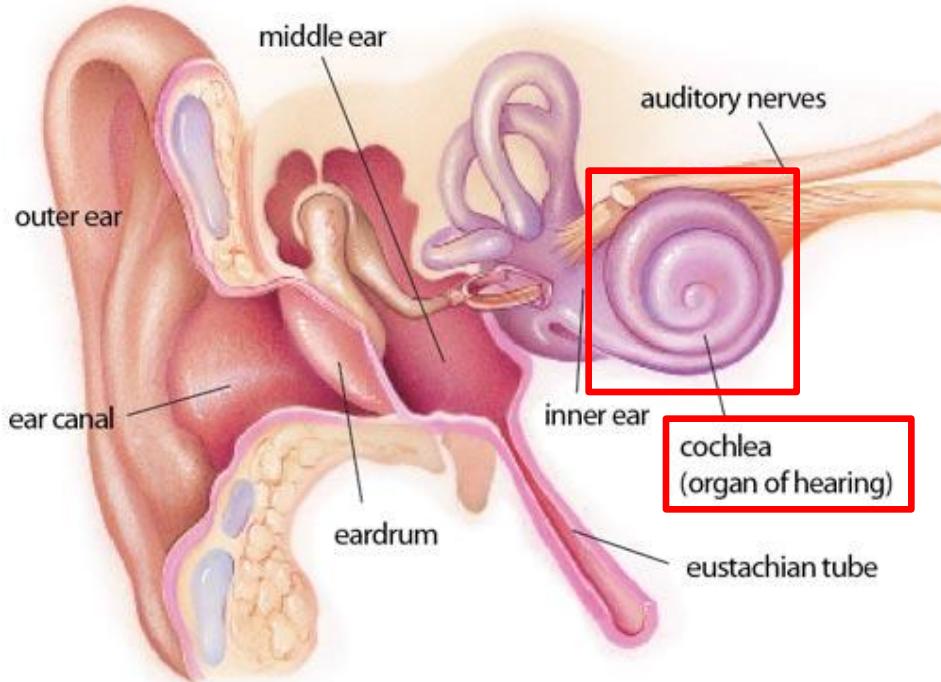
A grayscale scanning electron micrograph (SEM) showing several parallel, elongated, rectangular structures. These structures appear to be microelectromechanical systems (MEMS) force probes, characterized by their layered, etched appearance and sharp, tapered tips. They are arranged in a staggered pattern across the frame.

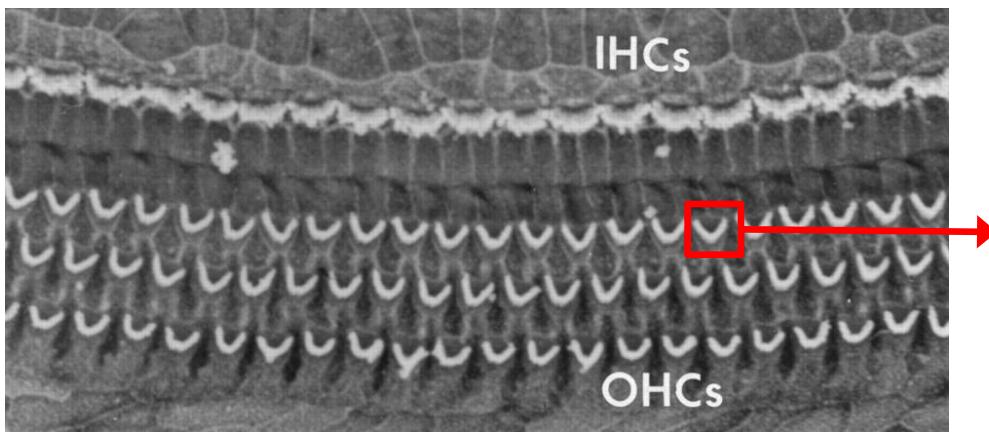
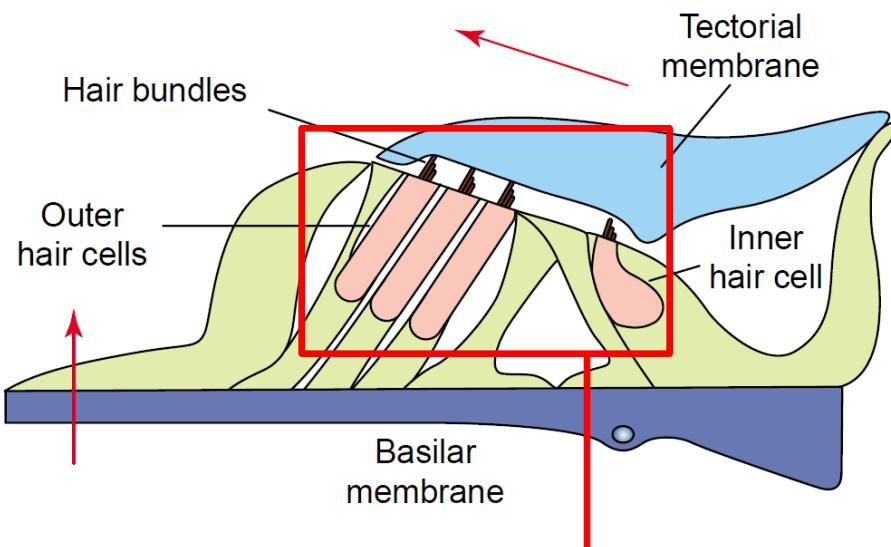
# MEMS Force Probes for Mechanobiology at the Microsecond Scale

Joey Doll  
PhD Dissertation Defense  
March 7, 2012

# Outline

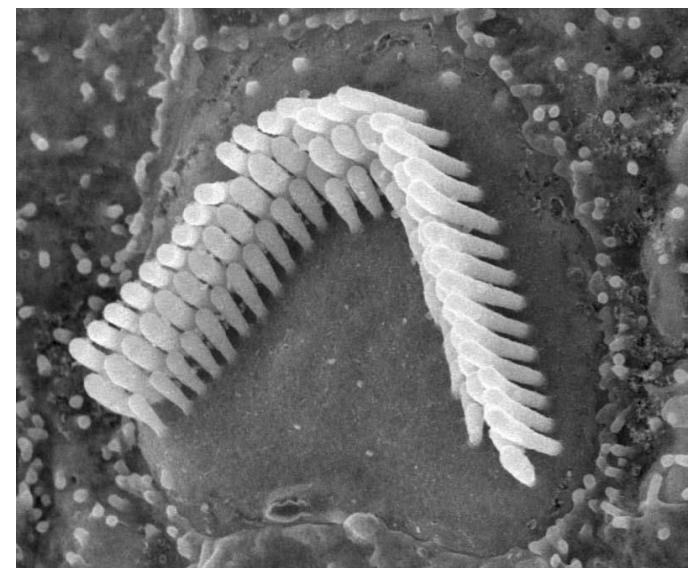
- 1) How hearing works and why we need a fast force probe
- 2) Probe design, fabrication and characterization
- 3) System integration and hair cell measurements



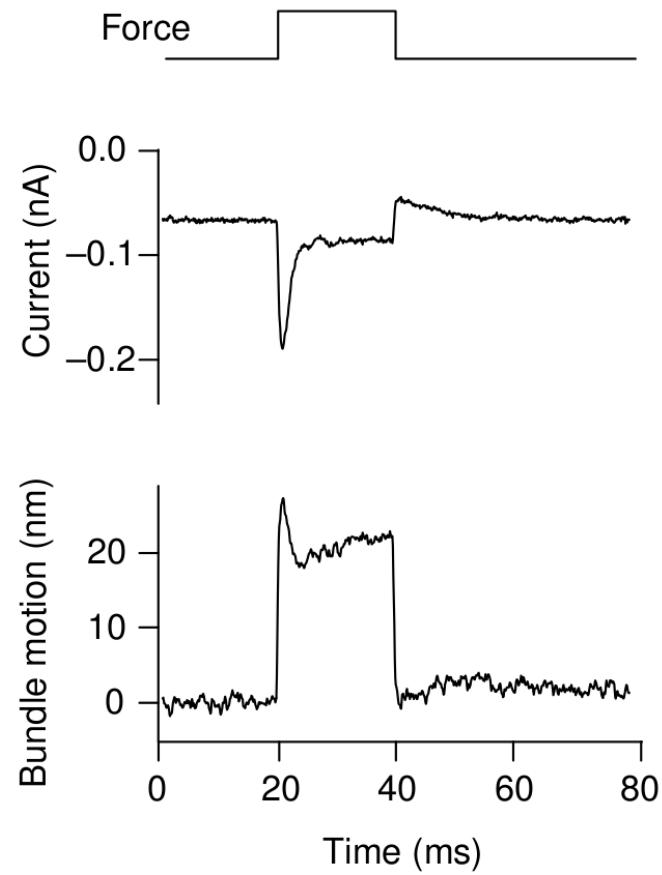
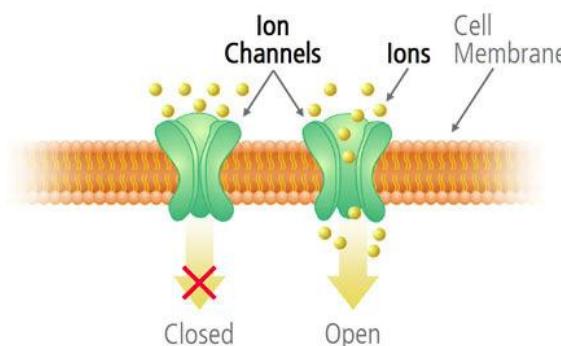
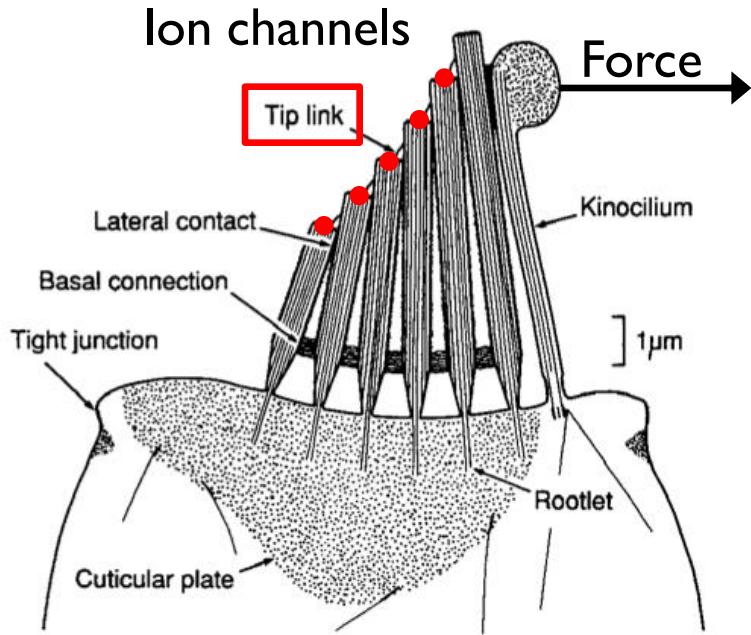


Inner hair cells (IHCs)  
Convert sound into  
electrical signals

Outer hair cells (OHCs)  
Mechanical amplifiers  
and filters

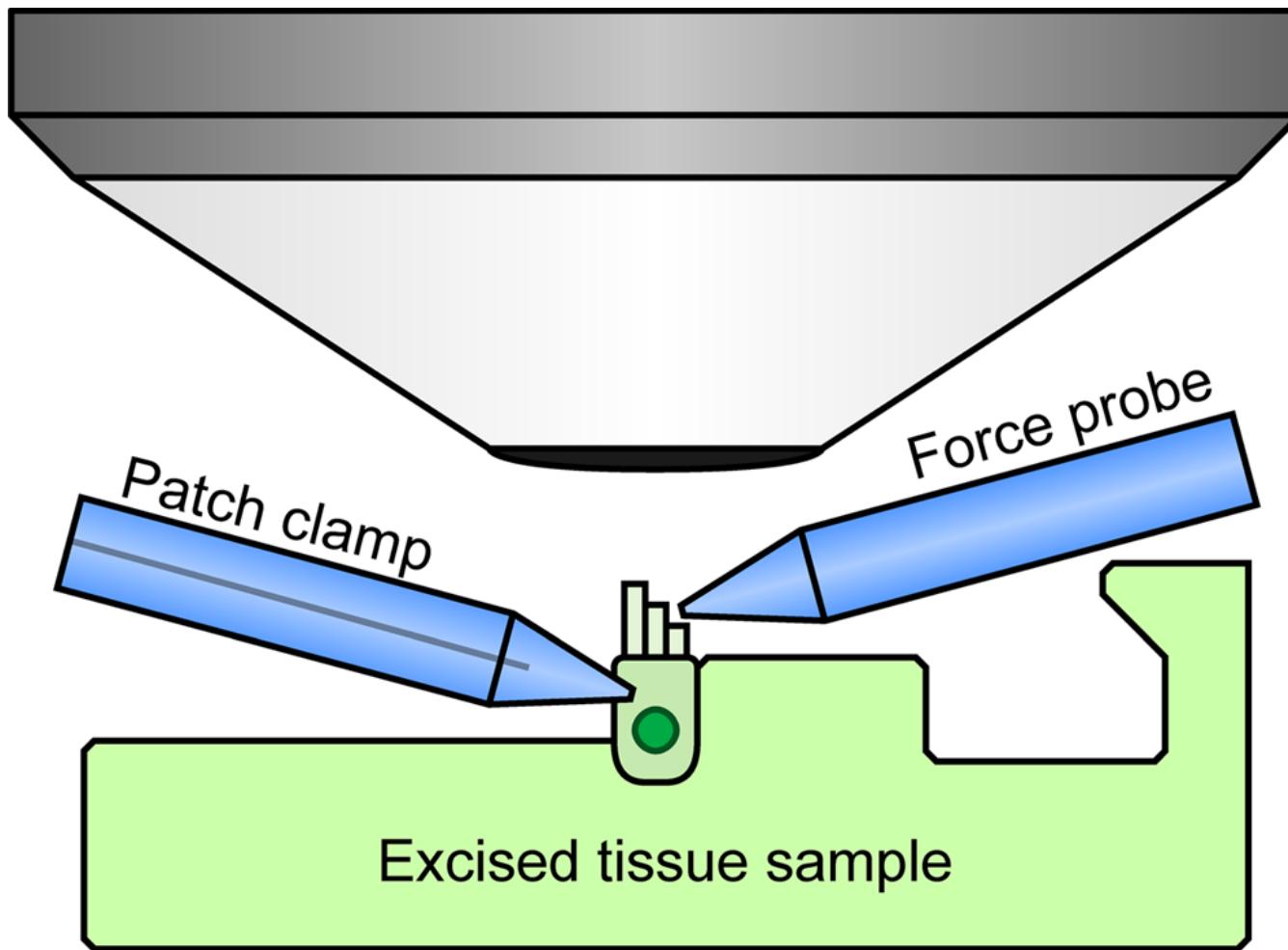


# Hair cell bundles transduce force into an electrical signal

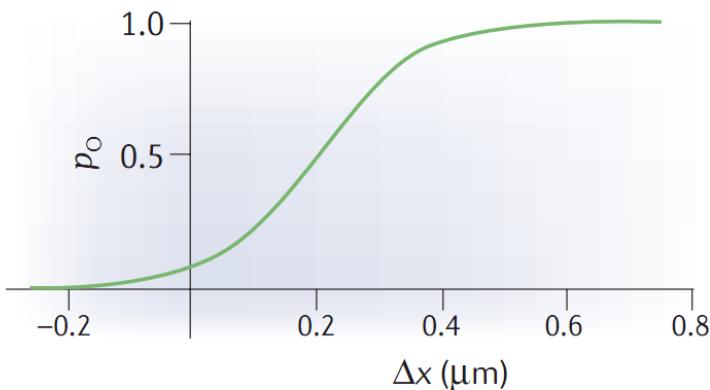


Images from Fettiplace (2001) and Icagen

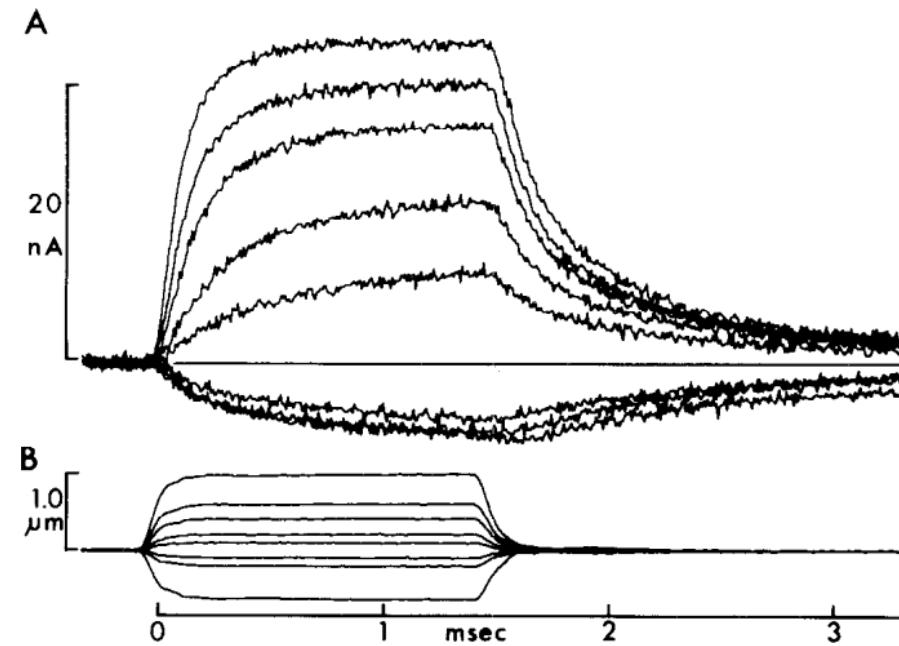
# Hair cell experimental setup



## Bundle mechanics (soft probes, 1 mN/m)



## Channel kinetics (stiff probes)



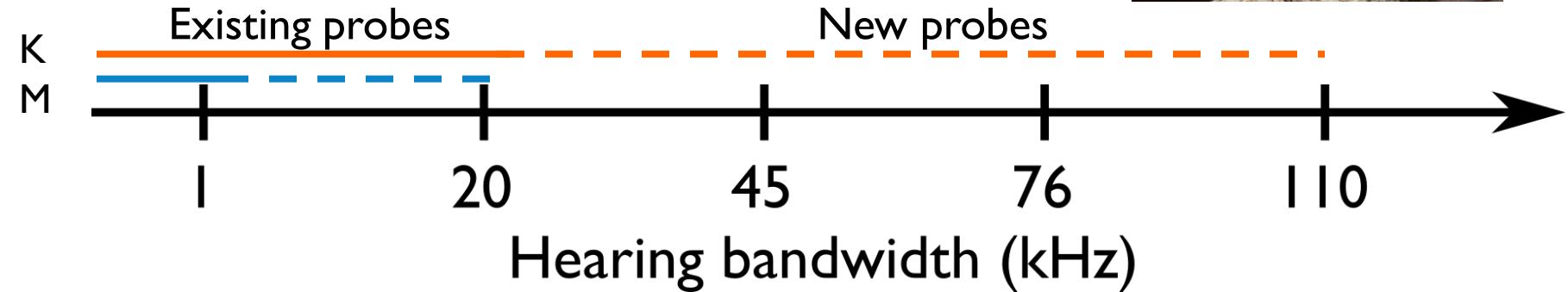
Limited by probe size

Limited by actuator speed

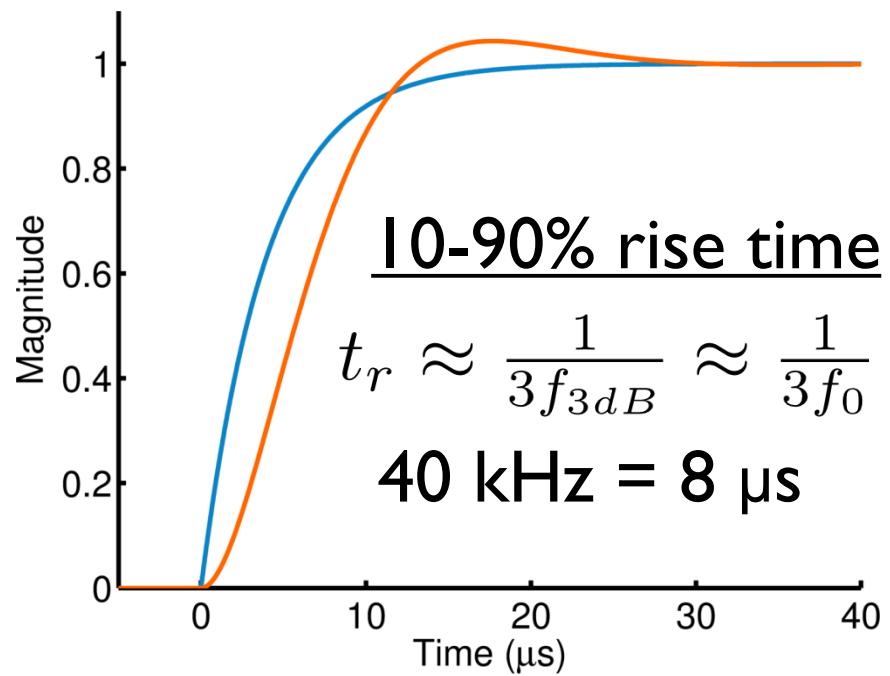
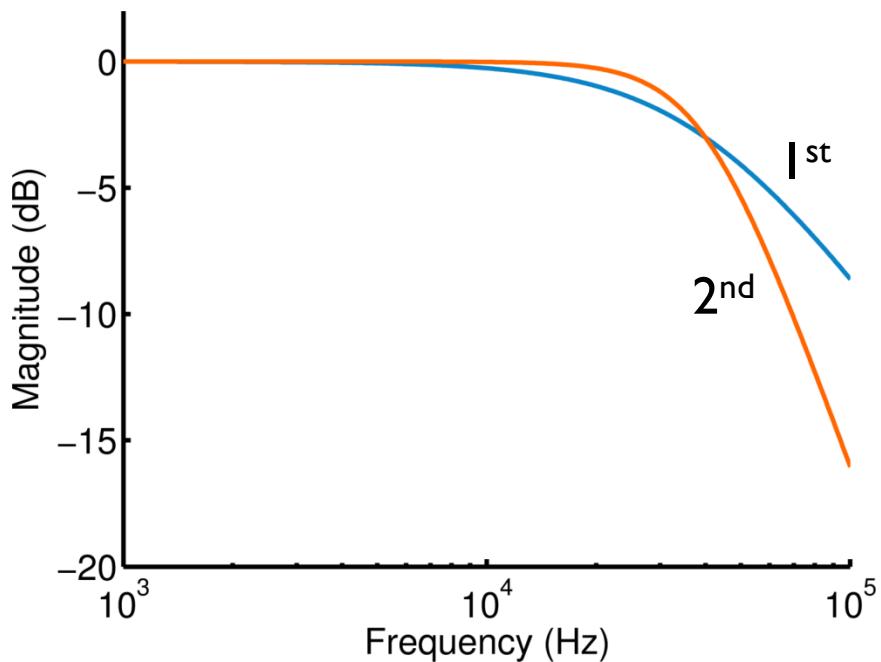
The force probe needs to be faster than the hair cell

Images from Fettiplace (2006) and Corey (1983)

# How fast do the probes need to be?



# Bandwidth vs. rise time



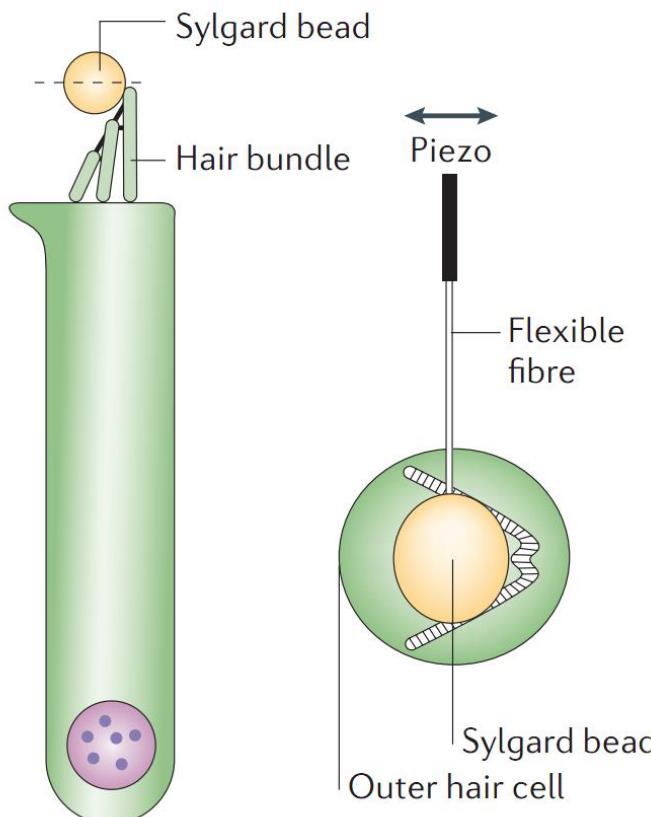
1<sup>st</sup> order system:  $f_{3dB} = 40 \text{ kHz}$

2<sup>nd</sup> order system:  $f_0 = 40 \text{ kHz}, Q = .707$

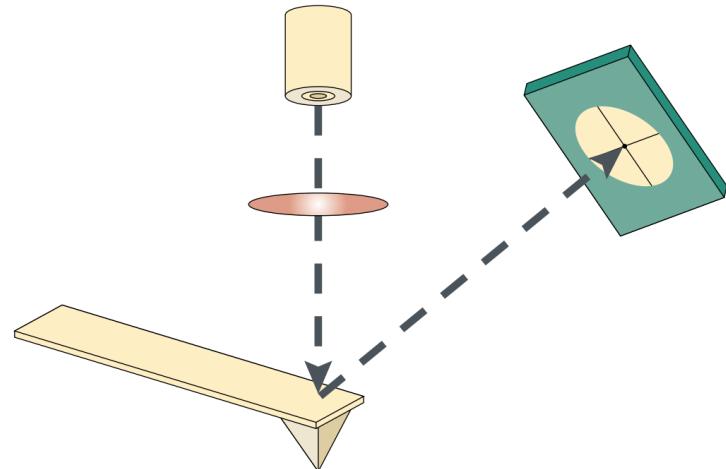
# Target force probe performance

- Mechanics
  - 1 mN/m spring constant
  - 5-20 kHz bandwidth (20-60  $\mu$ s rise time)
- Kinetics
  - Any spring constant
  - 50-200 kHz bandwidth (2-7  $\mu$ s rise time)
- Both
  - 500 nm tip deflection
  - Operate in grounded salt water

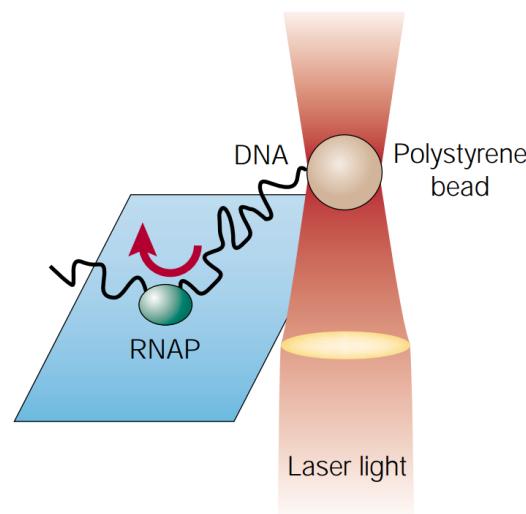
## Macroscale



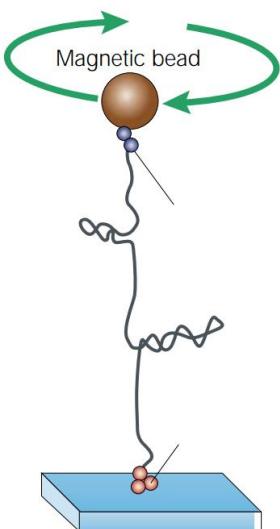
AFM



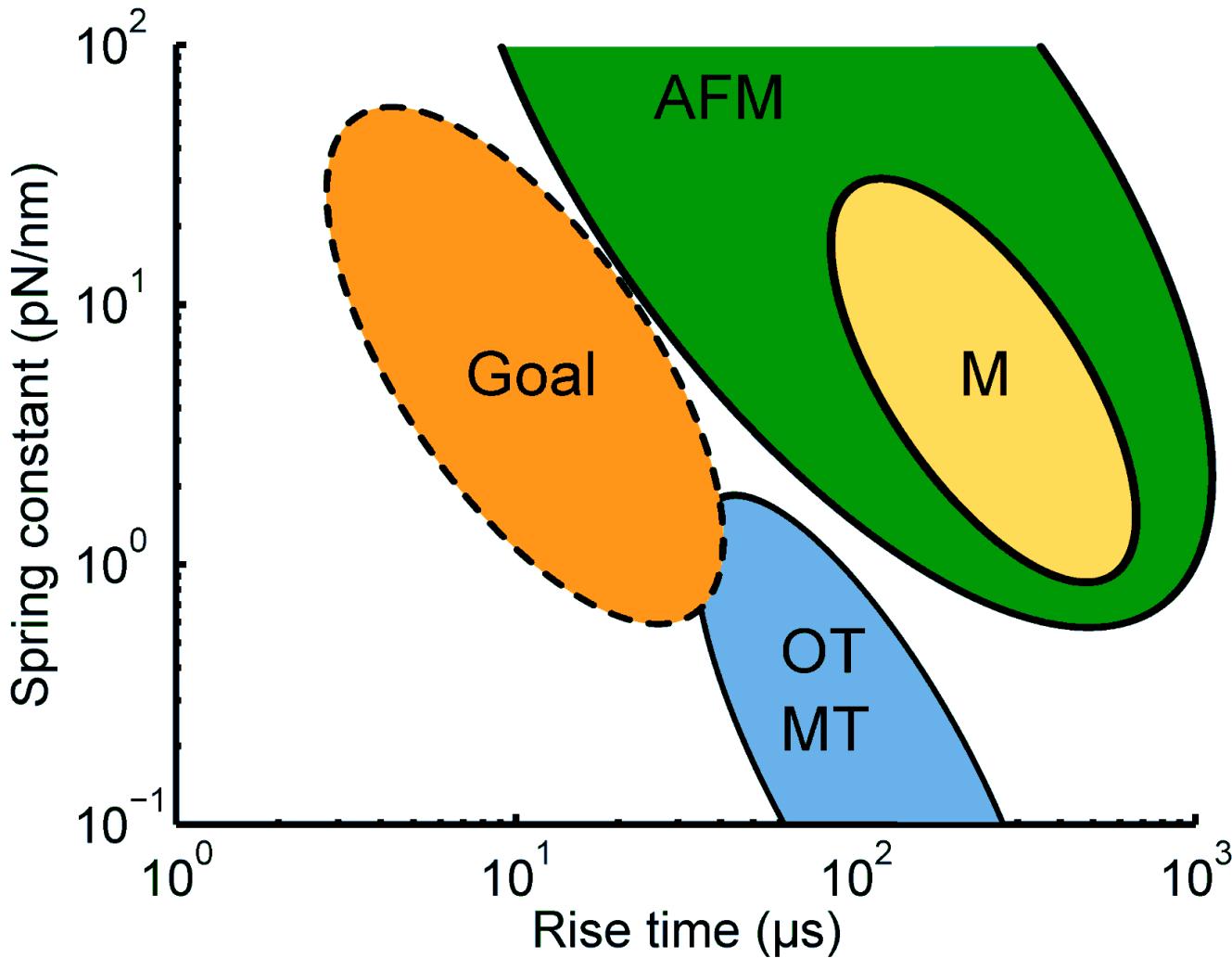
Optical  
tweezers



Magnetic  
tweezers



Images from Fettiplace (2006) and Bustamante (2000)



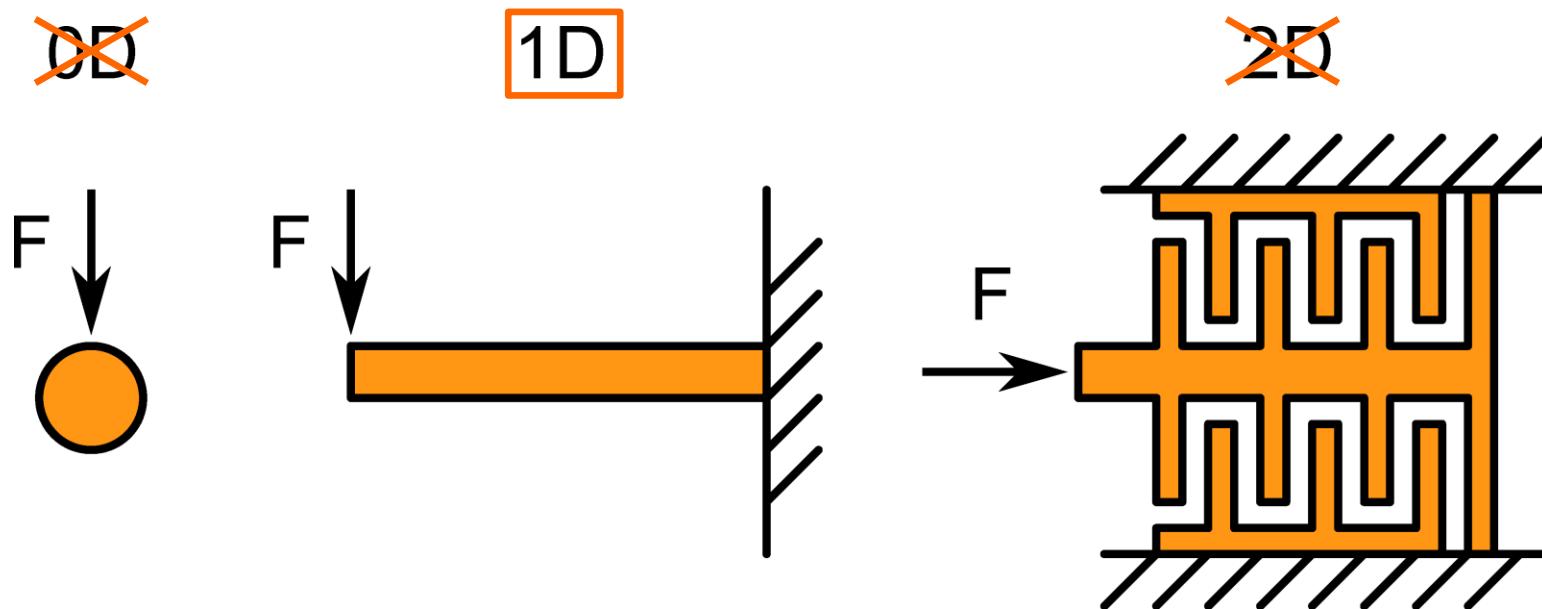
$$t_r \approx \frac{1}{3f_0} \propto \sqrt{\frac{m_{eff}}{k}}$$

(for  $Q = 1/\sqrt{2}$ )

Based upon “Single-molecule force spectroscopy: optical tweezers, magnetic tweezers and atomic force microscopy”, Neuman and Nagy (2008)

# Design overview (size/shape + sensor + actuator)

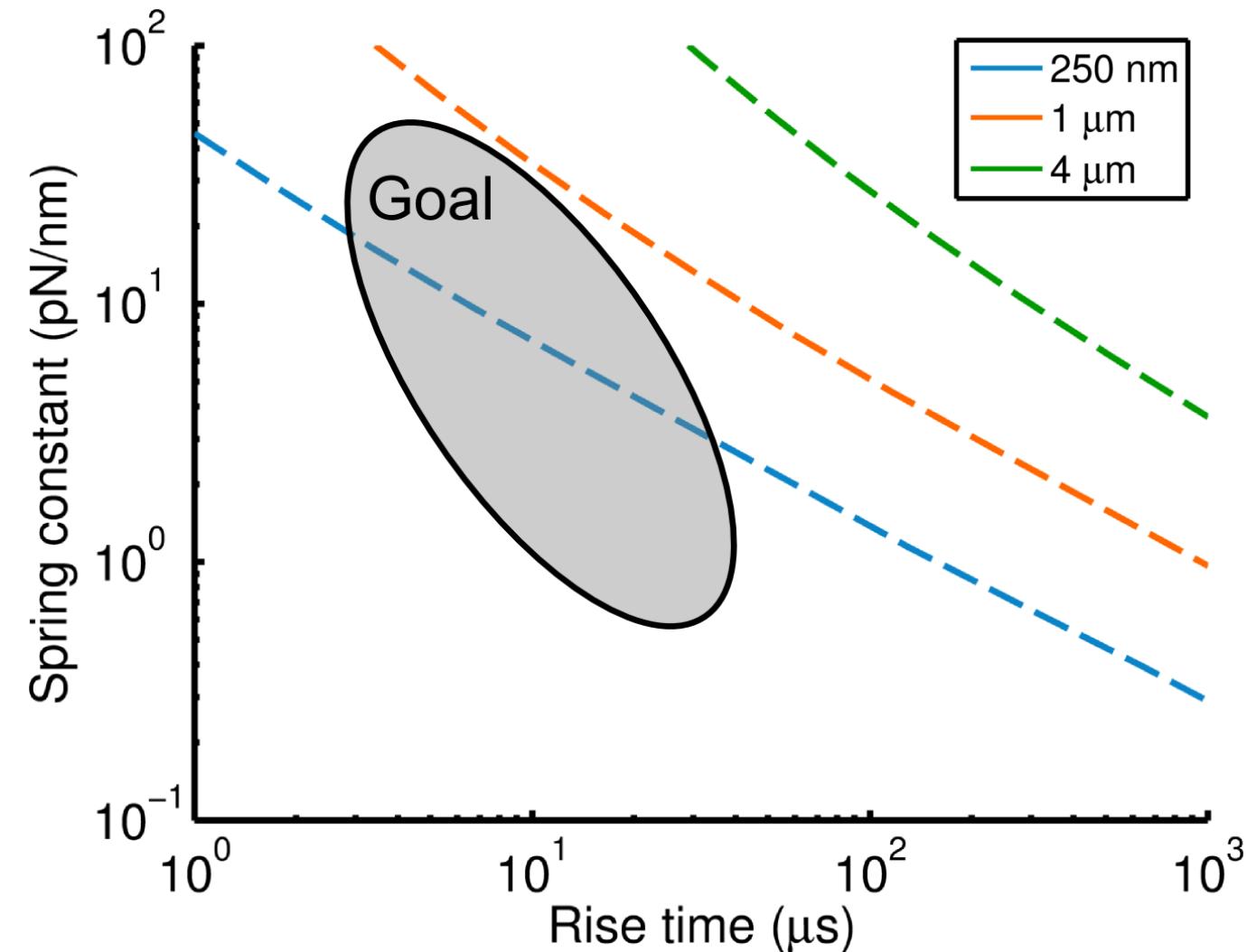
# What should a force probe look like?



Goals:

- 1) Minimize probe mass
- 2) Allow stiffness tuning

# The force probes need to be thin

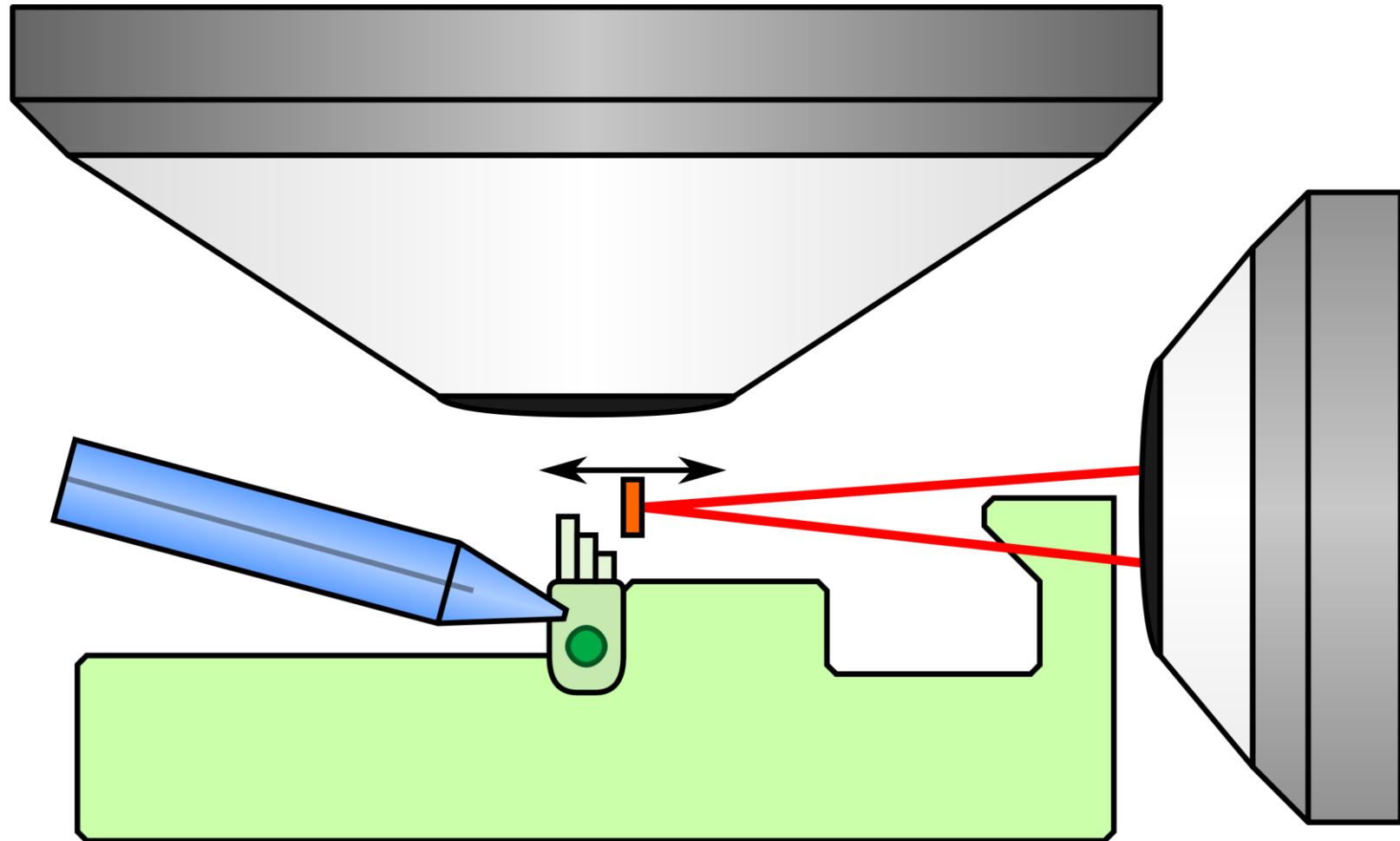


Operation in  
Water

$$kt_r \propto \frac{\sqrt{E_c \rho_c} w_c t_c^2}{l_c}$$

(for  $Q = 1/\sqrt{2}$ )

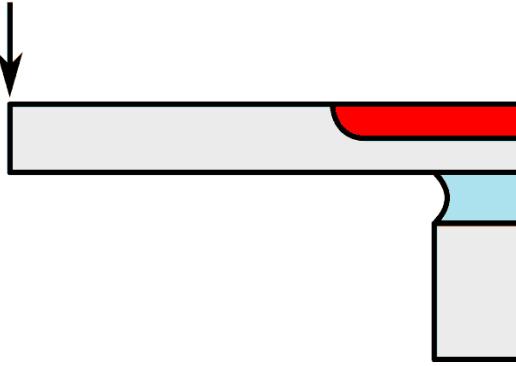
# Optical deflection sensing is impractical



# Force transduction options

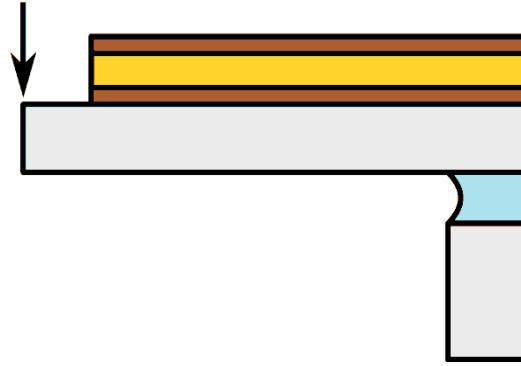
Piezoresistive

$$\Delta F \rightarrow \Delta R$$



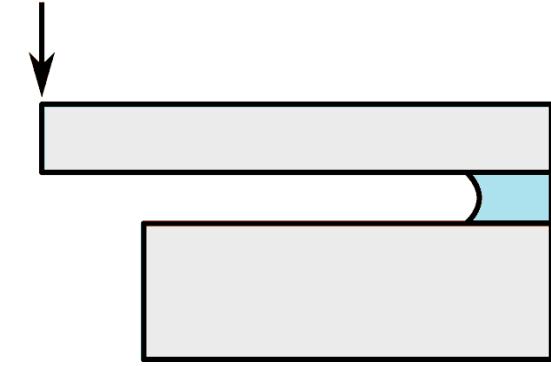
~~Piezoelectric~~

$$\Delta F \rightarrow \Delta Q$$

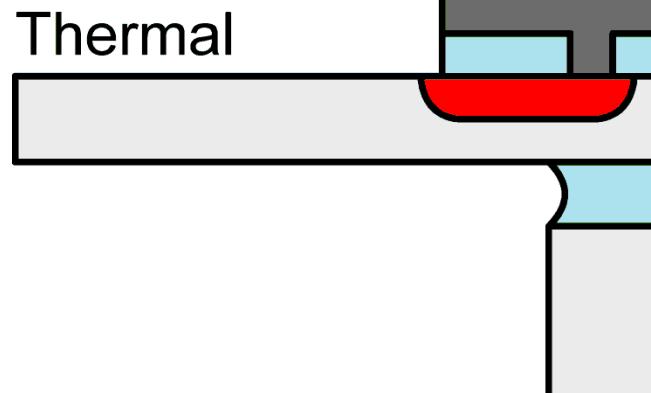
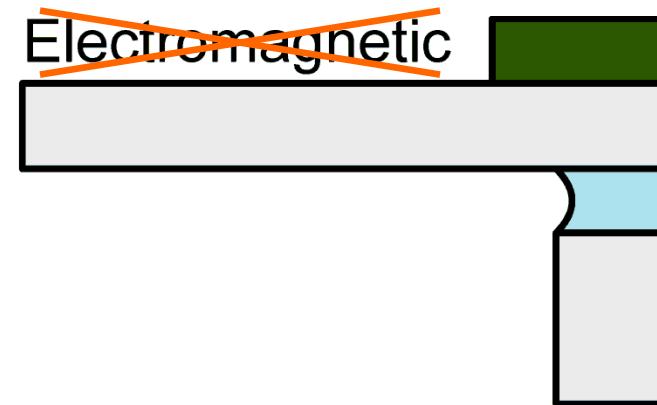
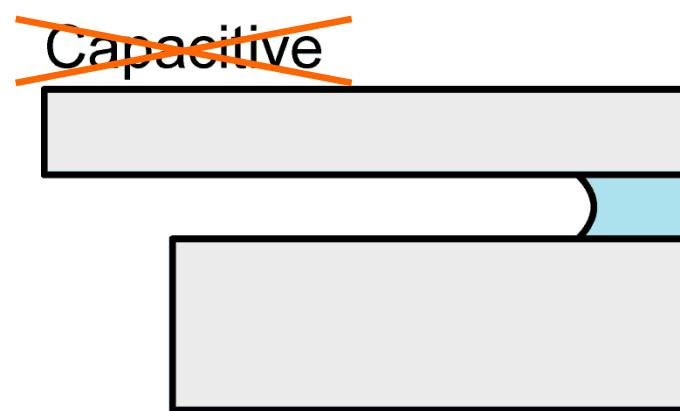


~~Capacitive~~

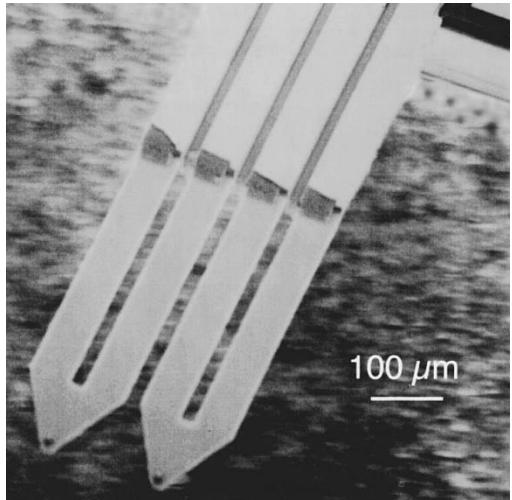
$$\Delta F \rightarrow \Delta C$$



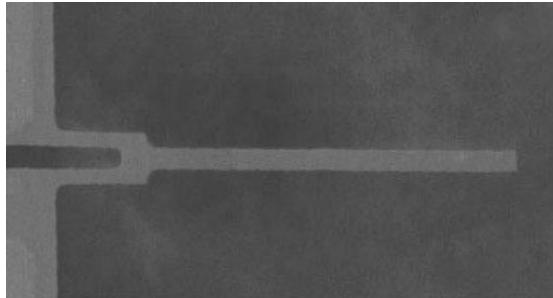
# Actuator options



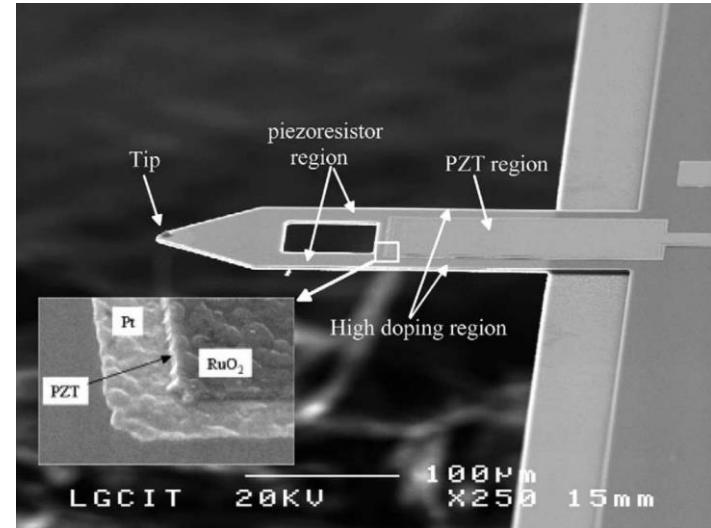
# Previous devices have been too large



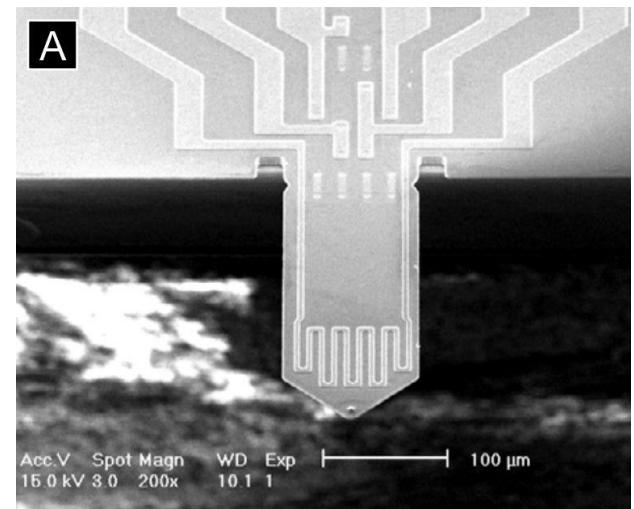
Minne et al. (1995)  
 $3.5 \mu\text{m} \times 85 \mu\text{m} \times 420 \mu\text{m}$



Harley and Kenny (1999)  
 $90\text{nm} \times 4 \mu\text{m} \times 60 \mu\text{m}$

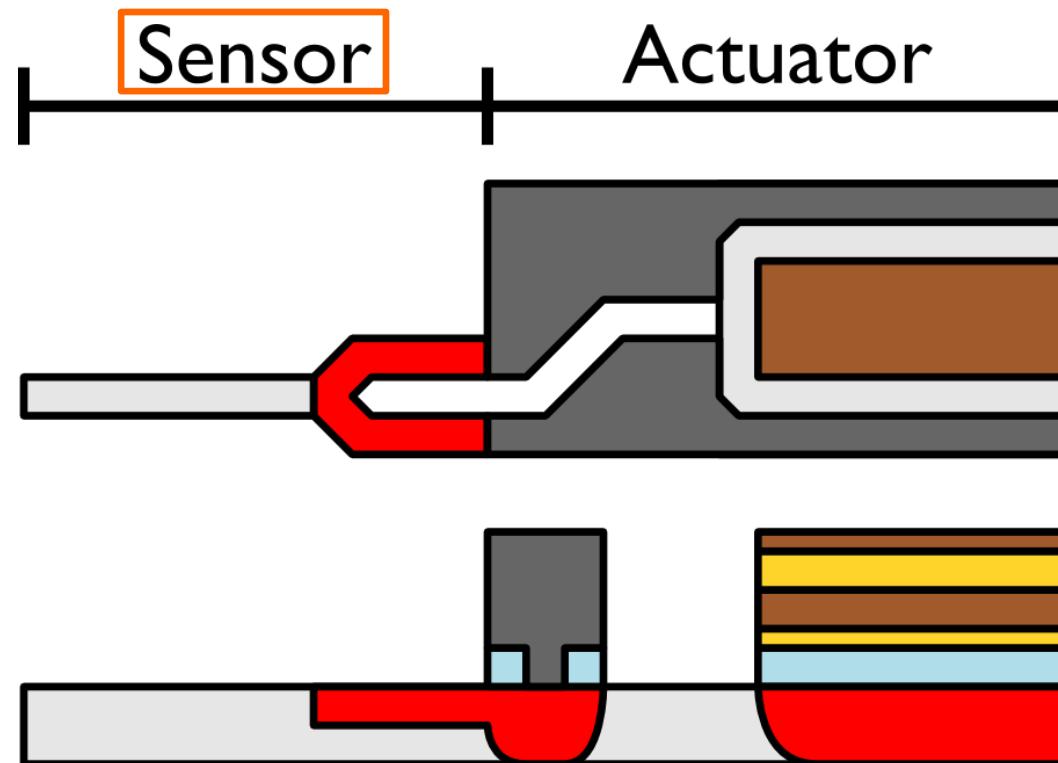


Kim et al. (2003)  
 $3 \mu\text{m} \times 70 \mu\text{m} \times 200 \mu\text{m}$

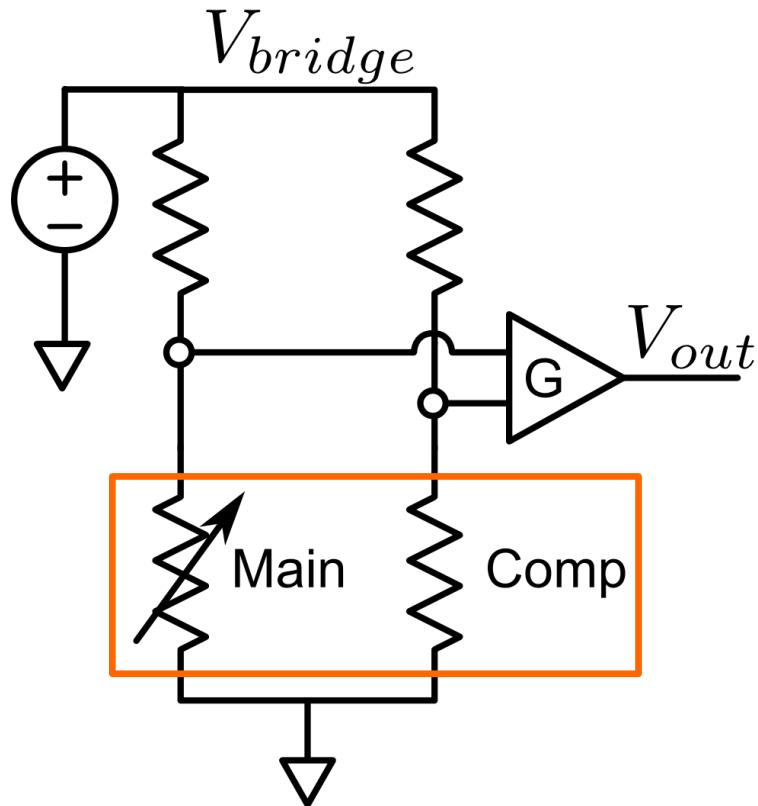


Fantner et al (2009)  
 $5 \mu\text{m} \times 110 \mu\text{m} \times 320 \mu\text{m}$

# Design



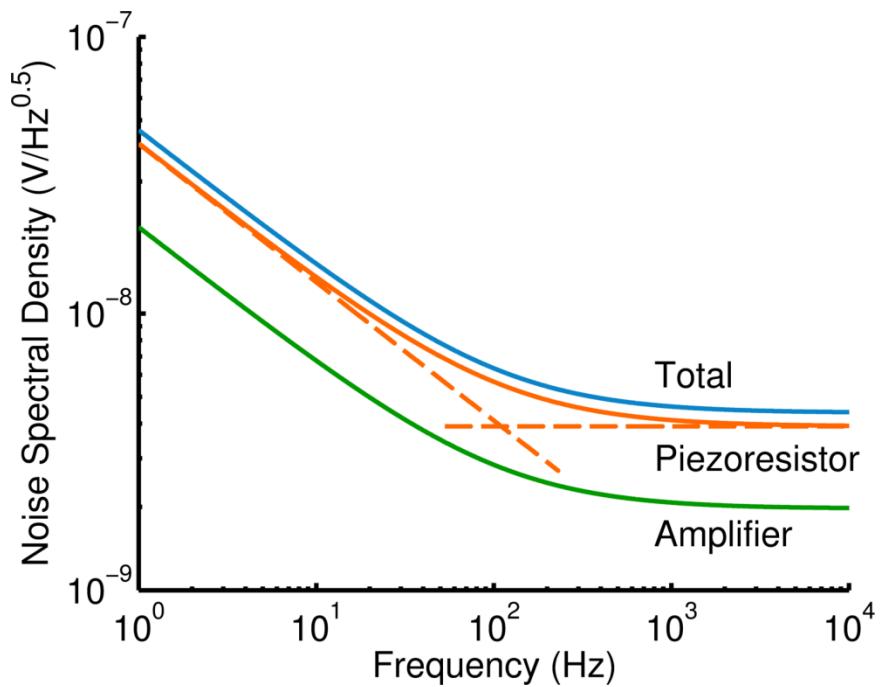
# Piezoresistor fundamentals



$$V_{out} \approx \frac{\Delta R}{4R} V_{bridge}$$
$$\frac{\Delta R}{R} \propto \pi\sigma$$

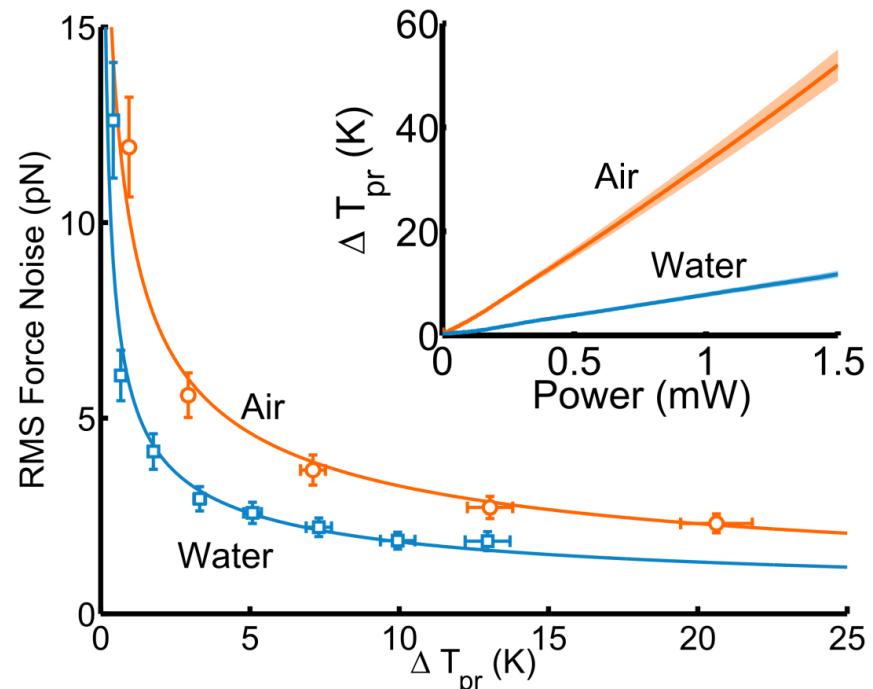
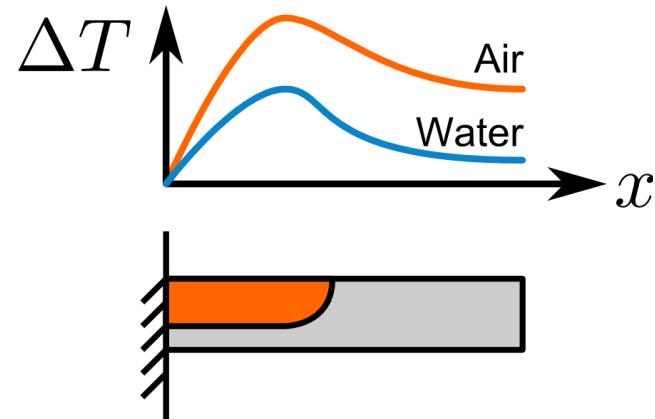
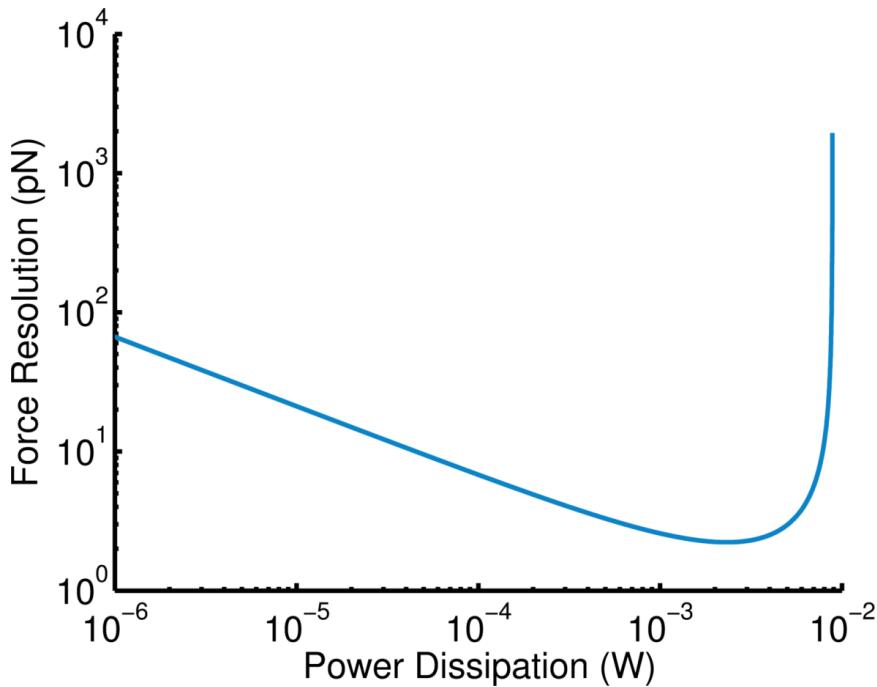
# Piezoresistor design fundamentals

$$\text{Resolution} = \frac{\text{Noise}}{\text{Sensitivity}}$$



Goal: minimize the minimum detectable force (MDF) by adjusting the sensor dimensions, bridge bias and doping process

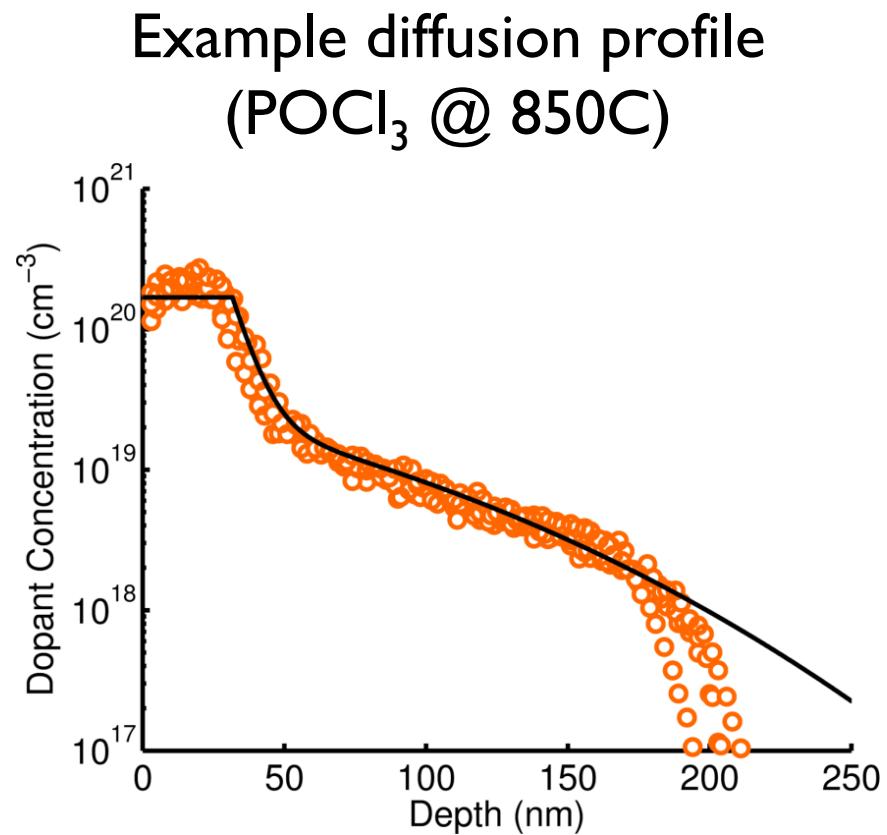
# Piezoresistors love water



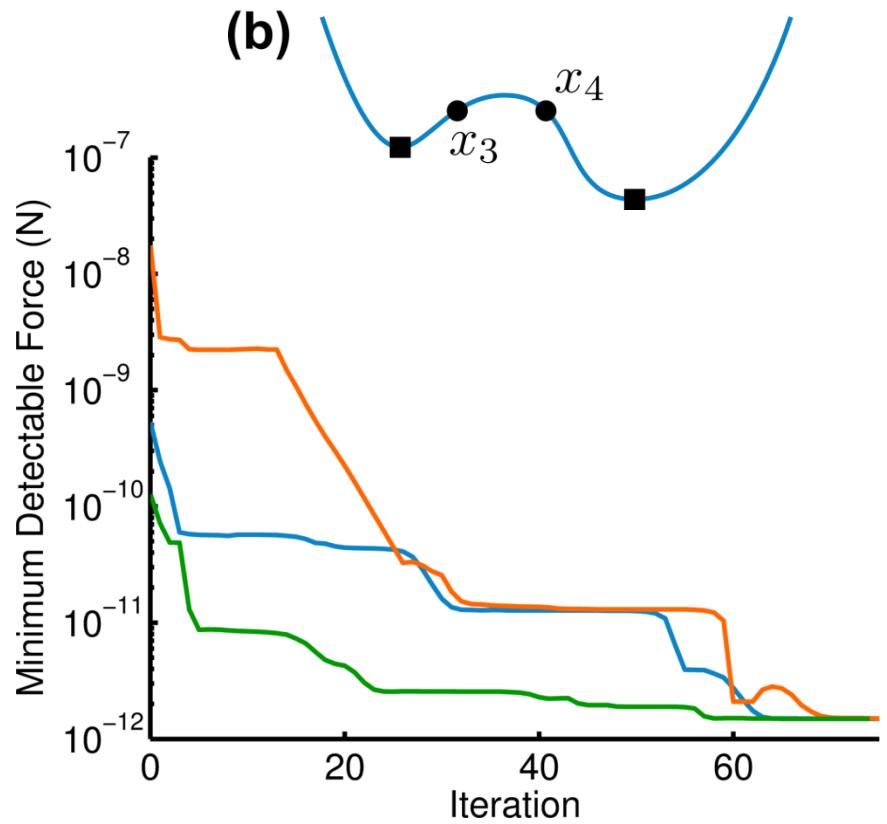
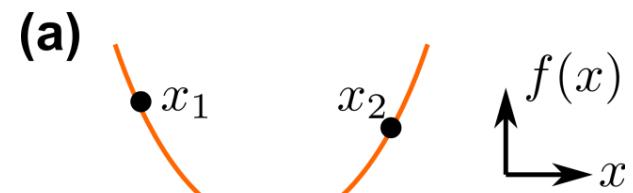
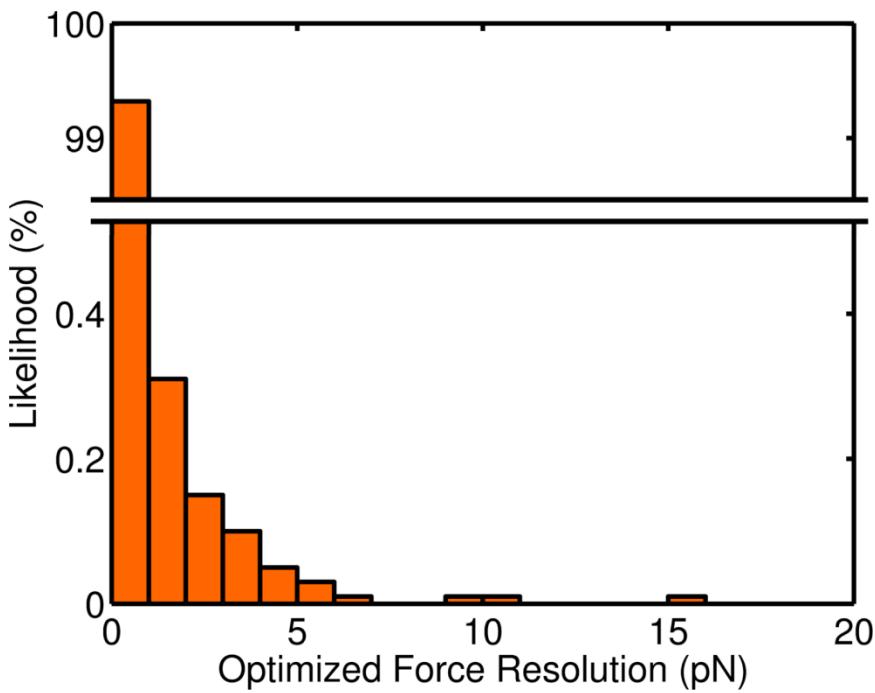
Self-heating in piezoresistive cantilevers  
J.C. Doll, E.A. Corbin, W.P. King and B.L. Pruitt  
Applied Physics Letters (2011)

# Piezoresistor design requires numerical modeling

- Complex dopant profiles
- Self-heating
- Fluid damping



# Numerical design optimization



Design optimization of piezoresistive cantilevers for force sensing in air and water

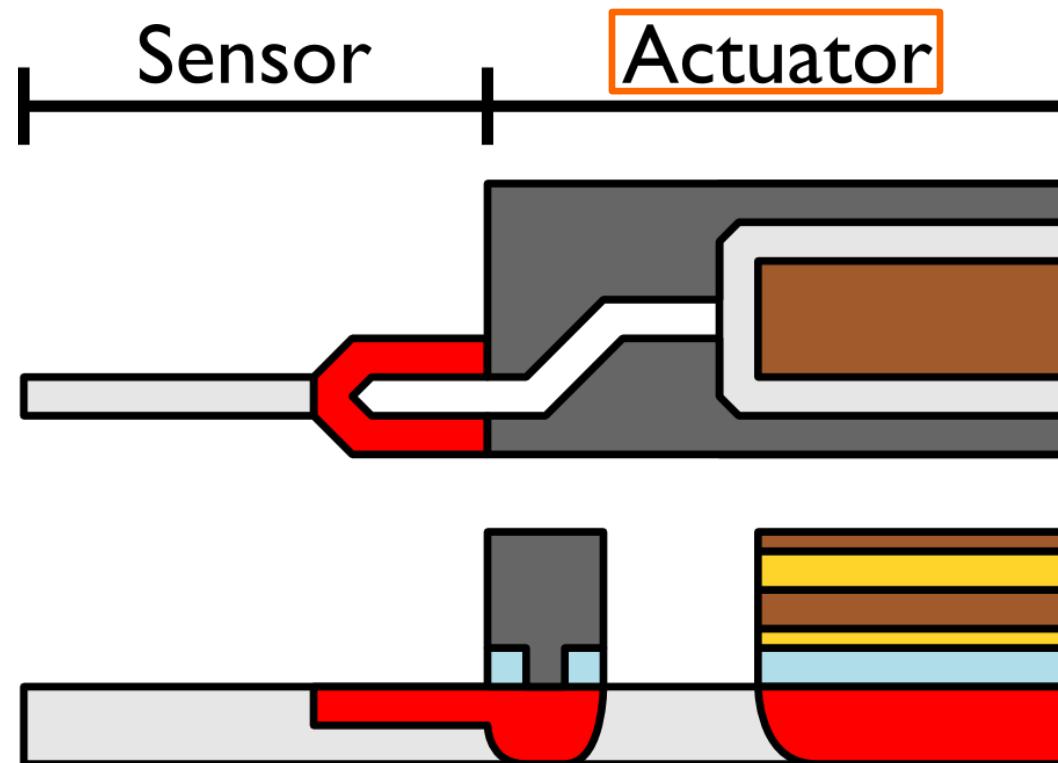
J.C. Doll, S.-J. Park and B.L. Pruitt

Journal of Applied Physics (2008)

# Design summary

Design #	$l_c$ (μm)	$k_c$ (mN/m)	$f_0$ (kHz)	$f_d$ (kHz)	MDF (pN)
1	142	0.3	18	3.3	3.3
2	96	1.0	40	9.7	6.2
3	75	2.1	65	19	9.6
4	61	3.9	97	32	14
5	46	9.0	170	64	24
6	35	20	290	124	42
7	29	36	430	190	61

# Design

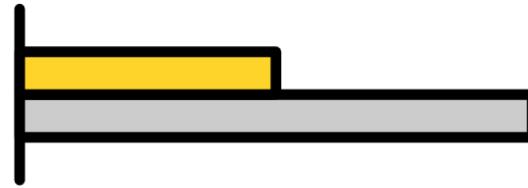


Actuators transduce a voltage  
into a tip deflection

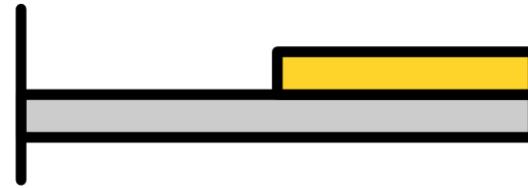
$$V \rightarrow \epsilon \rightarrow z_{tip}$$

# Actuator-sensor placement

Actuator at base



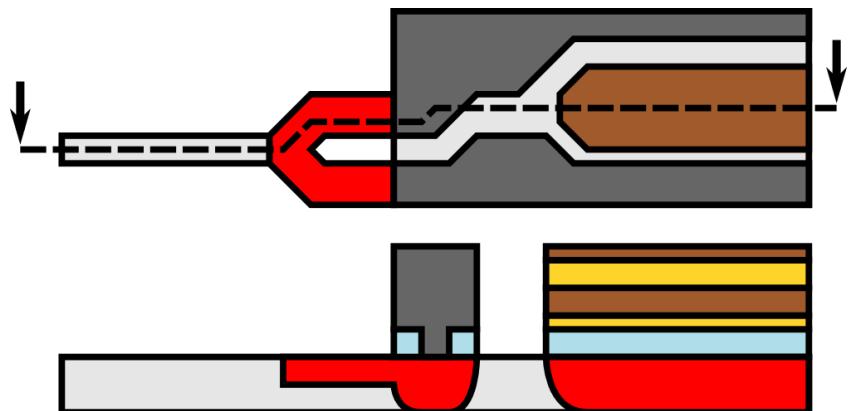
~~Actuator at tip~~



Actuator: thick and stiff  
Sensor: thin and soft

# Force probe design summary

## Piezoelectric actuation



Undoped Si

Doped Si

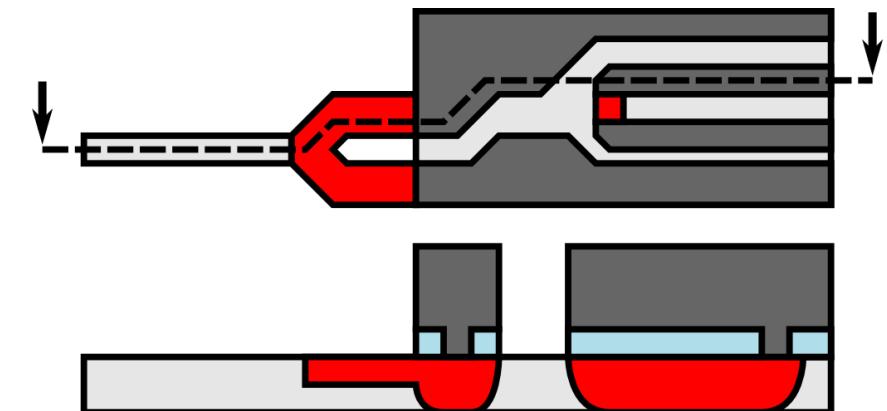
Oxide

Al

Mo

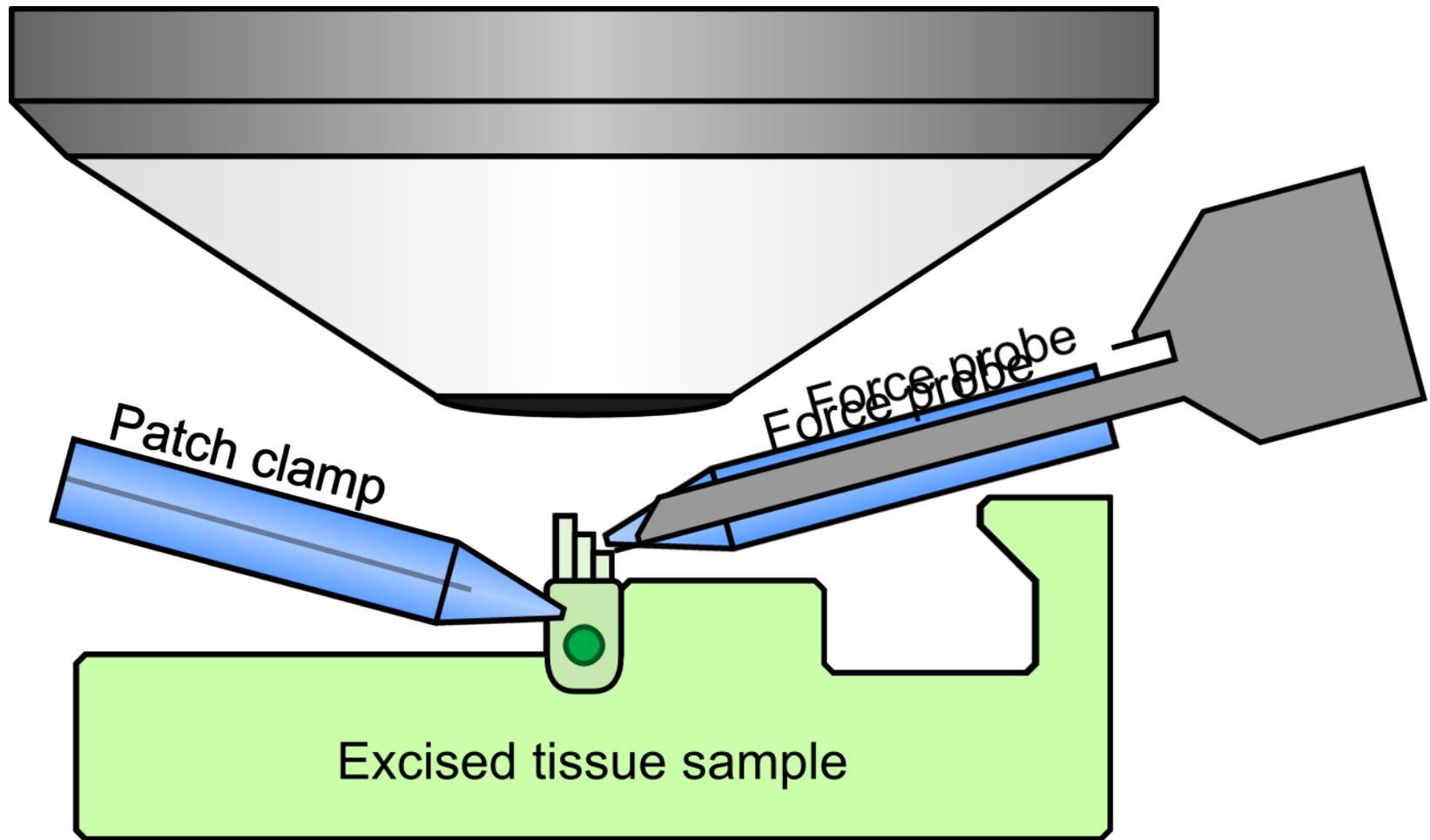
AlN

## Thermal actuation



Actuator length varies  
depending on sensor  
resonant frequency

# Designing for microscope compatibility



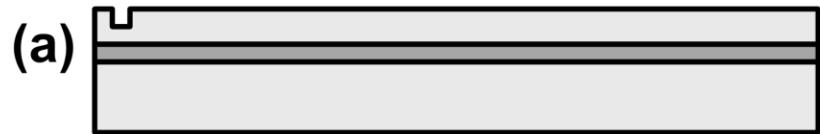
# Fabrication

# Fabrication overview

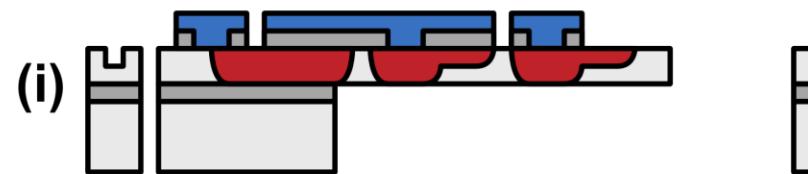
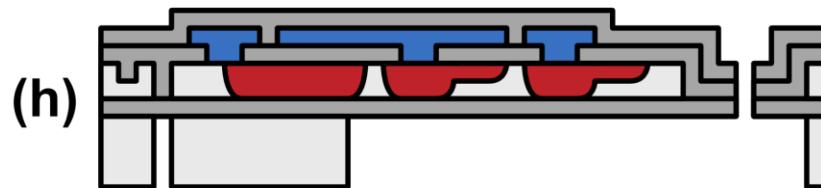
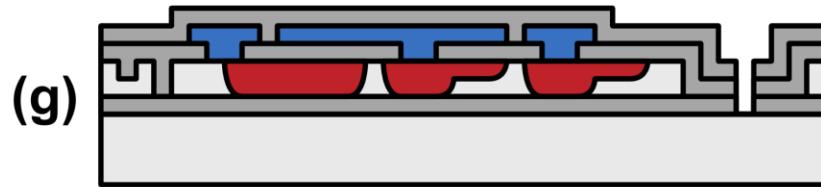
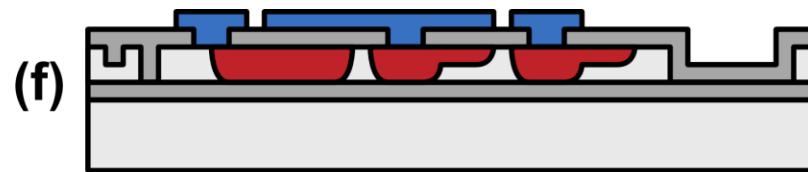
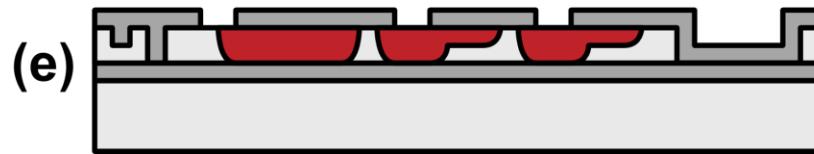
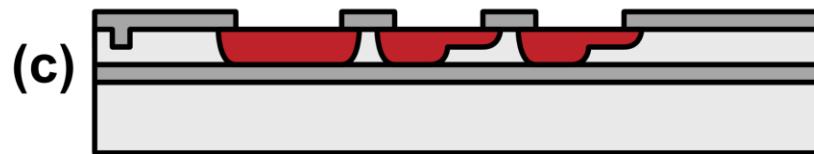
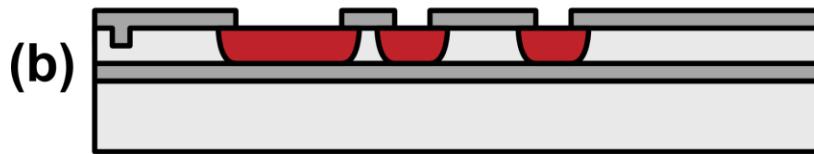
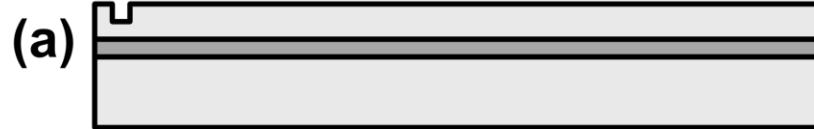
- Three processes
  - Piezoresistive sensor only
  - Thermal actuation
  - Piezoelectric actuation
- Process specs
  - 7 and 9 mask processes
  - 0.5 um CD and 0.25 um overlay tolerance
  - Start from 340nm device layer SOI wafers

# Piezoresistive sensor only

---



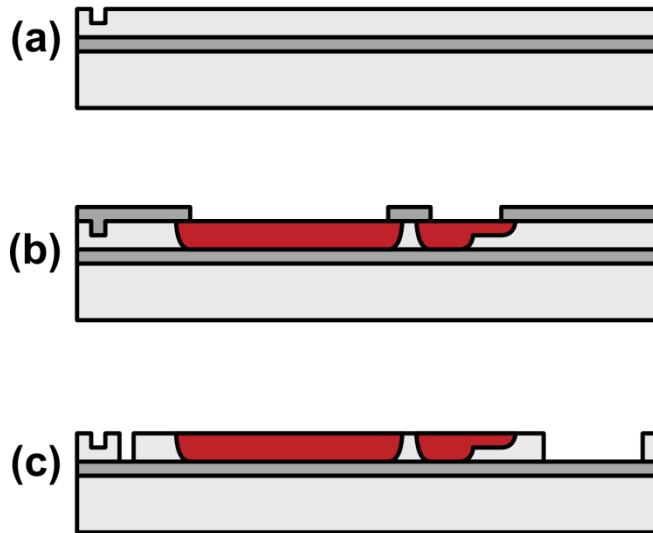
# Thermal actuation



Legend:

- Si
- SiO<sub>2</sub> (LTO)
- Doped Si
- Al

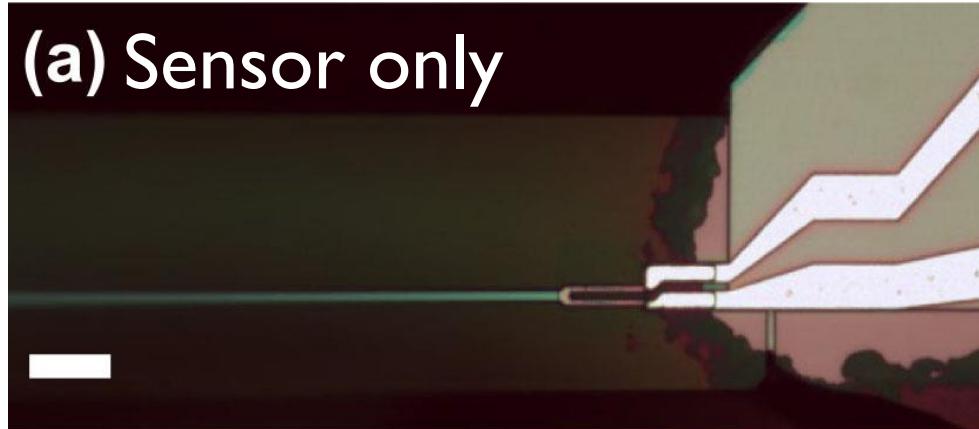
# Piezoelectric actuation



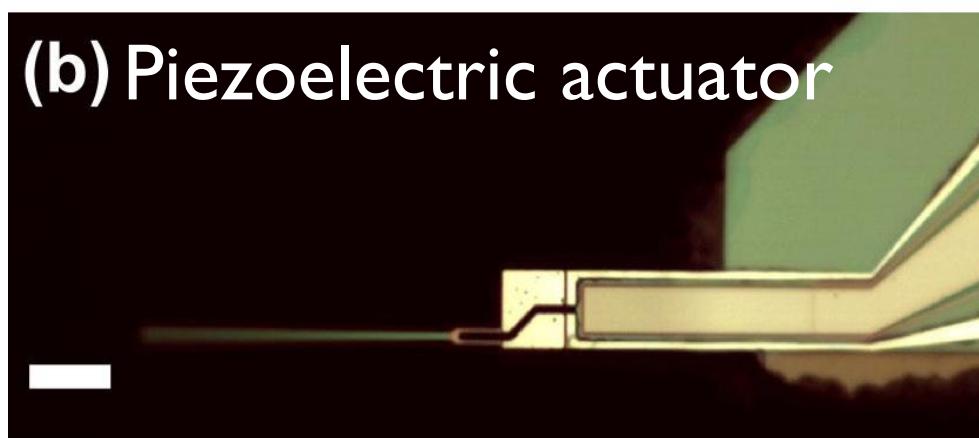
Legend:

Si	SiO <sub>2</sub>	AlN
Doped Si	Al	Mo

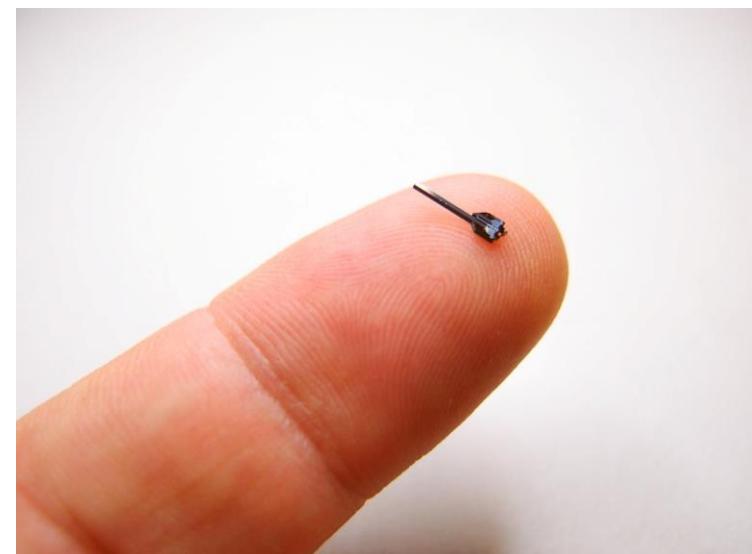
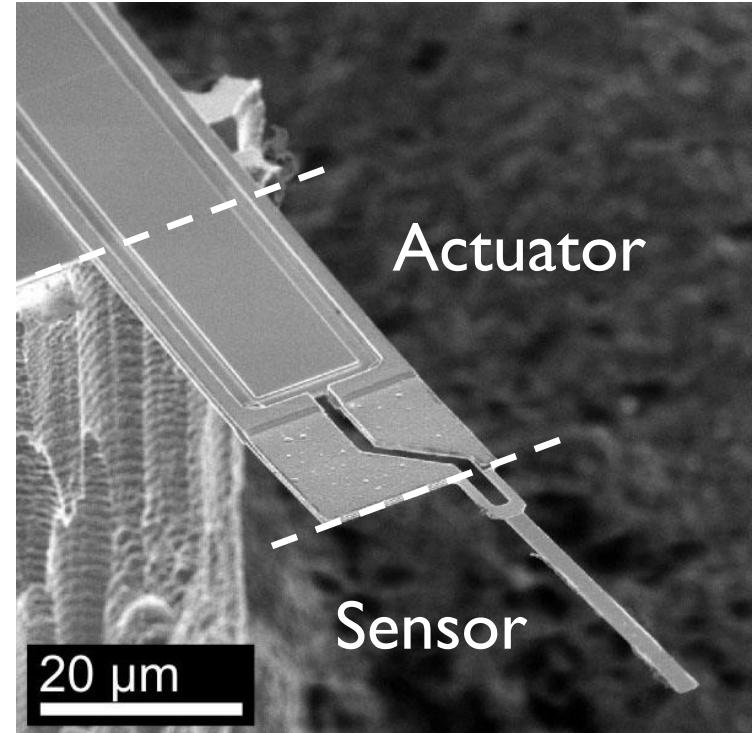
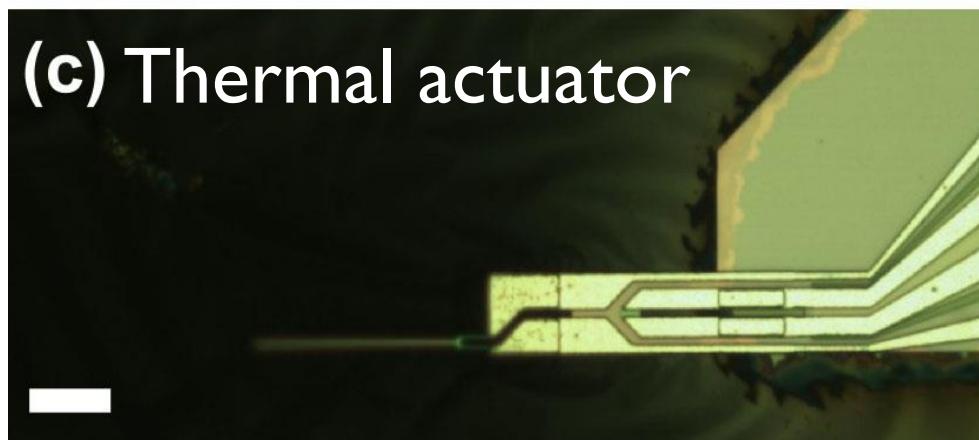
**(a) Sensor only**



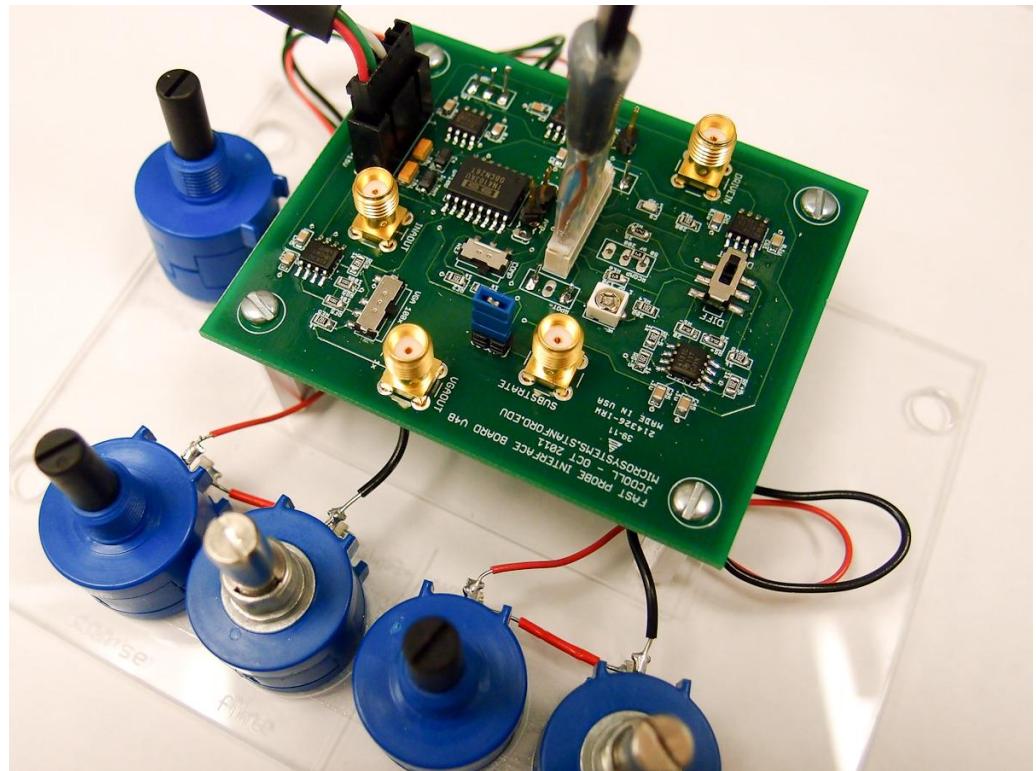
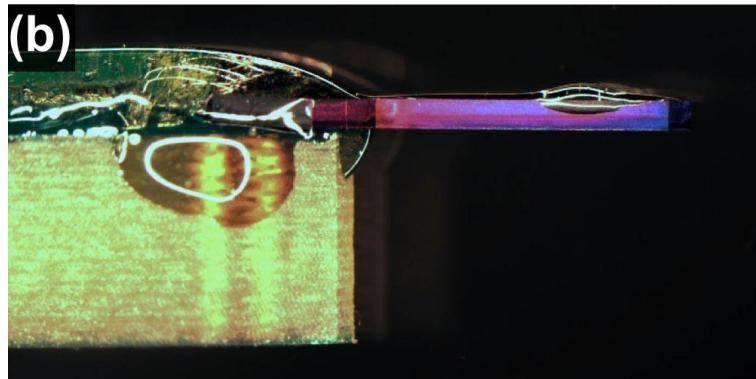
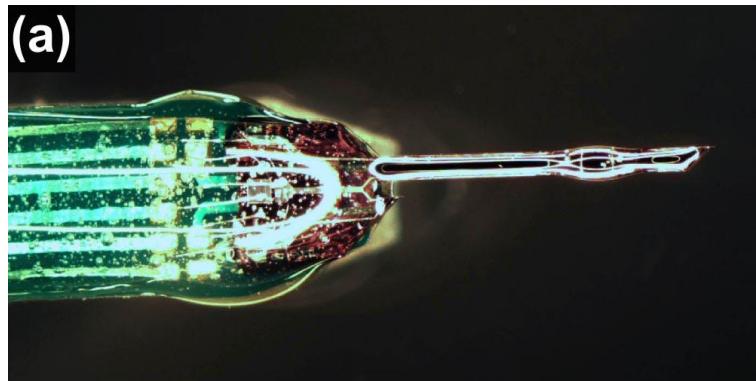
**(b) Piezoelectric actuator**



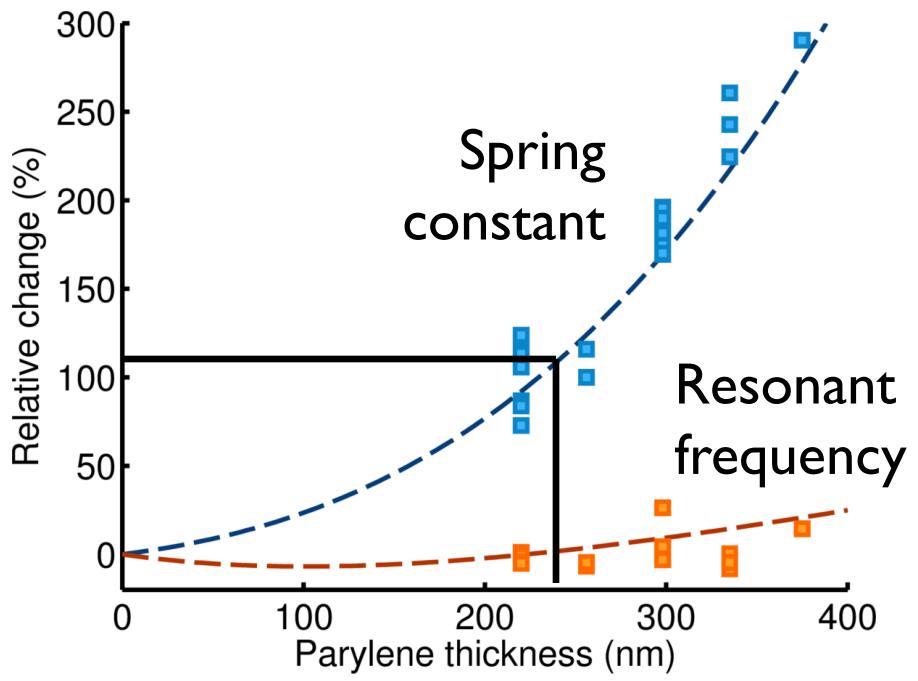
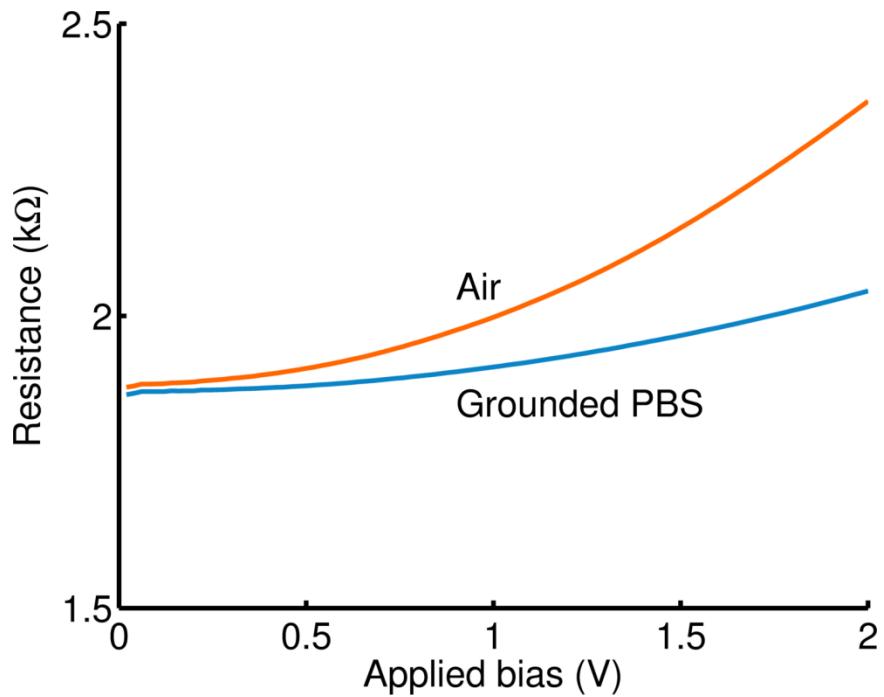
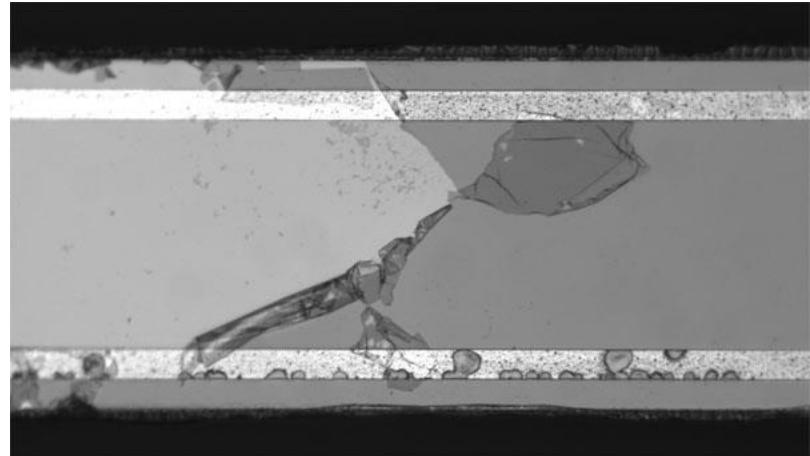
**(c) Thermal actuator**



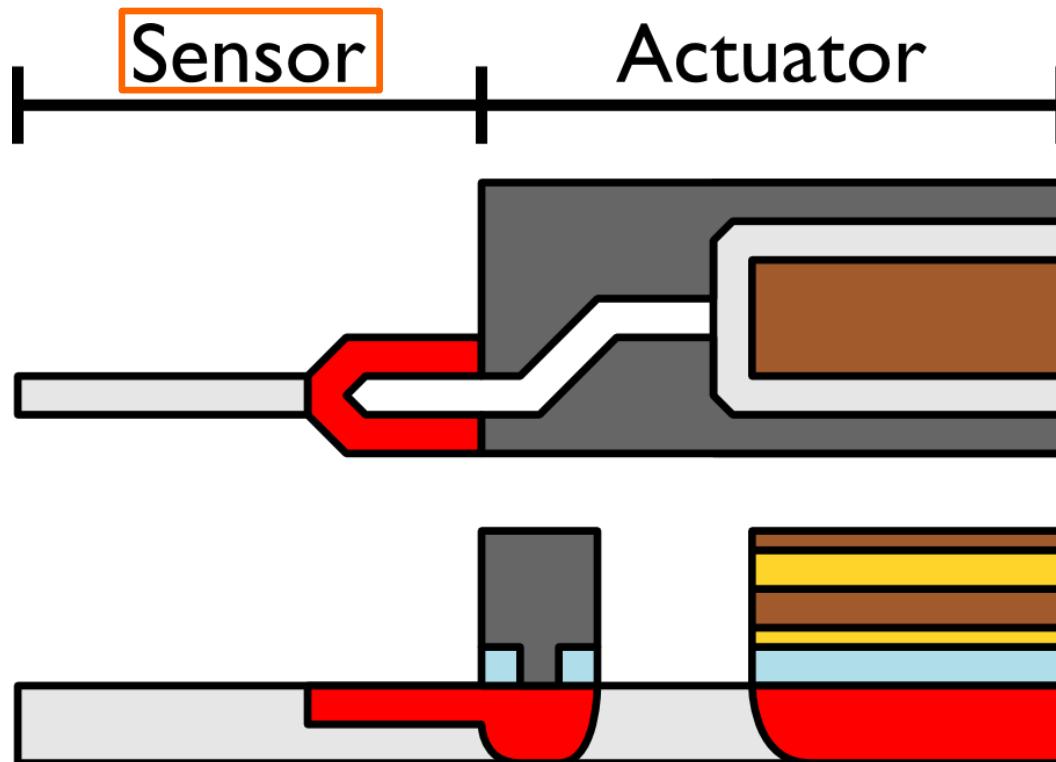
# Assembly and Circuits



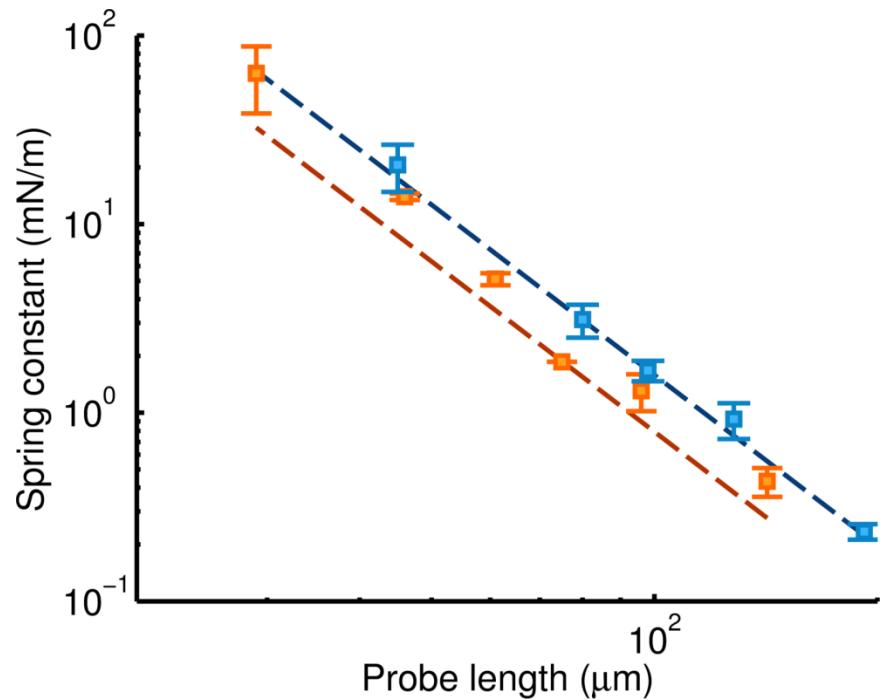
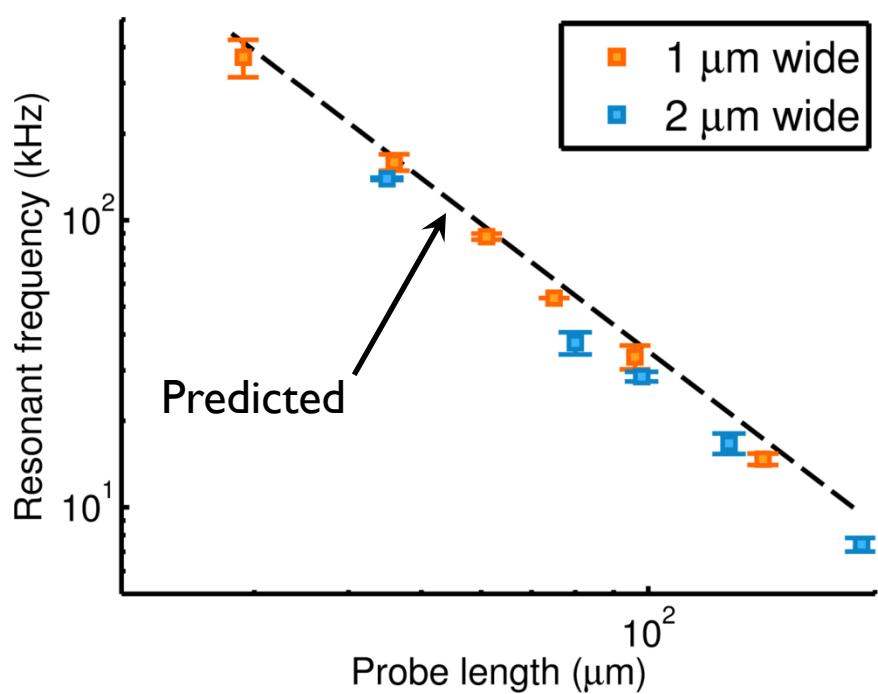
# Parylene is required for operation in water



# Characterization



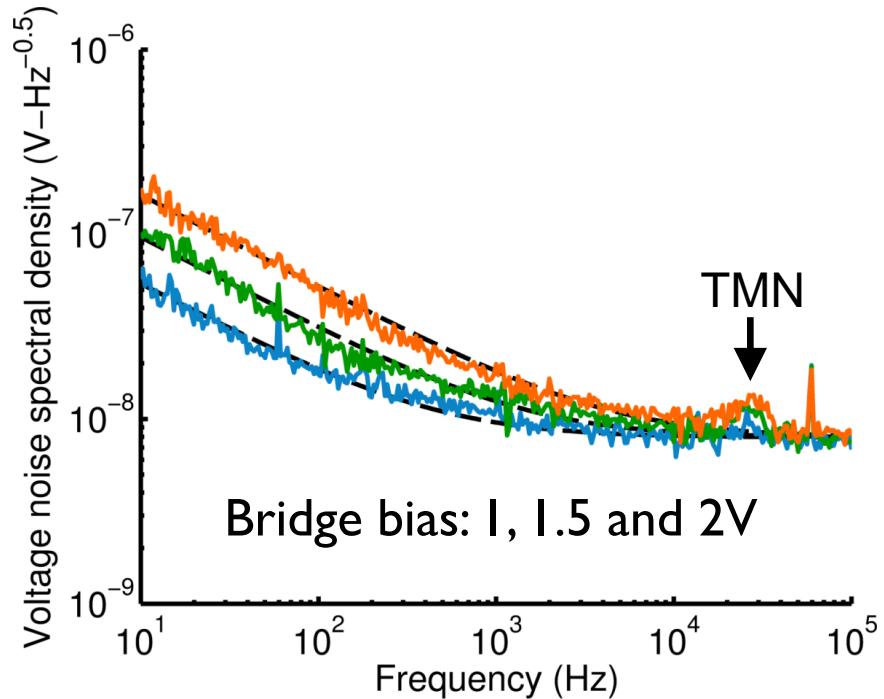
# Resonant frequencies and spring constants match model predictions



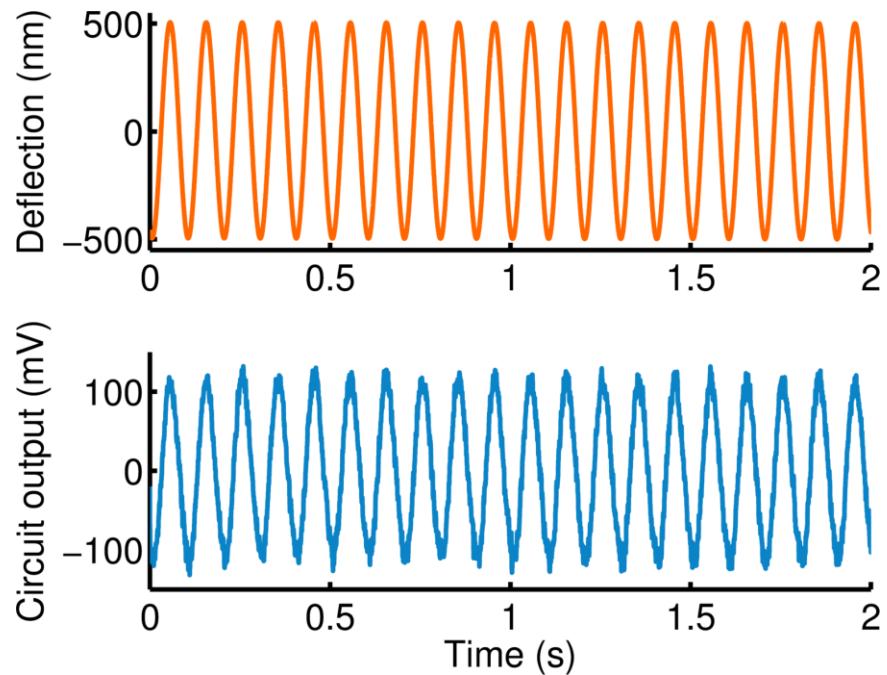
(from thermomechanical noise measured via laser doppler vibrometry)

# Measuring sensor resolution

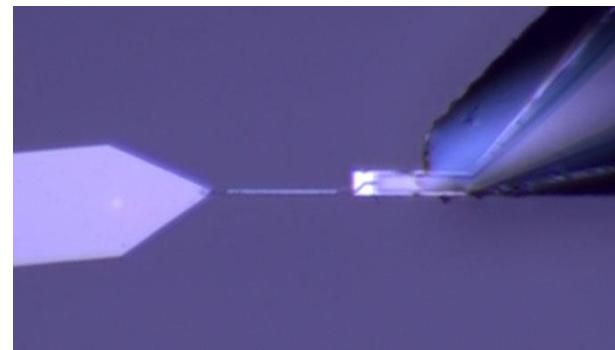
## Sensor noise



## Displacement sensitivity



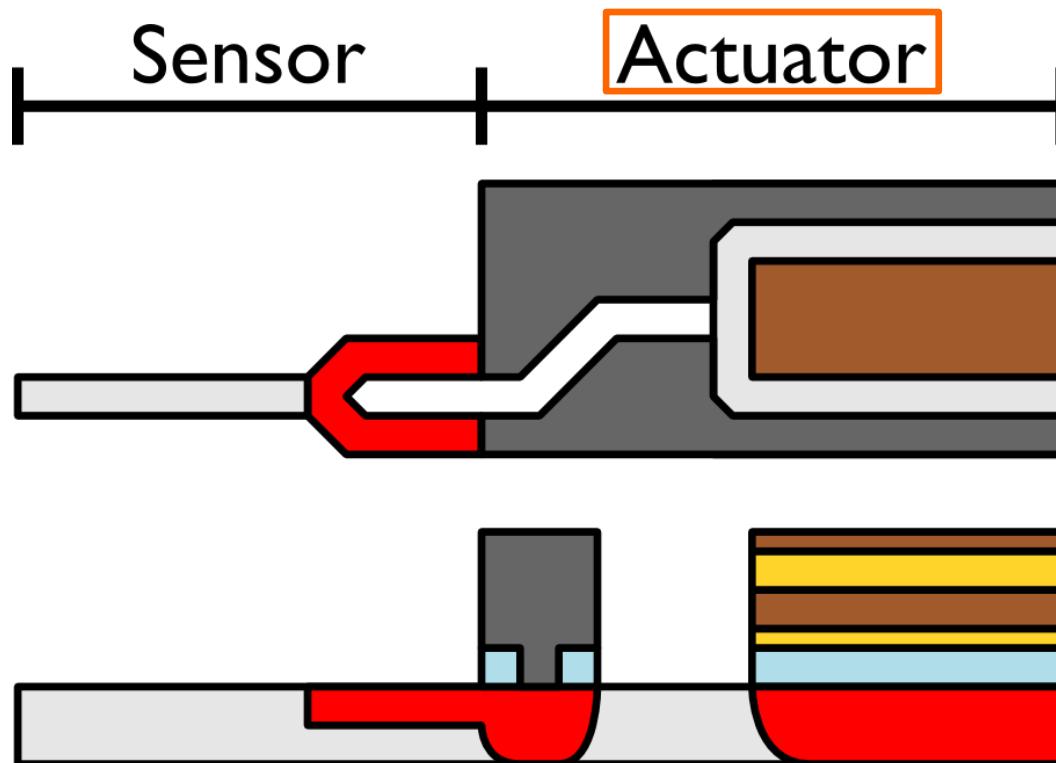
$$\text{Resolution} = \frac{\text{Noise}}{\text{Sensitivity}}$$



# Example sensor performance

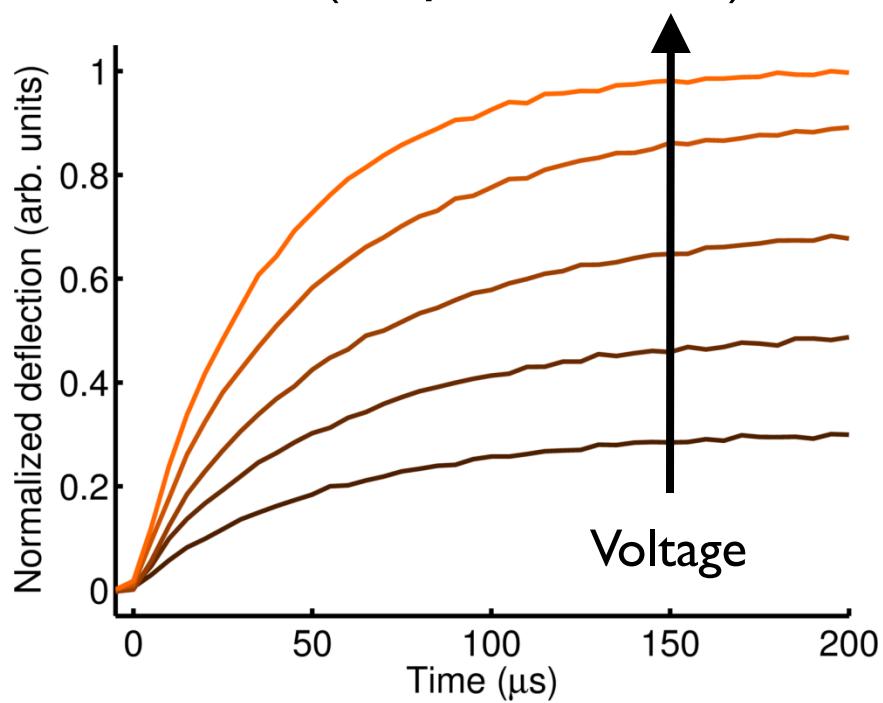
	Example devices	1	2	<u>Model predictions</u>
Mechanics	$l_c$ ( $\mu\text{m}$ )	98	192	
	$l_{pr}$ ( $\mu\text{m}$ )	11.1	17.4	
	$w_c$ ( $\mu\text{m}$ )	2	2	
	$t_c$ ( $\mu\text{m}$ )	0.3	0.3	
Mechanics	$f_0$ (kHz)	27.8	(36)	7.1
	$k_c$ (mN/m)	$1.63 \pm 0.13$	(1.68)	$0.26 \pm 0.01$
	$Q$ (-)	3.8		1.5
	$V_{bridge}$ (V)	2		2
	$R$ (k $\Omega$ )	3.3		4.8
	$W$ ( $\mu\text{W}$ )	306		209
	$\alpha$ (-)	$0.8 \pm 0.3 \times 10^{-5}$		$3.1 \pm 0.6 \times 10^{-5}$
	$S_{XV}$ (V/m-V)	$225.2 \pm 12.6$		$73.5 \pm 10.3$
Resolution	$S_{FV}$ (V/mN-V)	$137.9 \pm 13.5$		$282.7 \pm 42.5$
	$V_{noise}$ ( $\mu\text{V}$ )	0.60		0.74
	MDD (nm)	$2.7 \pm 0.1$	(2.4)	$10.1 \pm 1.4$
	MDF (pN)	$4.4 \pm 0.4$	(4.0)	$2.6 \pm 0.4$
	TMN floor (pN)	1.0		0.6

# Characterization

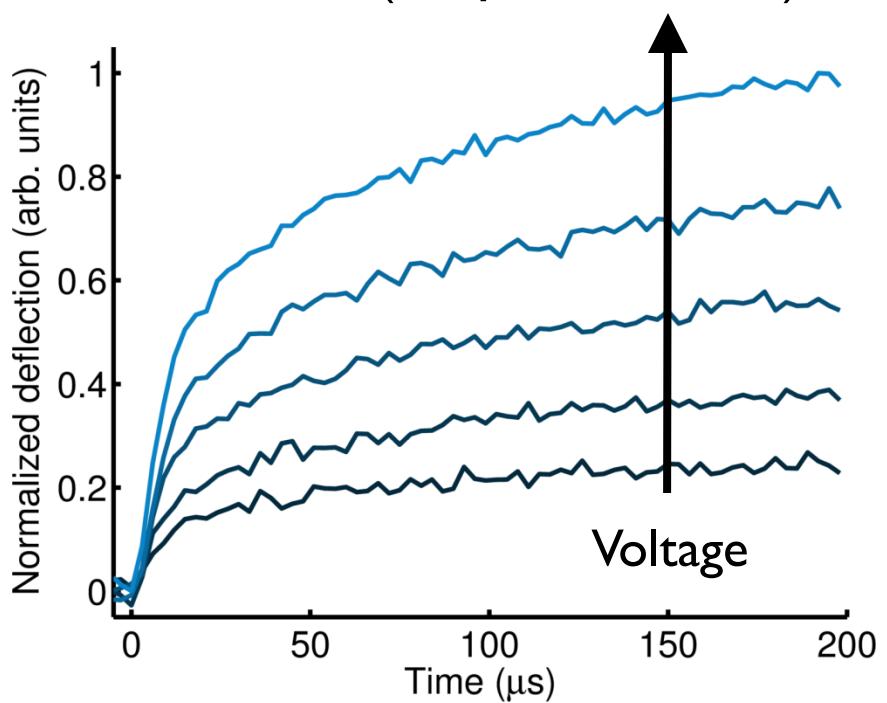


# Thermal actuation – slower than expected

Air (90  $\mu$ s rise time)

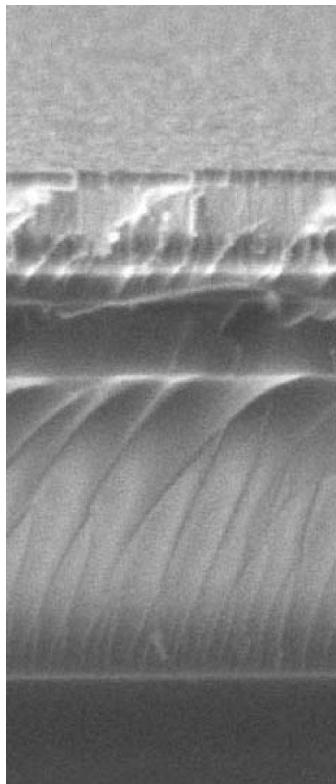


Water (80  $\mu$ s rise time)

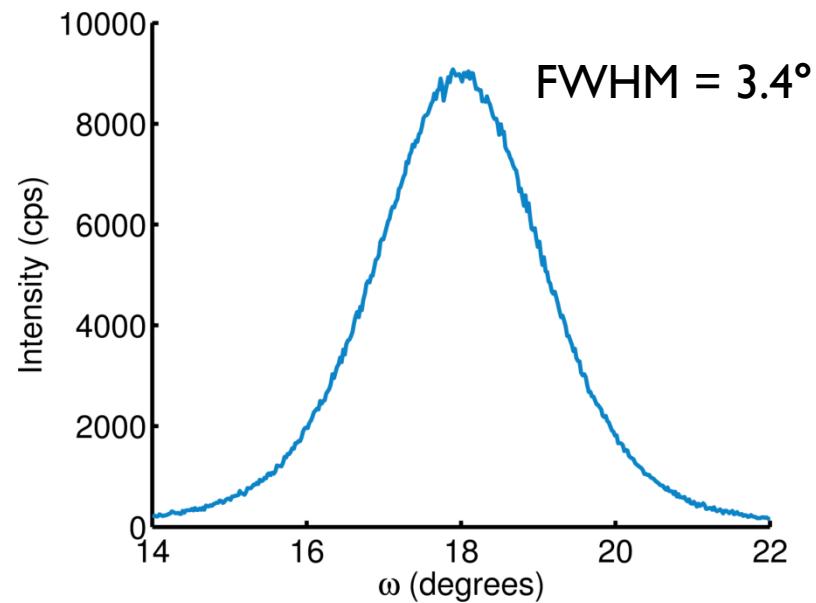
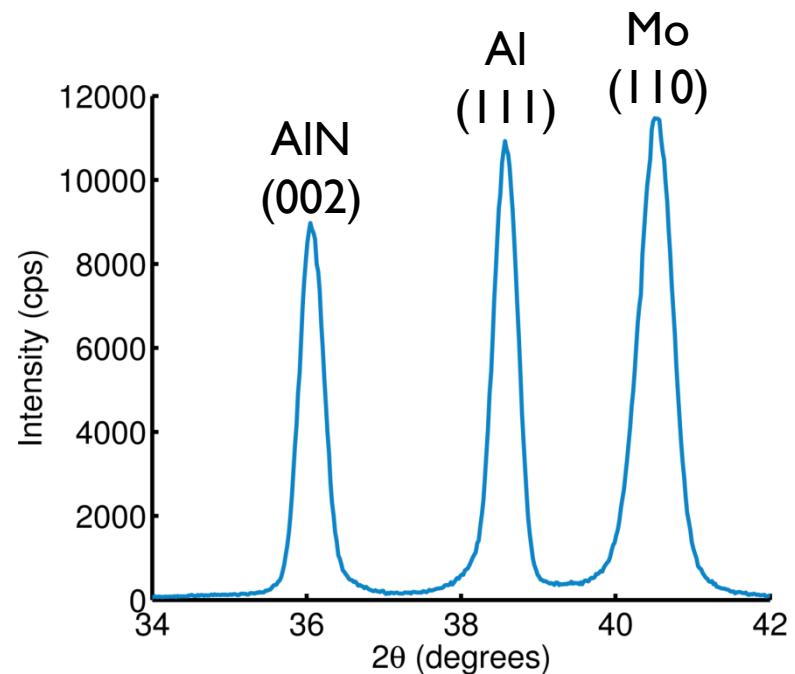


(measured with Anton Peng by projecting the probe shadow onto a photodiode pair)

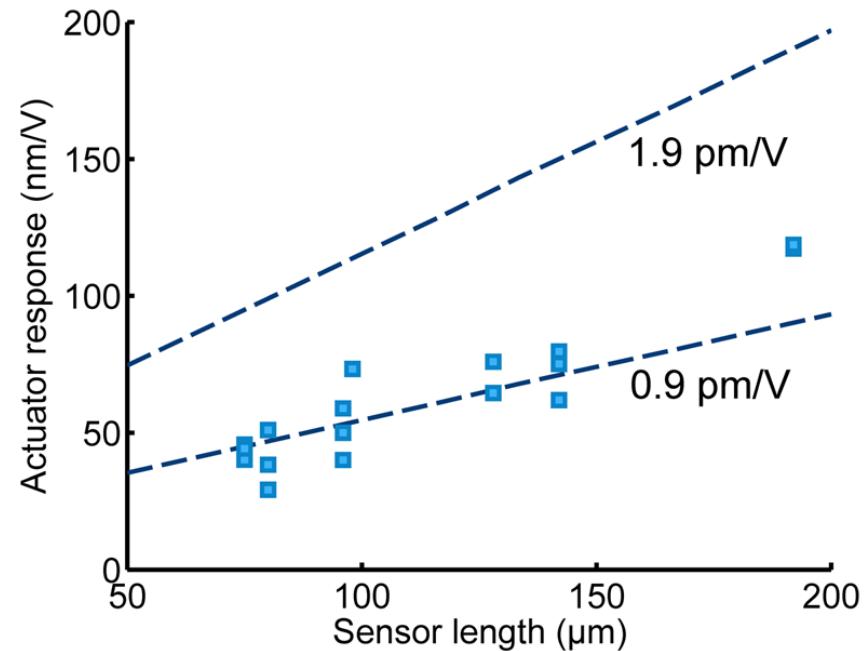
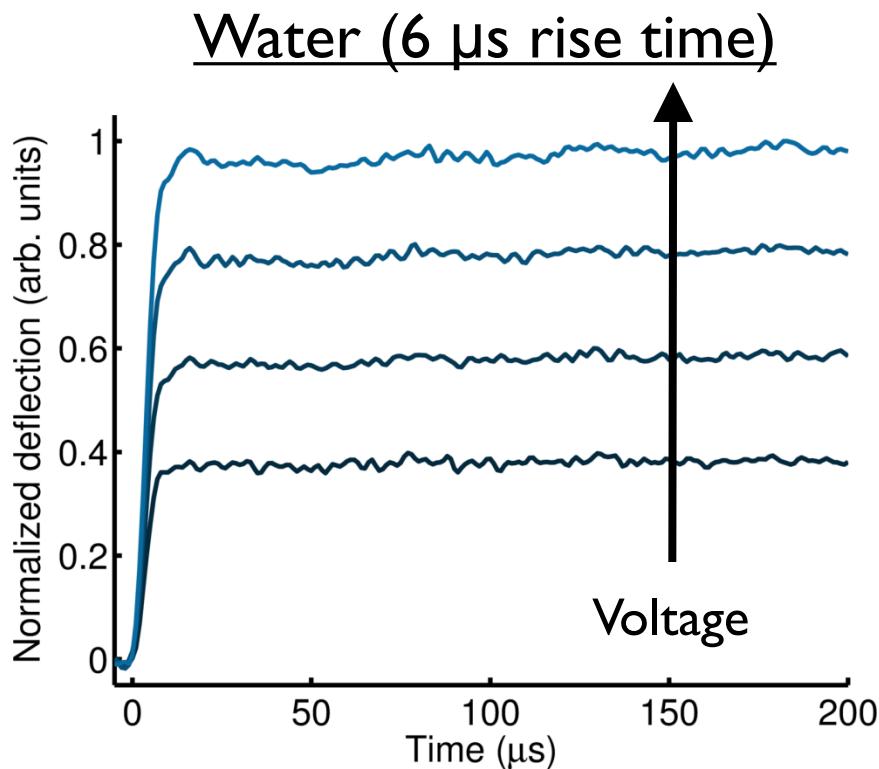
# Piezoelectric films have good crystallinity



- [white square] Si
- [blue square] SiO<sub>2</sub>
- [yellow square] AlN
- [dark green square] Mo

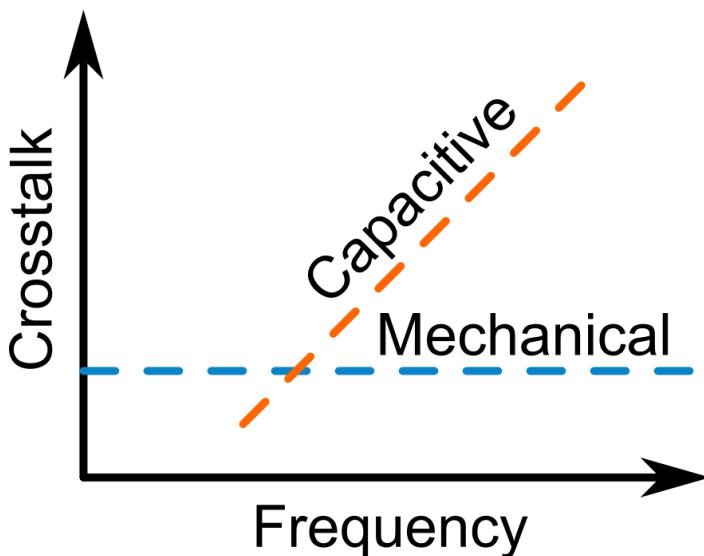
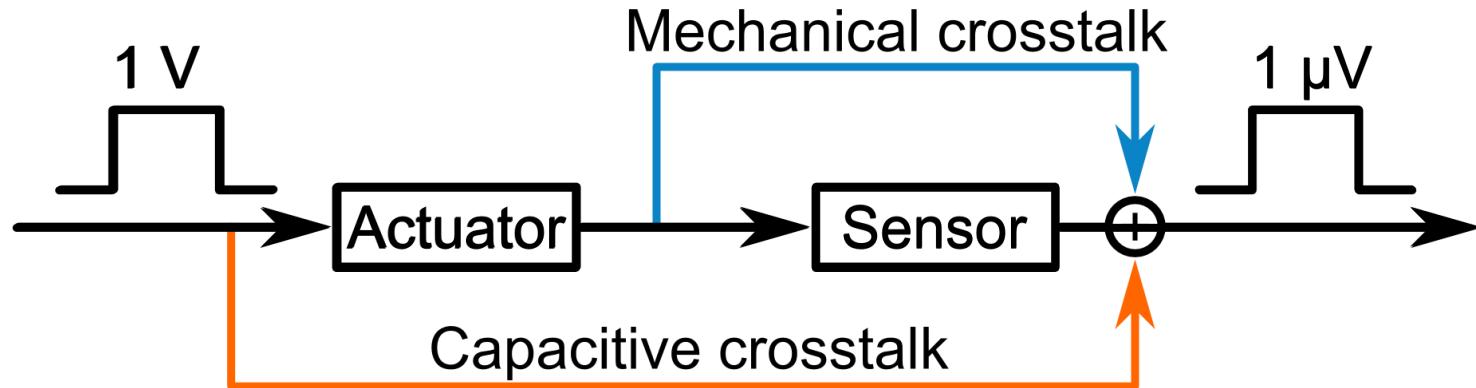


# Piezoelectric actuation is fast



# System integration and hair cell experiments

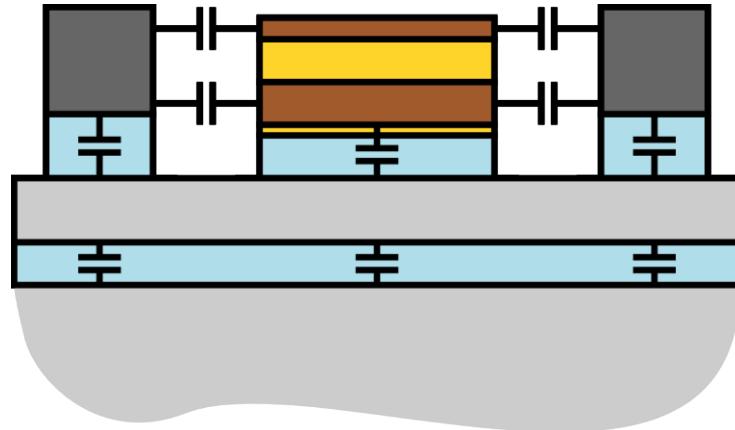
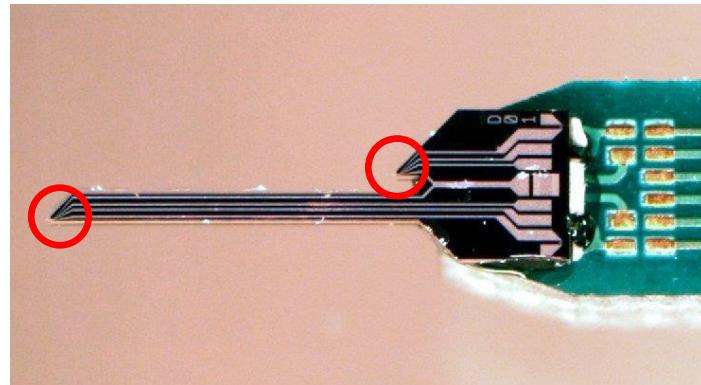
# Actuator-sensor crosstalk



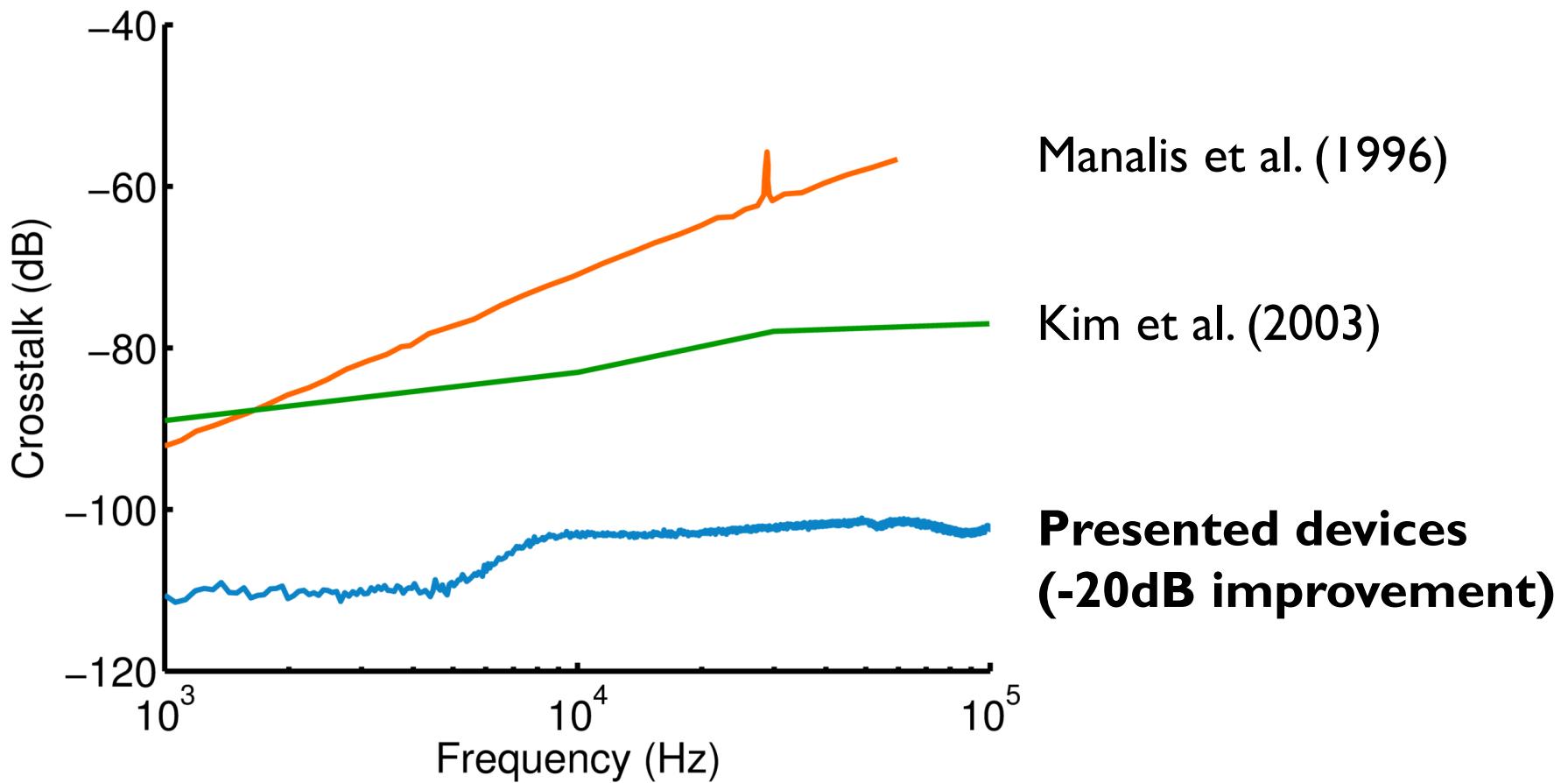
The actuator signal is  $10^6$ -fold greater than the sensor signal

# Crosstalk compensation

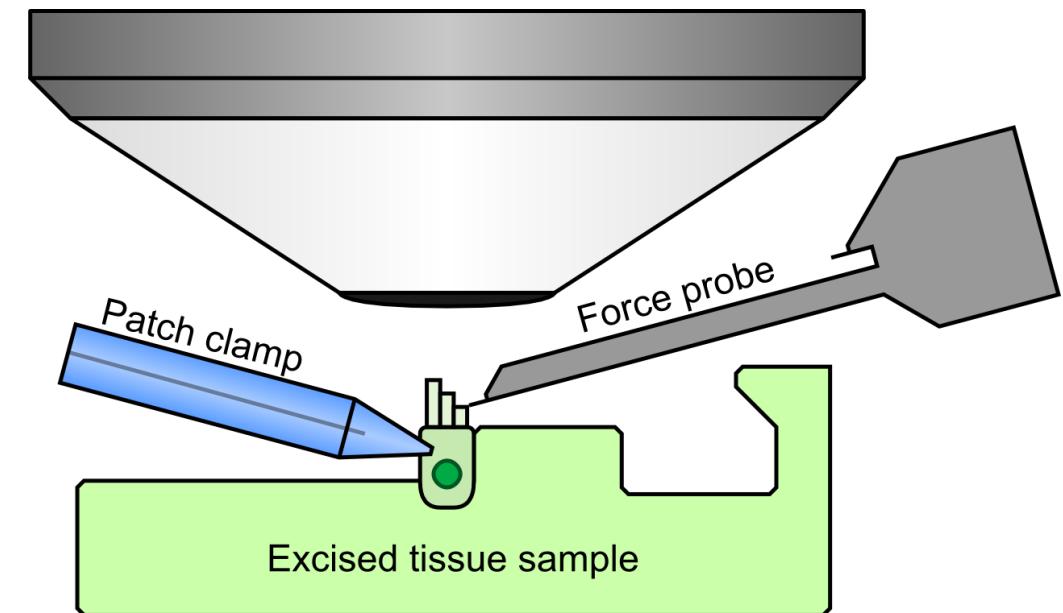
- 1) Identical compensation probe
- 2) Diffusion well and isolation trench
- 3) Circuit-level compensation (varcap)



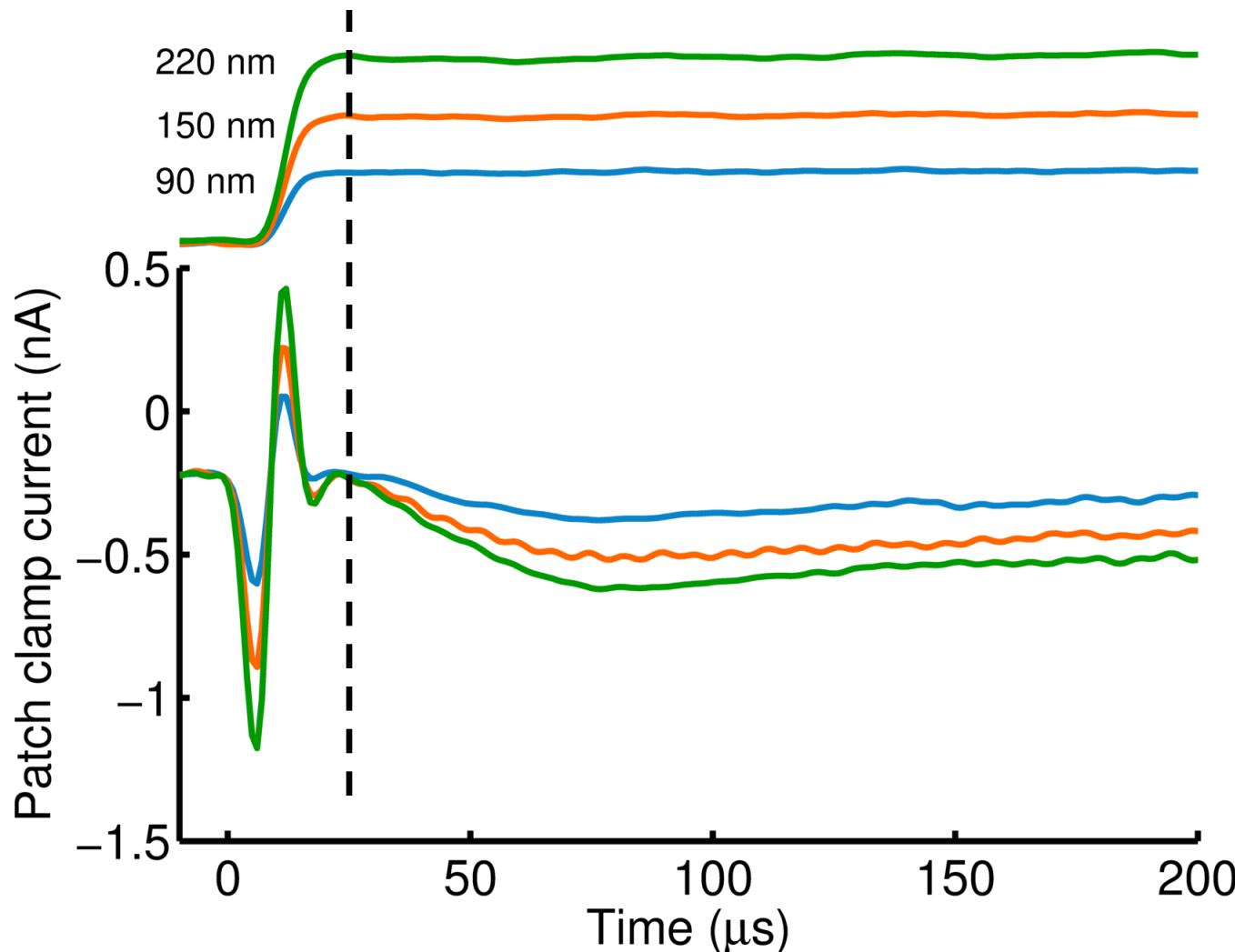
# Crosstalk is 10x smaller than previous work



# Measuring hair cell kinetics



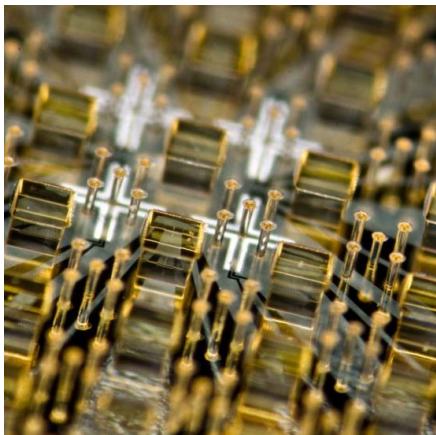
# Mammalian hair cell kinetics



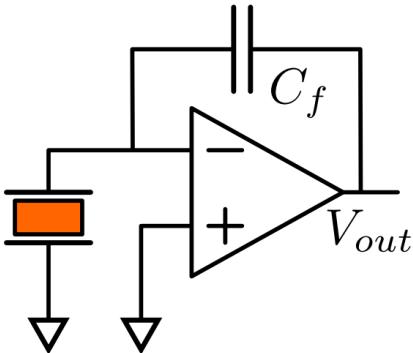
# Contributions

1. Developed new techniques for piezoresistor design optimization
2. Fabricated force probes capable of detecting and applying pN forces at the  $\mu$ s timescale
3. Integrated the probes with simultaneous patch clamp measurements to study mammalian cochlear hair cells

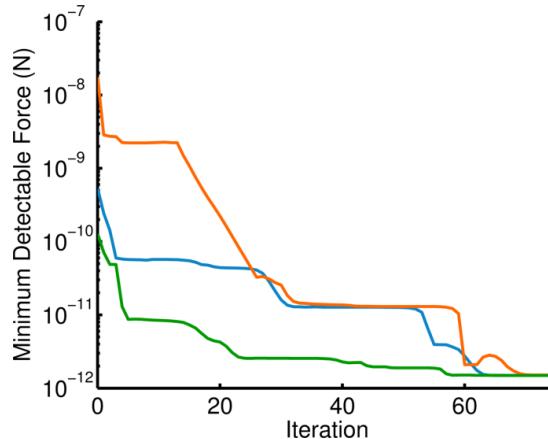
# Other parts of the story...



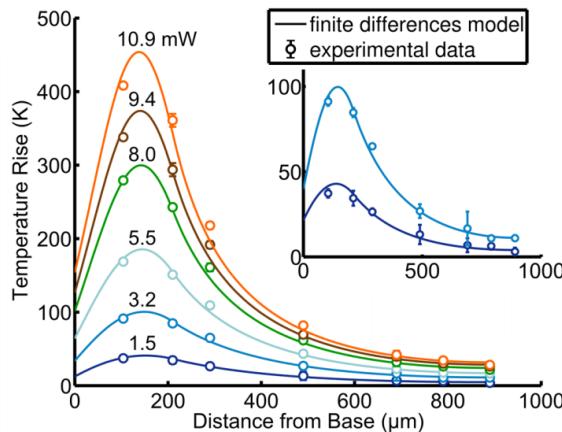
SU-8 force sensing pillar arrays  
for biological measurements  
Lab on a Chip (2009)



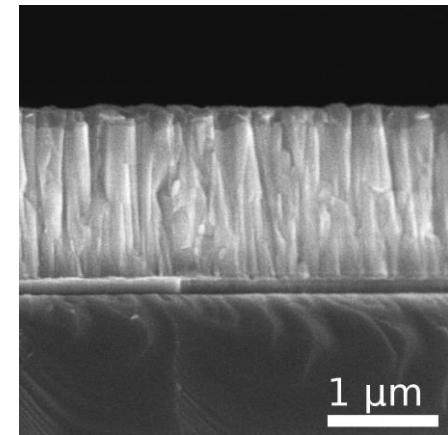
Design of PR vs. PE scanning probes  
JMM (2010)



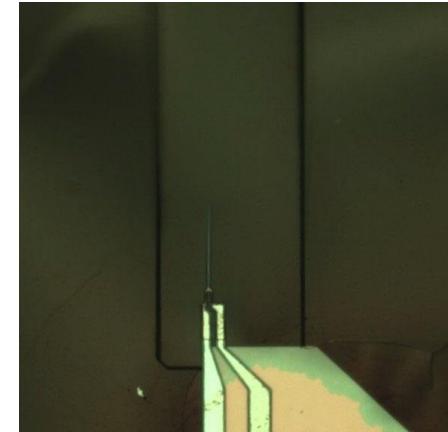
Design optimization of PR cantilevers  
for force sensing in air and water  
Journal of Applied Physics (2009)



Self-heating in piezoresistive cantilevers  
Applied Physics Letters (2011)



Aluminum nitride on titanium for CMOS  
compatible piezoelectric transducers  
JMM (2010)



Patterned cracks improve yield in the  
release of microdevices from SOI wafers  
JMM (2011)

# Acknowledgements



Prof. Beth Pruitt

# Acknowledgements



Prof. Roger Howe



Prof. Miriam Goodman



Prof. Ellen Kuhl



Prof. Tony Ricci

# Acknowledgements



# Acknowledgements

## Worm Club



## SNF Staff and User Community



### Collaborators

Elise Corbin  
Shana Geffeney  
Haneesh Kesari  
Anton Peng

### PR Gang

Alex Haemmerli  
Nahid Harjee  
Joe Mallon  
Sung-Jin Park  
Ali Rastegar

### Fab Gurus

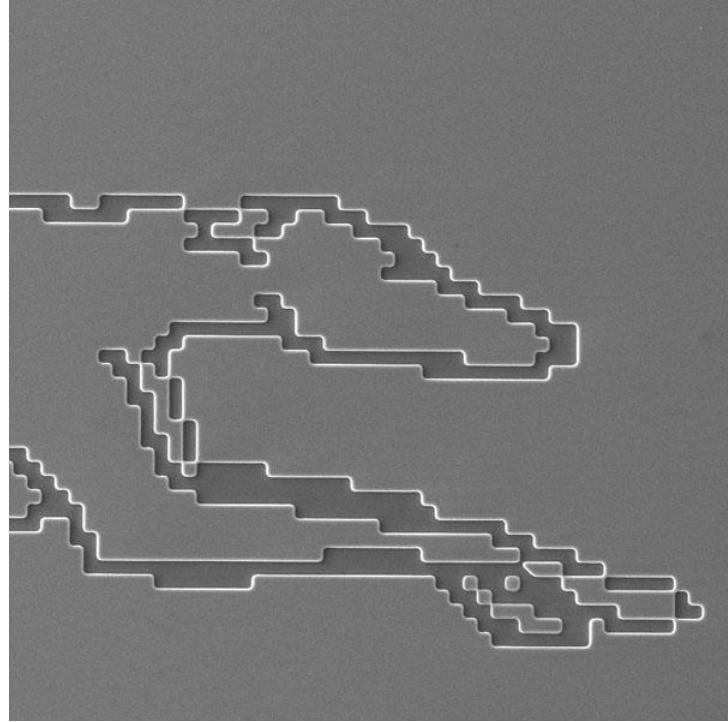
Ginel Hill  
Rishi Kant  
Tina Lamers  
Eric Perozziello  
J Provine  
Gary Yama

+ many more

# Acknowledgements

Friends, family and Cassie



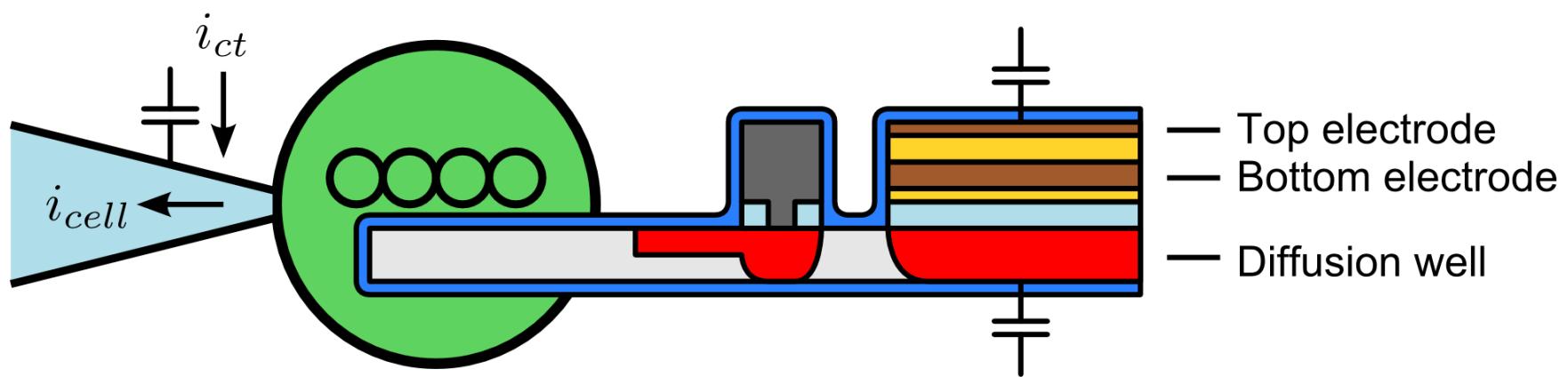


**Thank you for listening!**

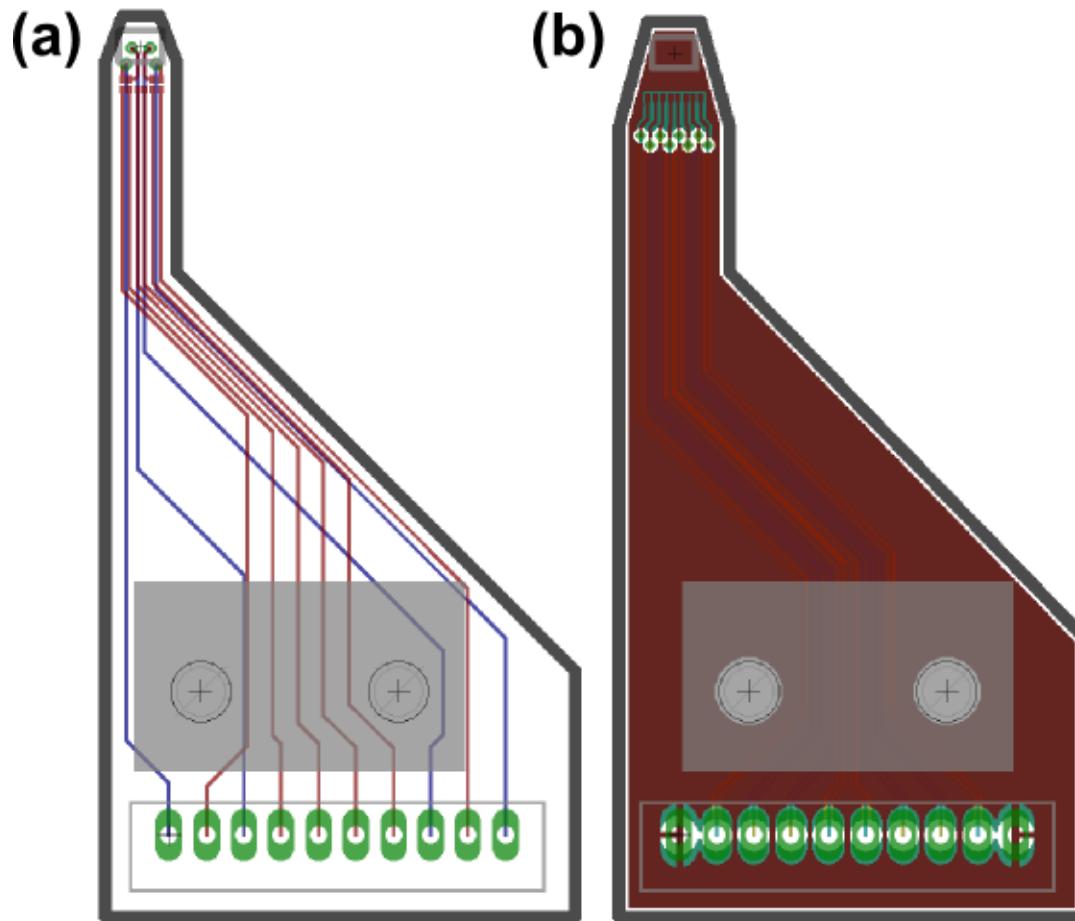


# Bonus slides

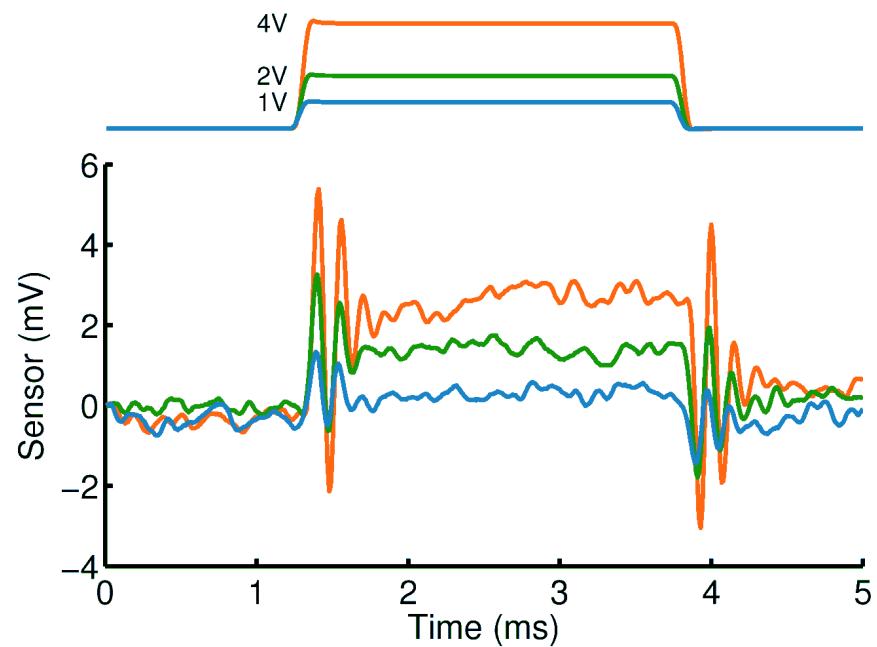
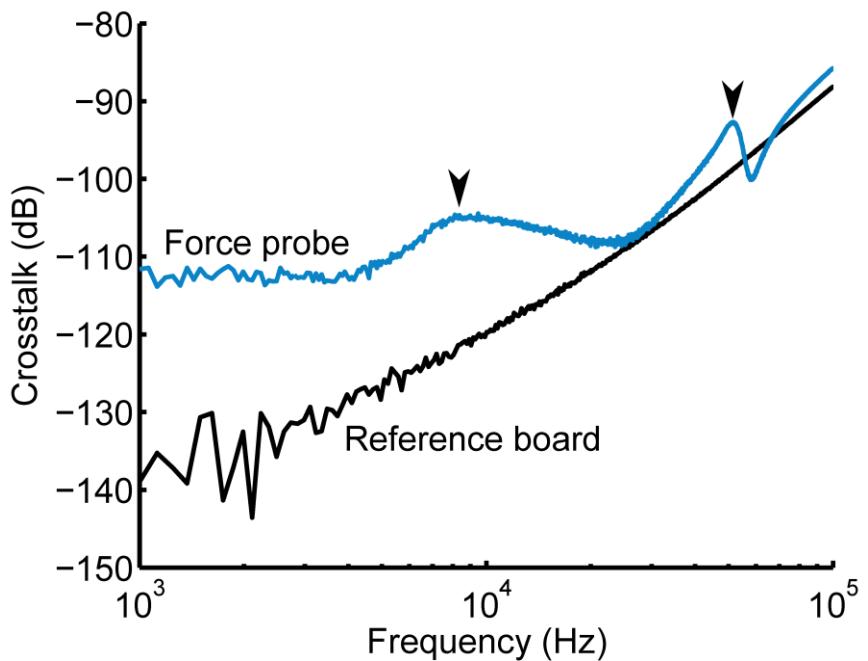
# Patch clamp crosstalk



# 2- and 4- layer cantilever PCBs



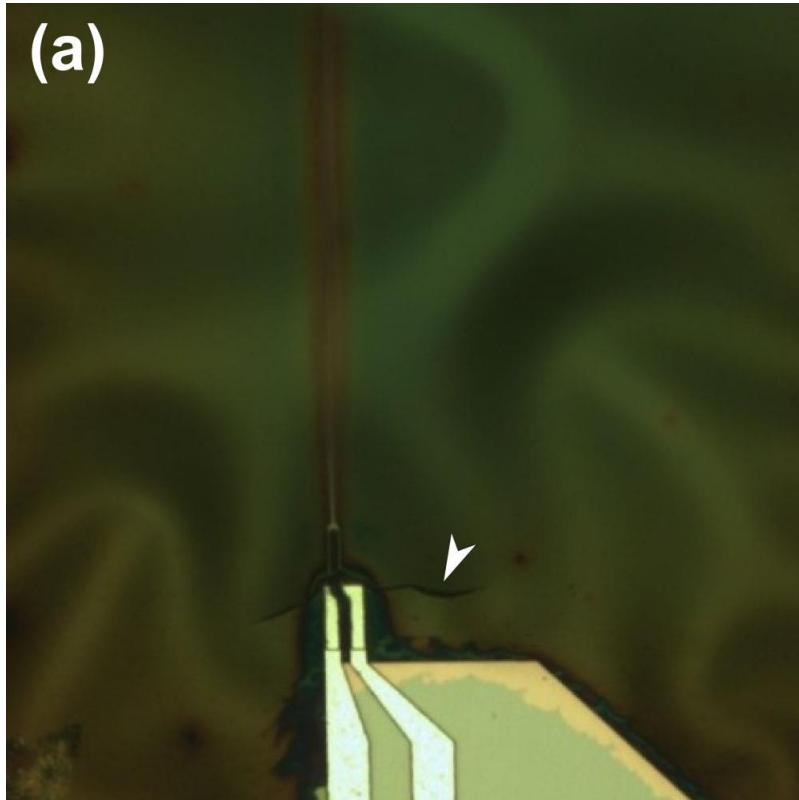
# Mechanical crosstalk



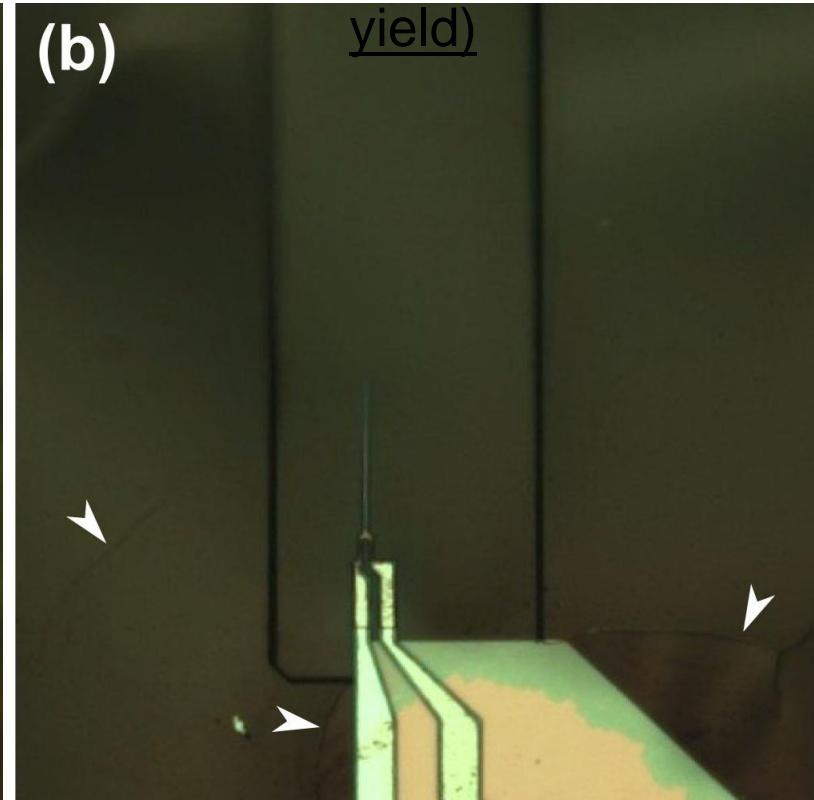
0.65 pN/nm (parylene coated)  
7.3 kHz (in air)  
75 nm/V deflection  
1 mV = 0.2 pN

# Patterned cracks doubled probe yield

Initial devices (16-50% yield)

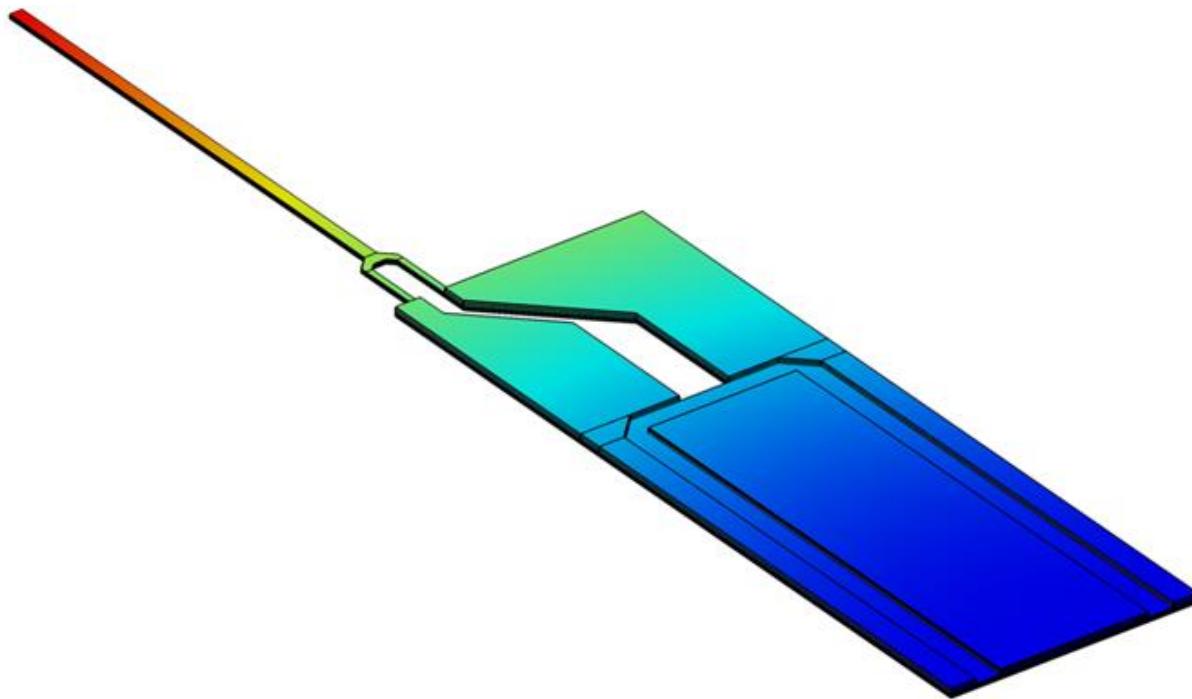


Patterned cracks (50-90% yield)



Patterned cracks improve yield in the release of compliant microdevices from SOI wafers  
G.C. Hill, J.I. Padovani, J.C. Doll, B.W. Chui, D. Rugar, H.J. Mamin, N. Harjee, B.L. Pruitt  
Journal of Micromechanics and Microengineering (2011)

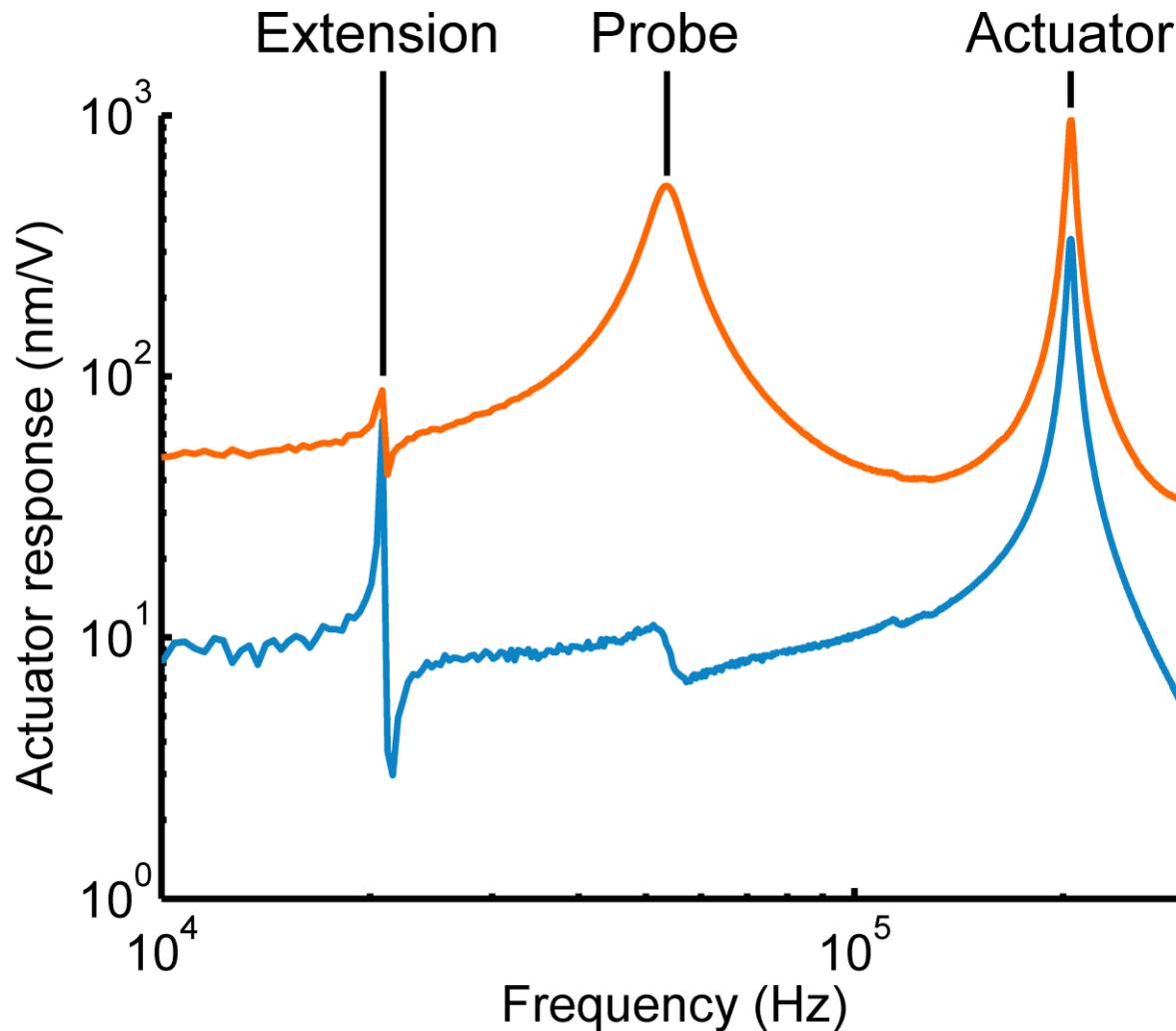
# Actuator bandwidth



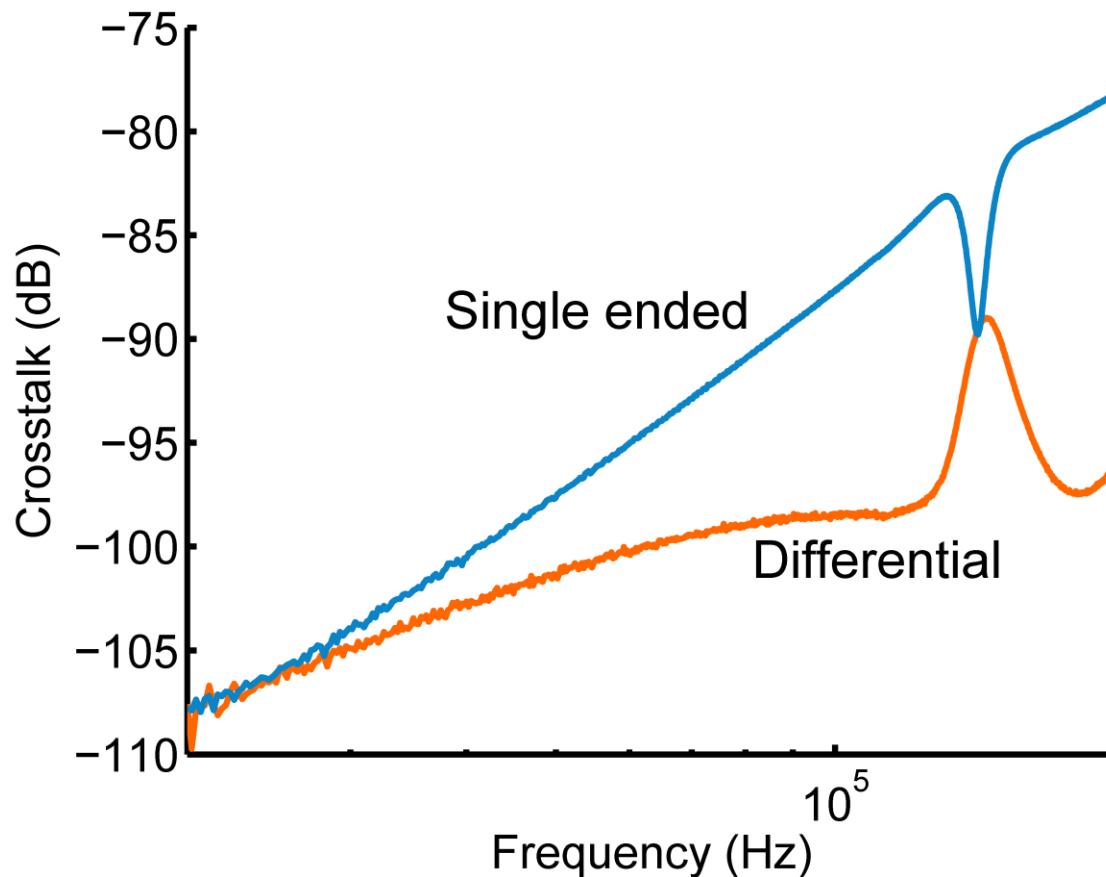
Calculation methods for  $k$  and  $f_0$ :

- 1) 1D numerical (i.e. Rayleigh-Ritz)
- 2) FEA (Comsol) for spot checks

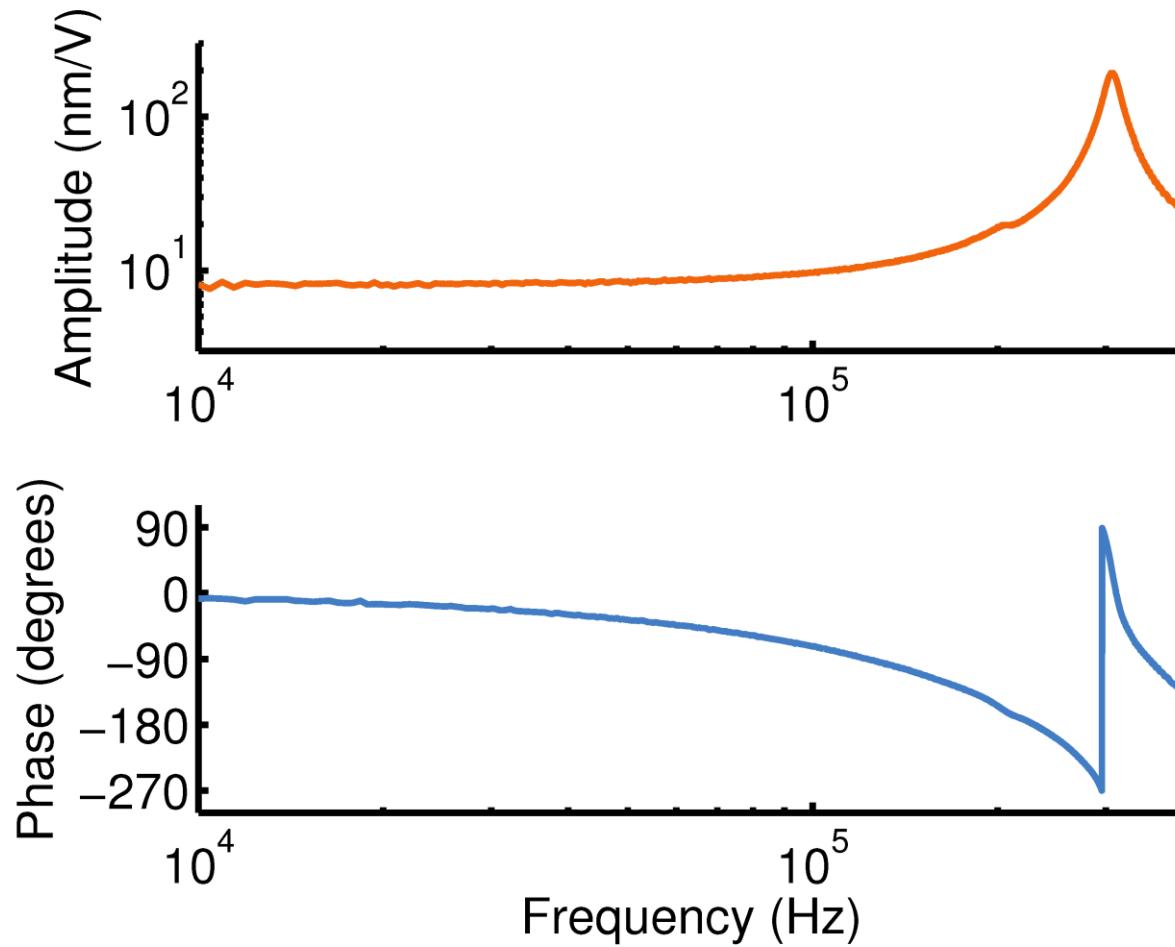
# Actuator bandwidth



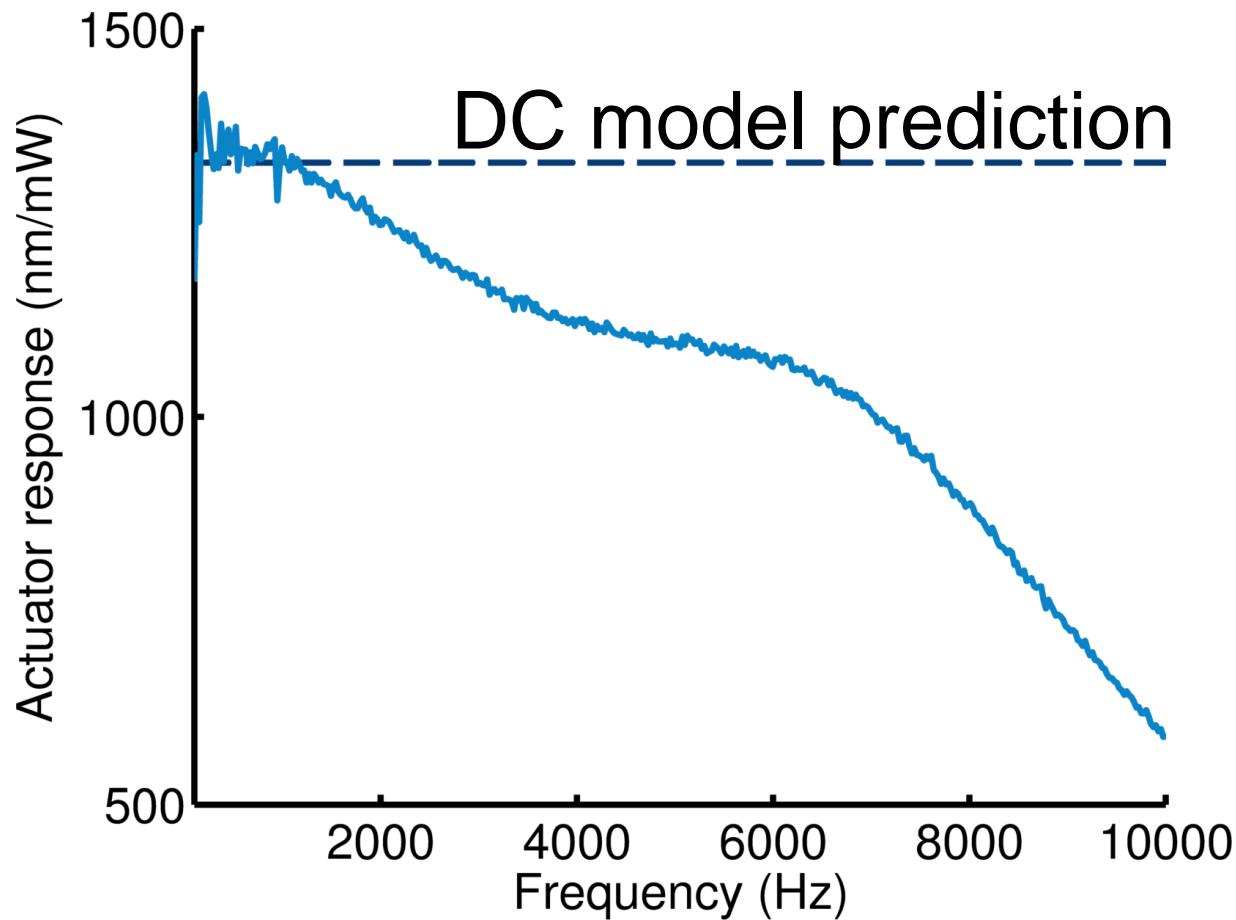
# Single ended vs. differential drive

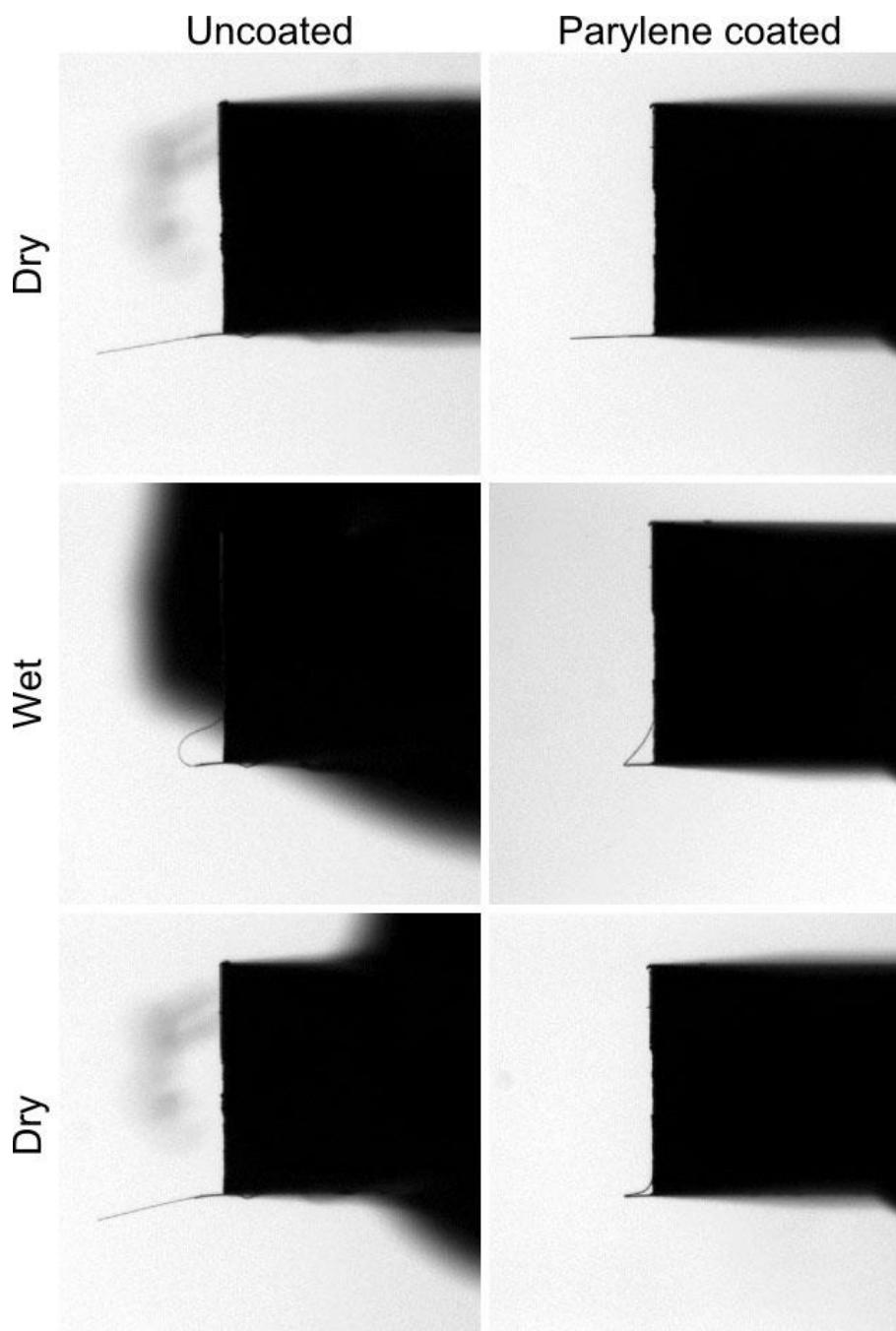


# Piezoelectric actuator bandwidth

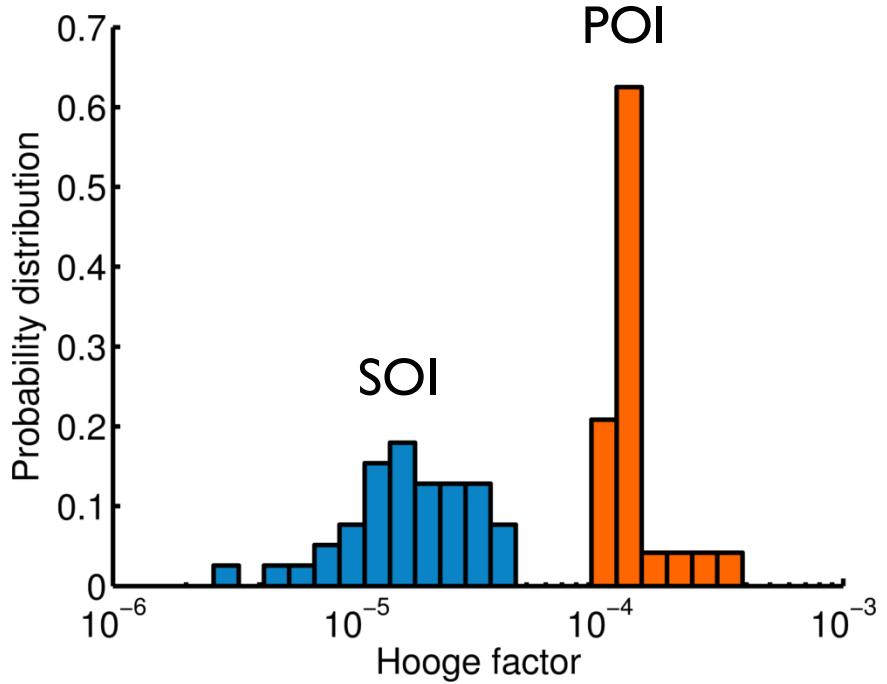
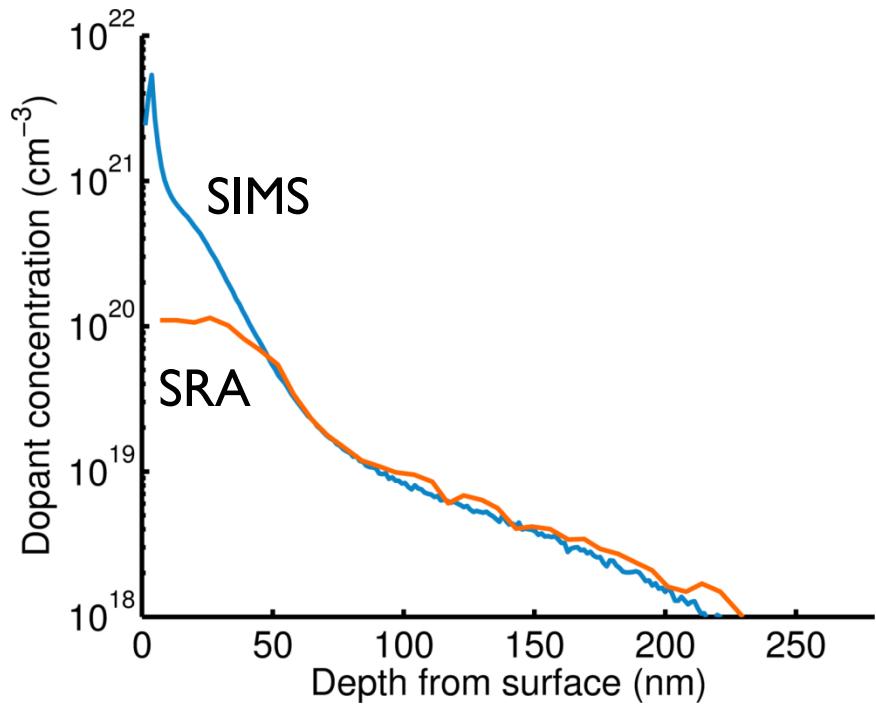


# Thermal actuator frequency response

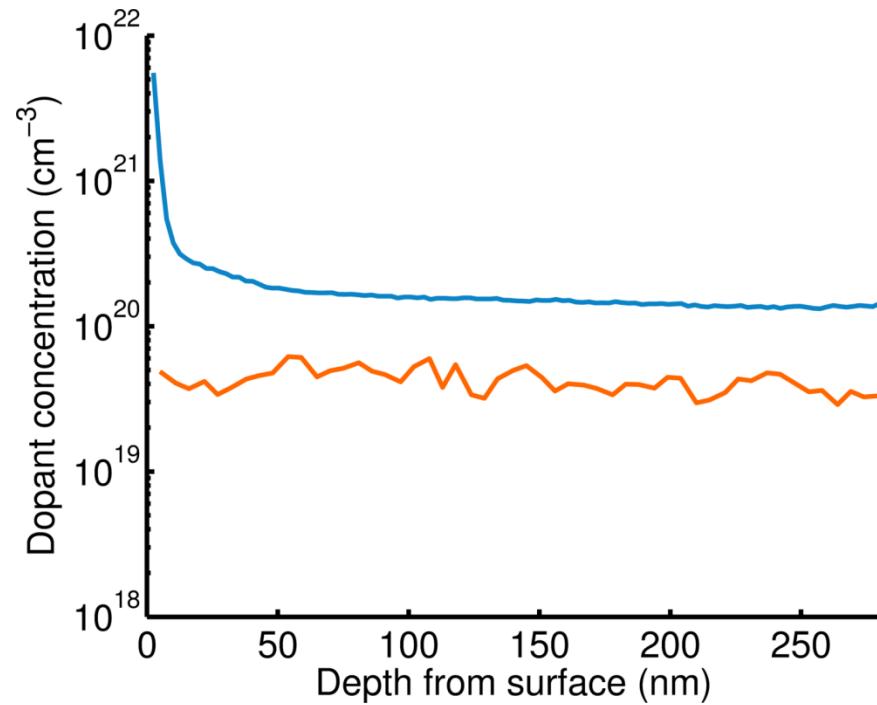
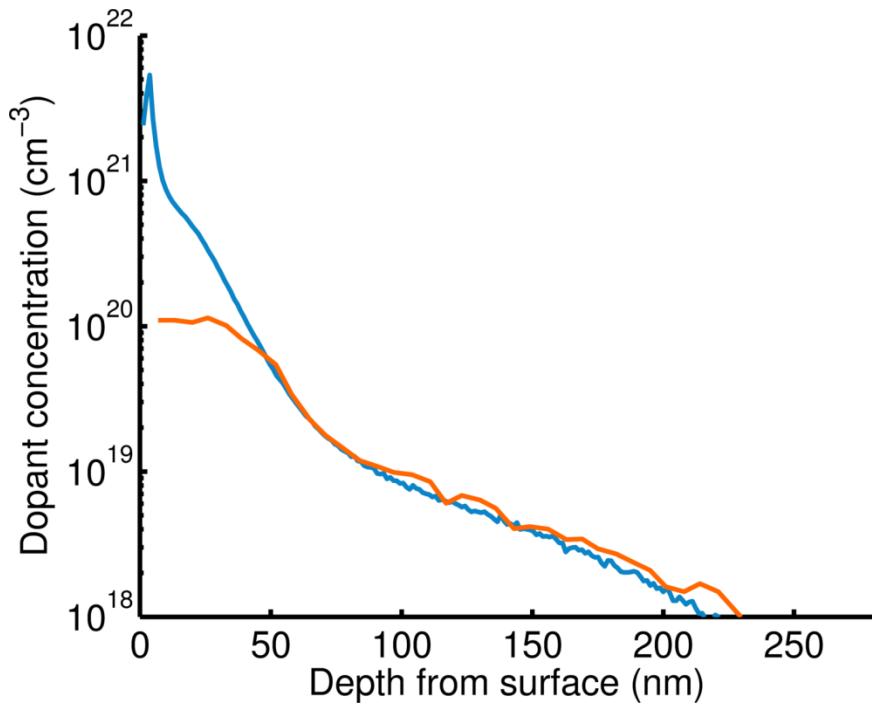




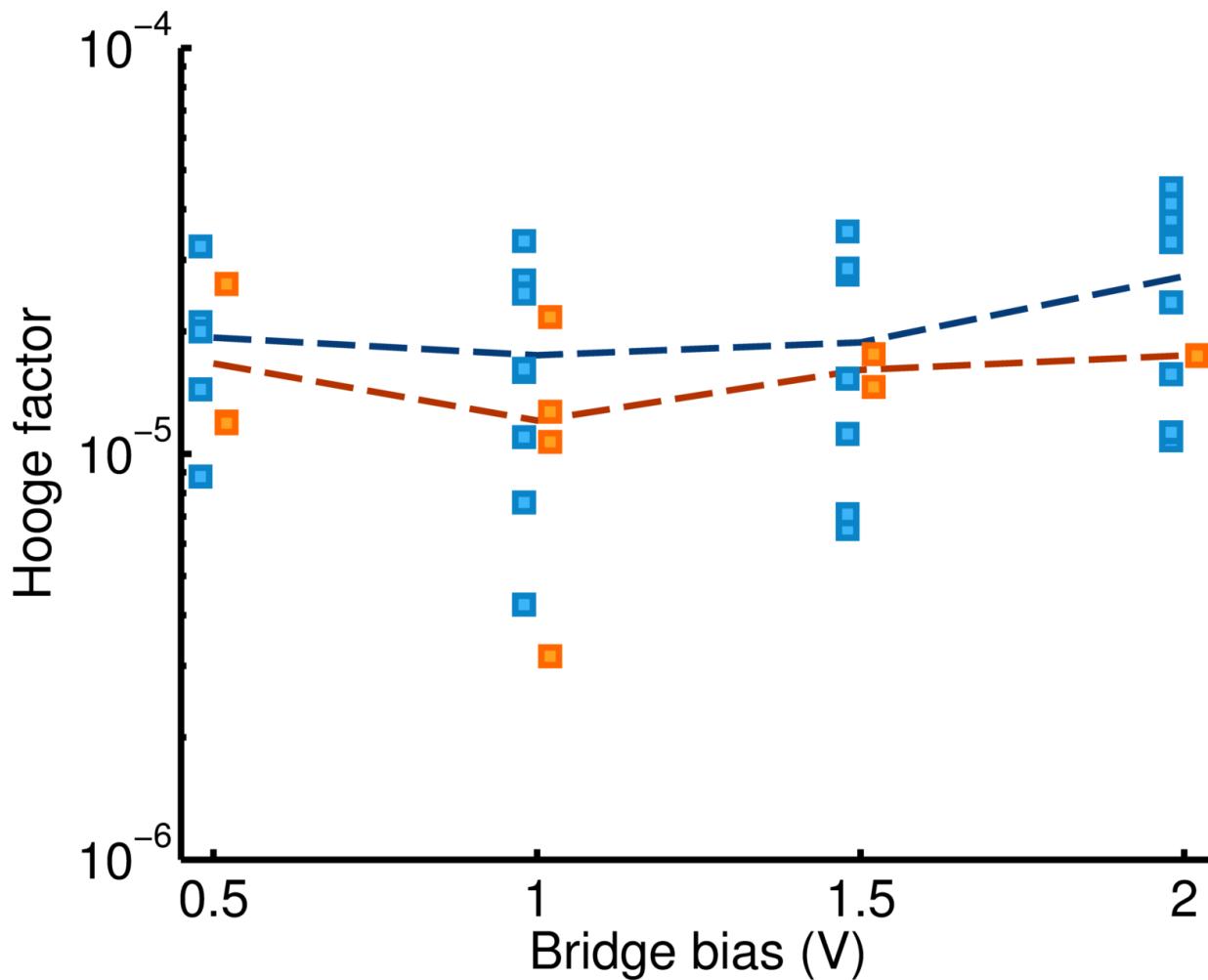
# Piezoresistor noise



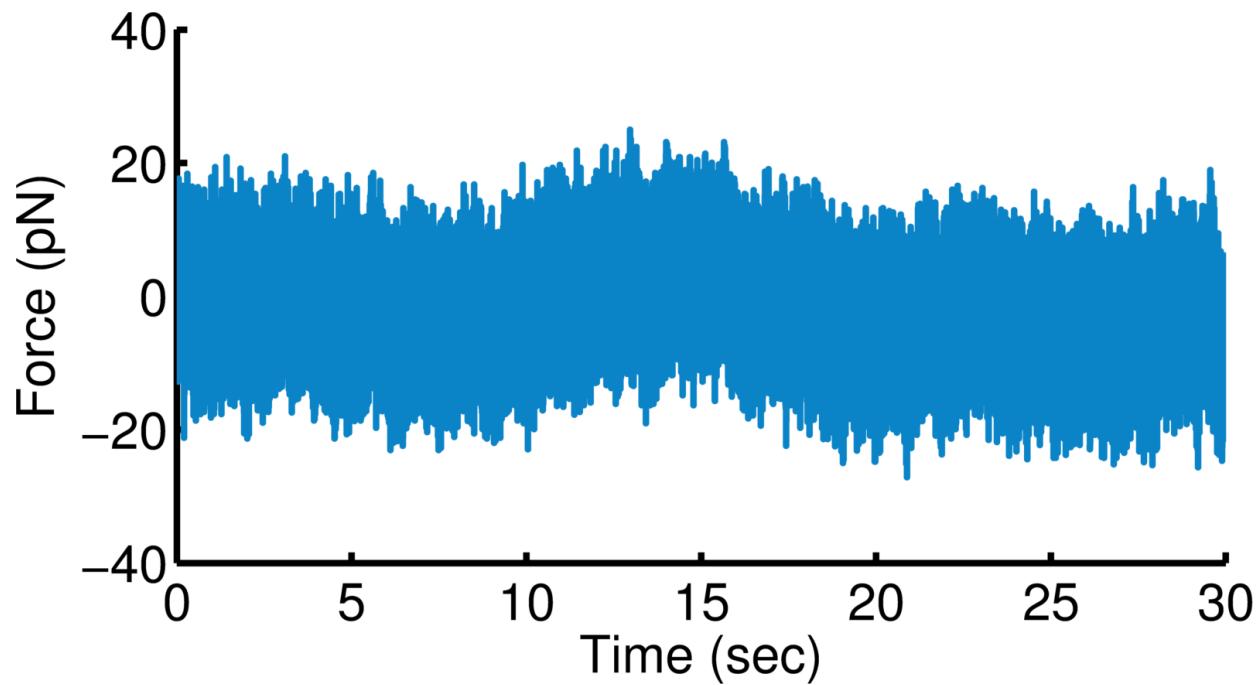
# c-Si vs. poly concentration profiles



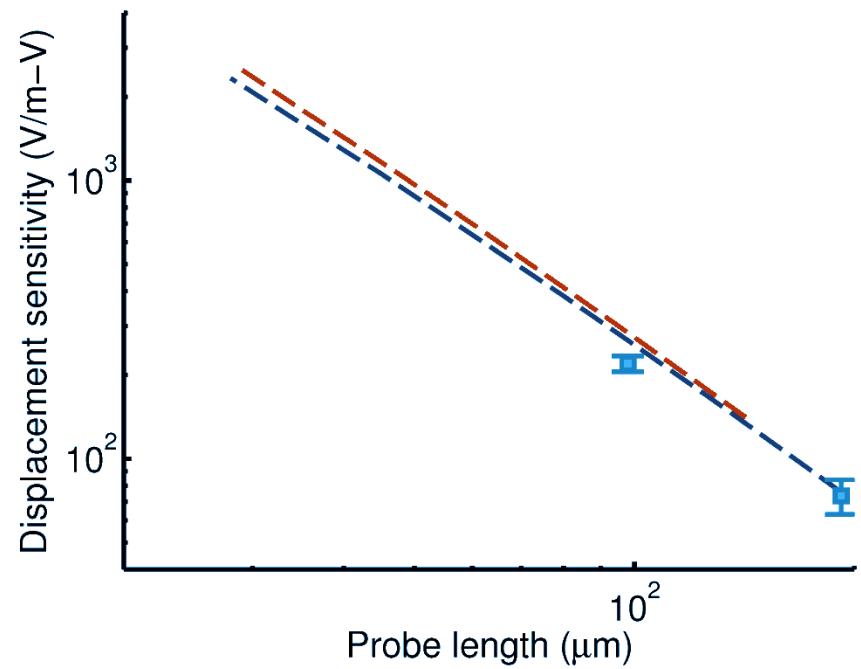
# Piezoresistor noise



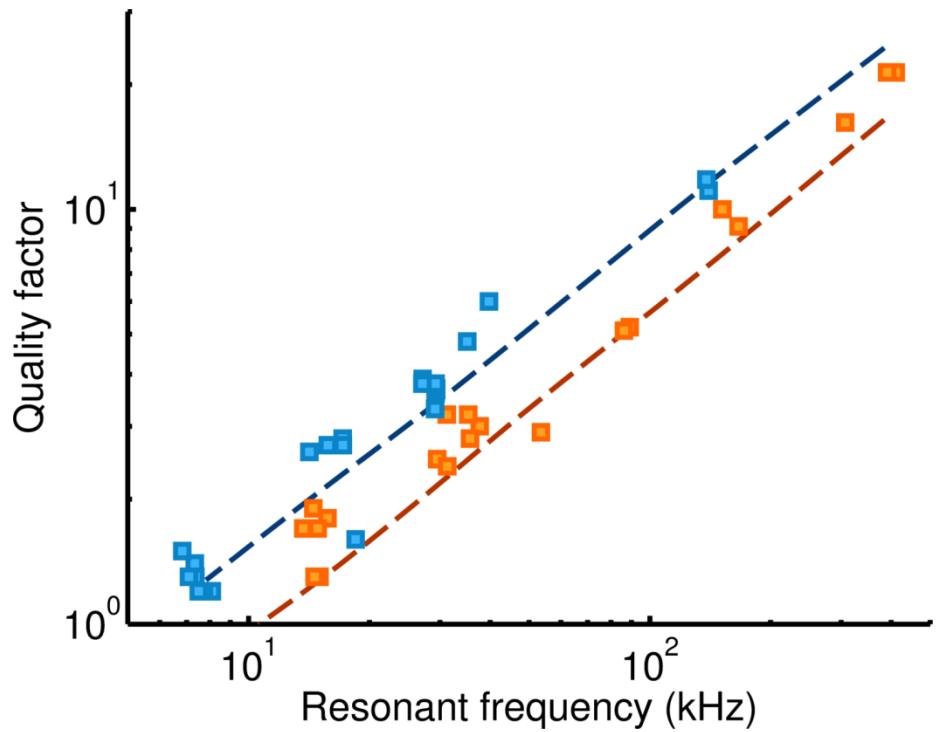
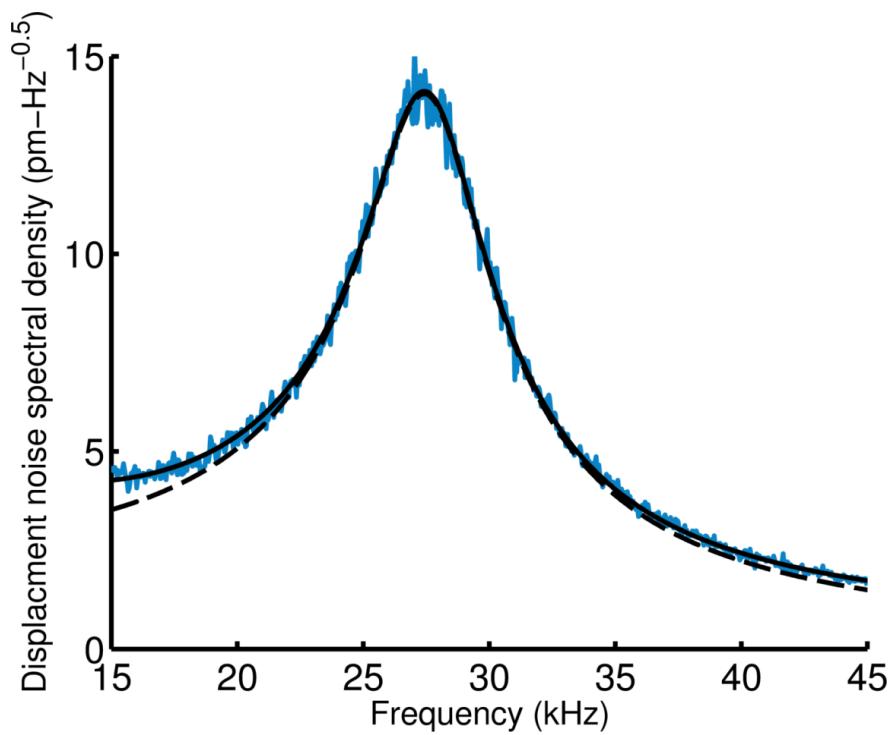
# Piezoresistor noise



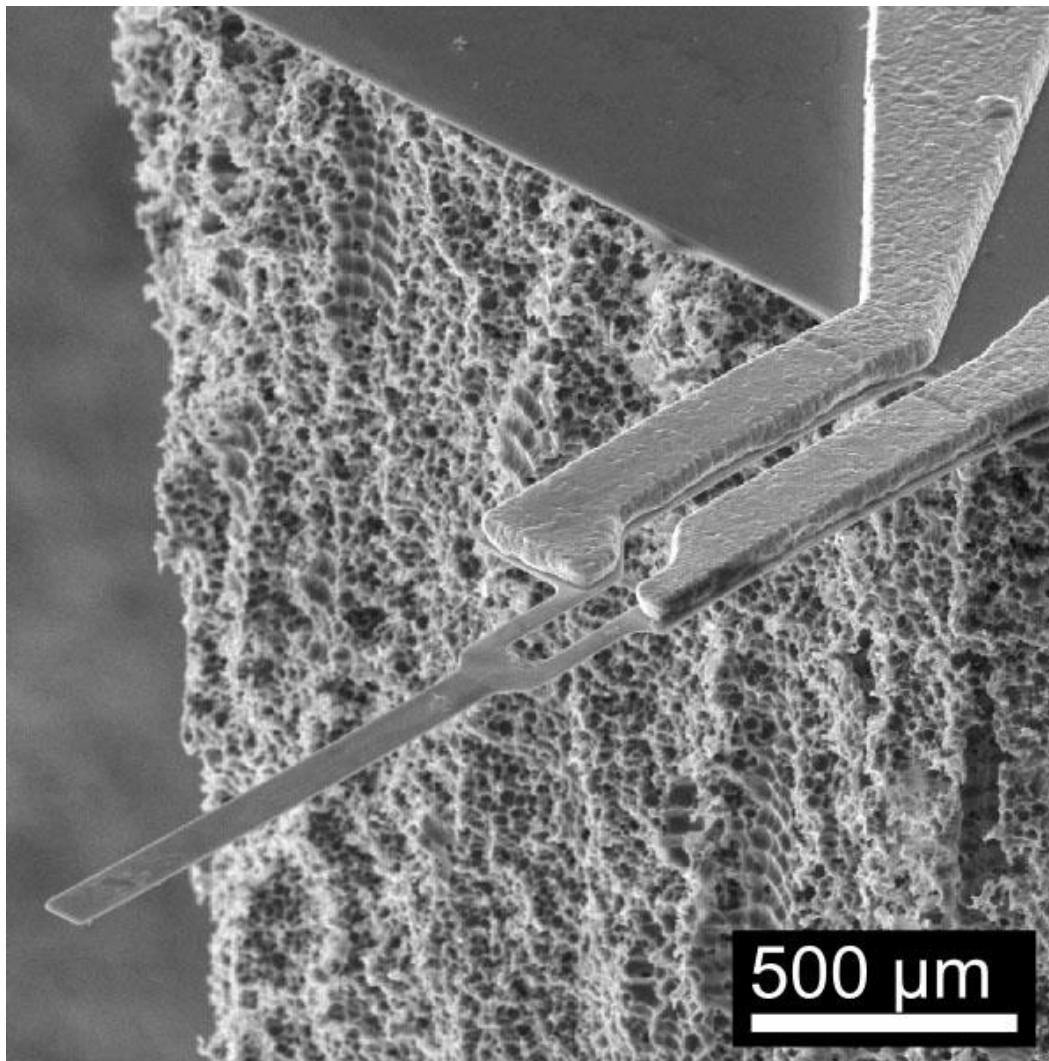
# Sensitivity measurements



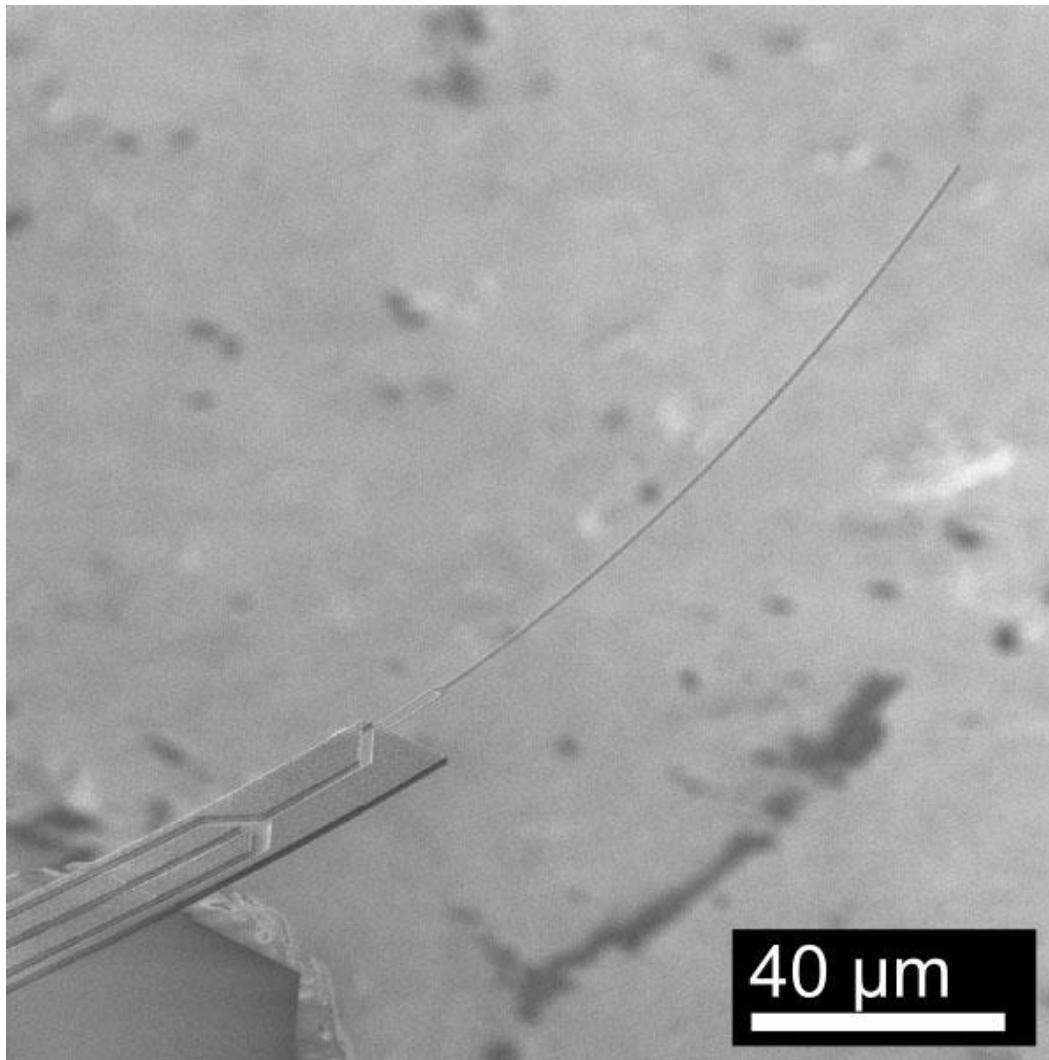
# TMN and quality factor scaling



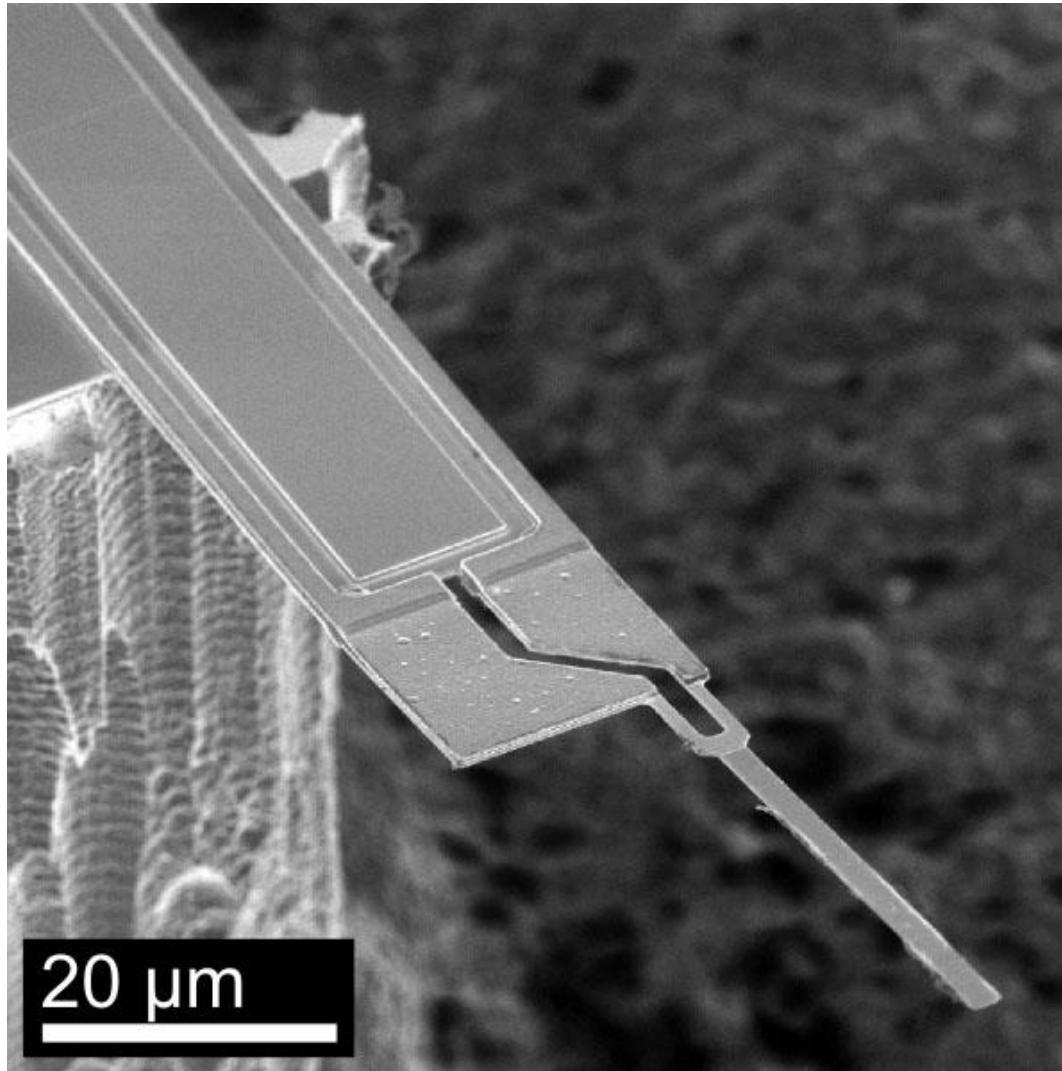
# Finished Device SEMs



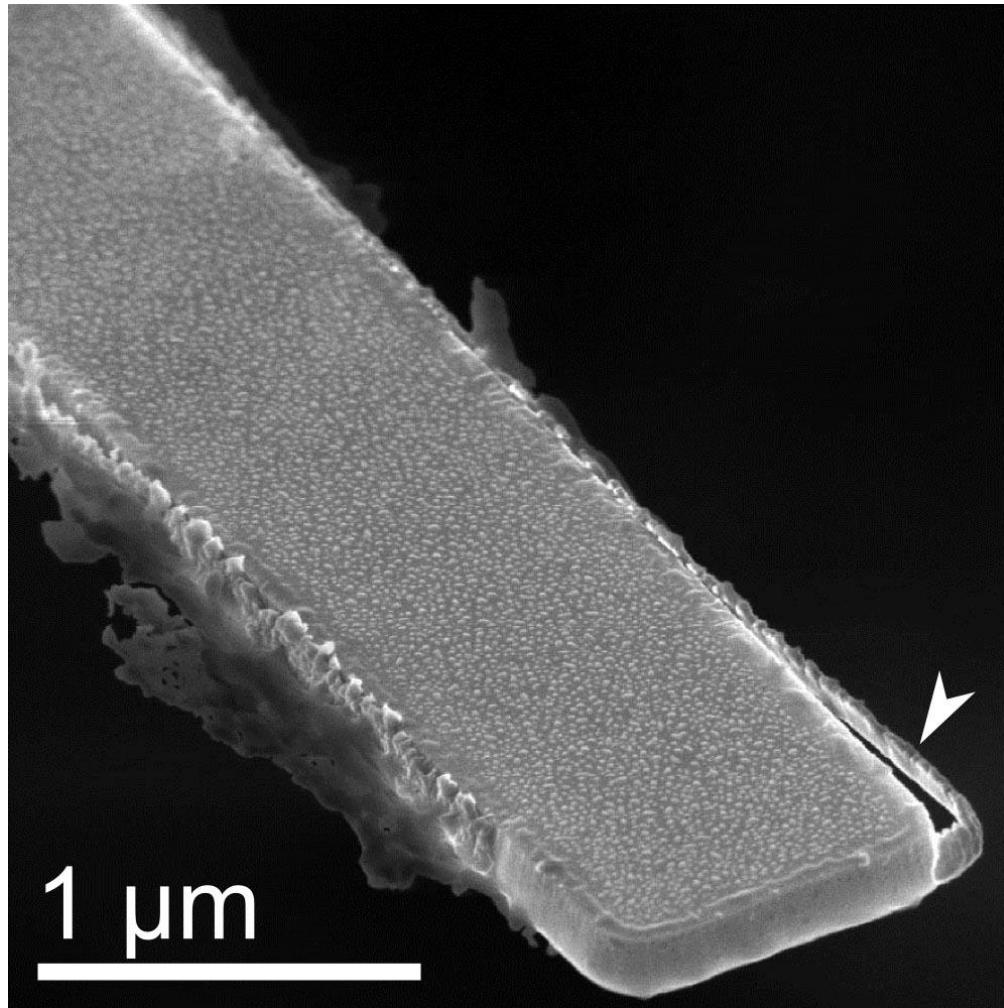
# Finished Device SEMs



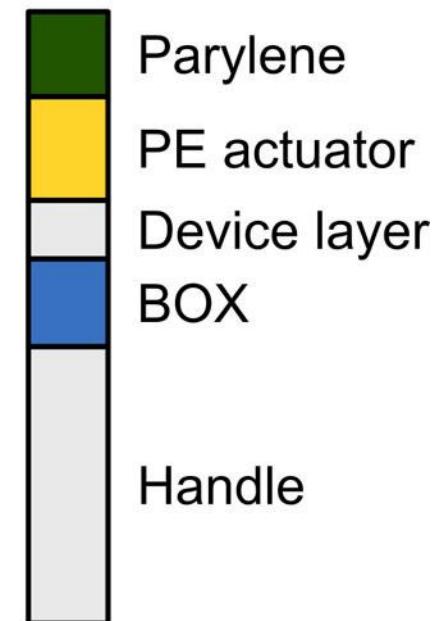
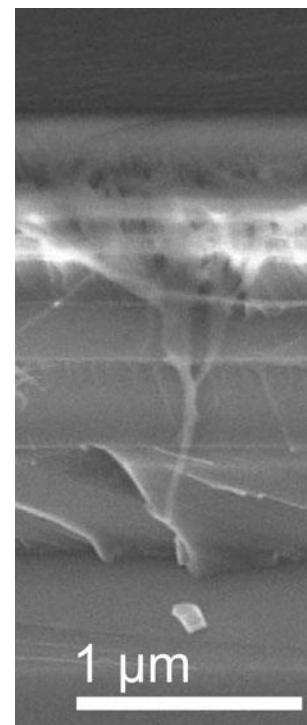
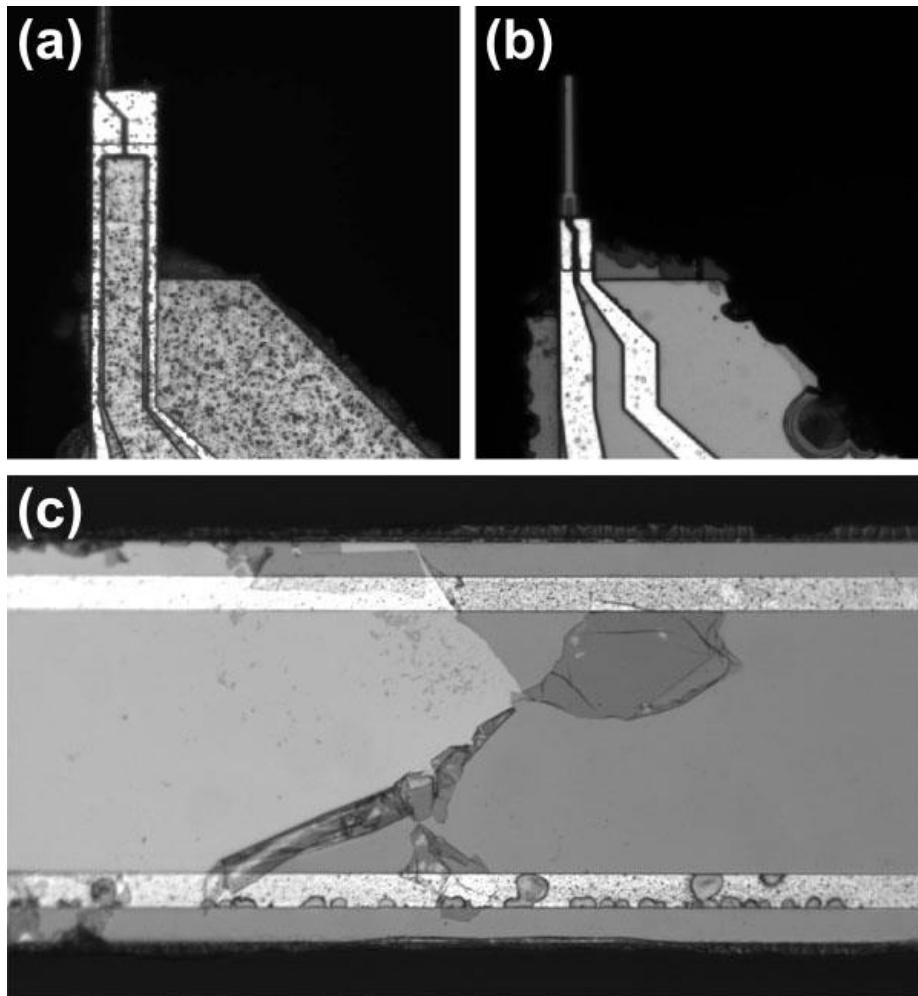
# Finished Device SEMs



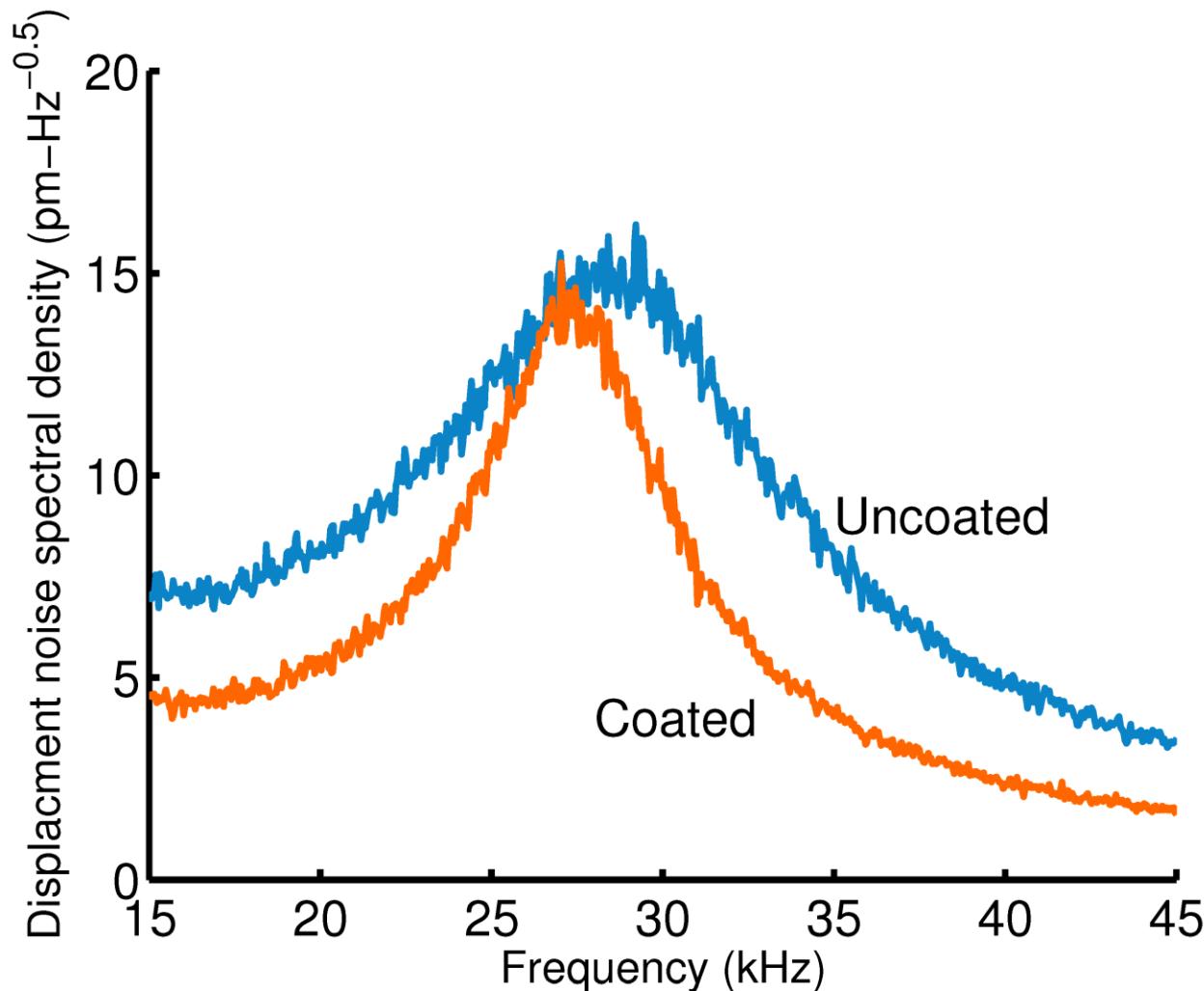
# Stringers



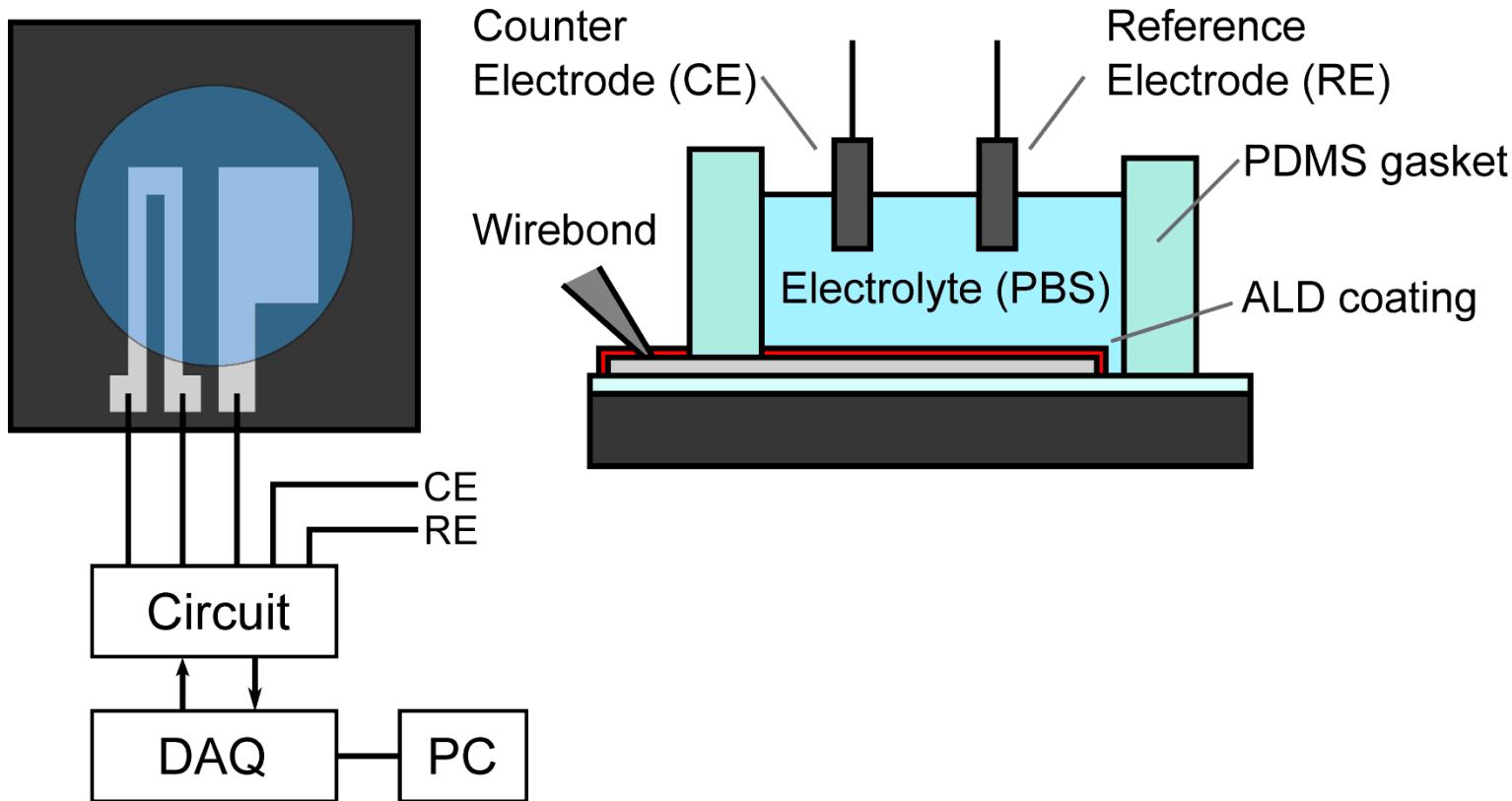
# Parylene passivation



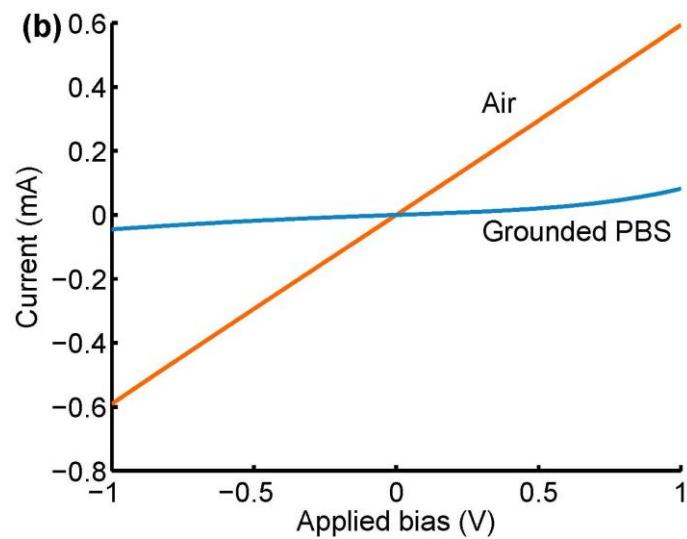
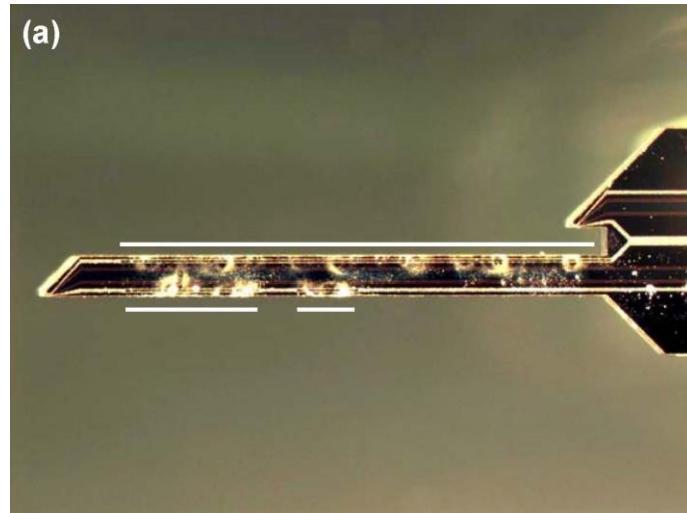
# Parylene passivation



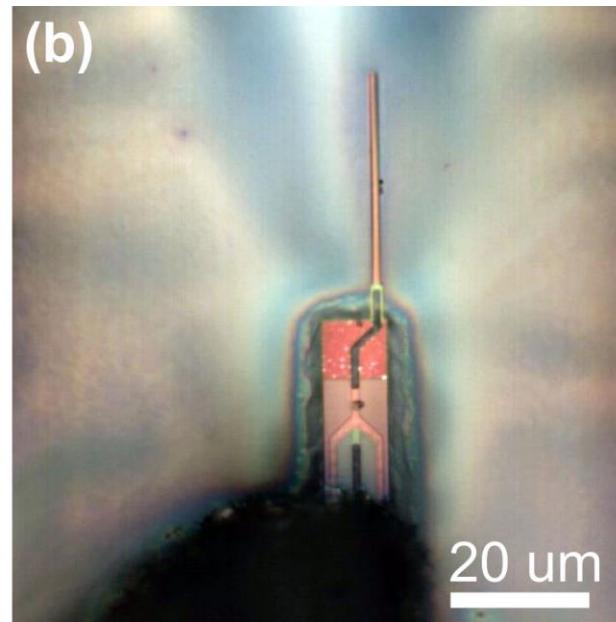
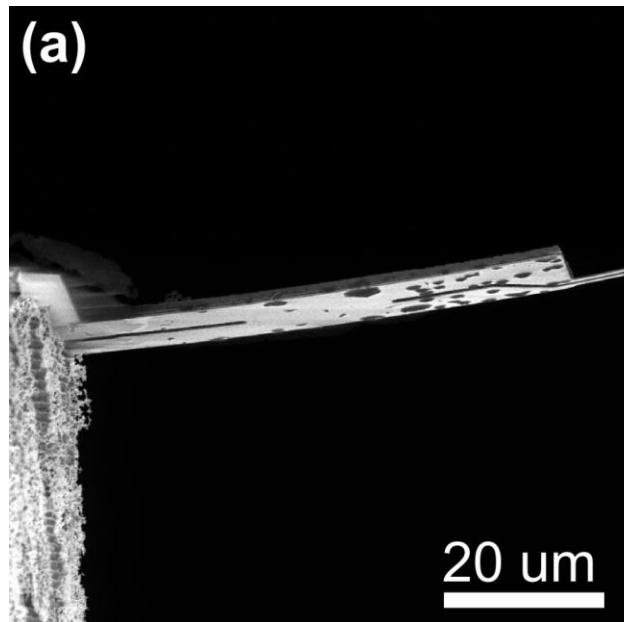
# ALD passivation



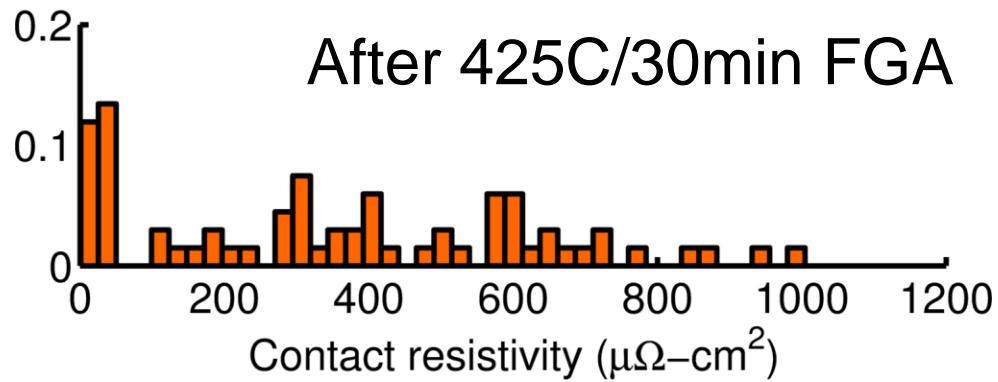
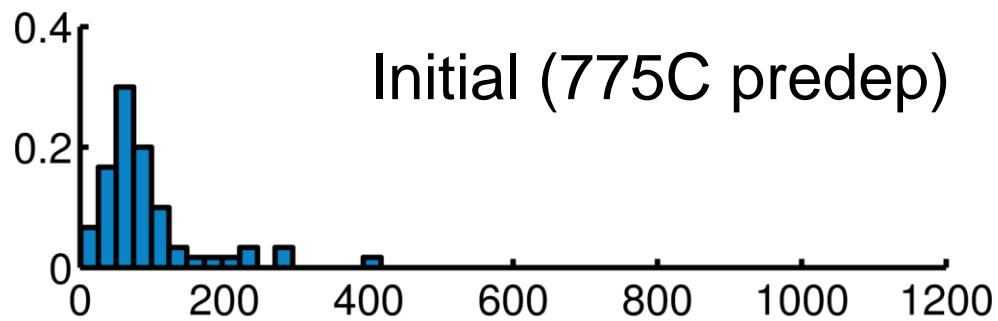
# ALD passivation



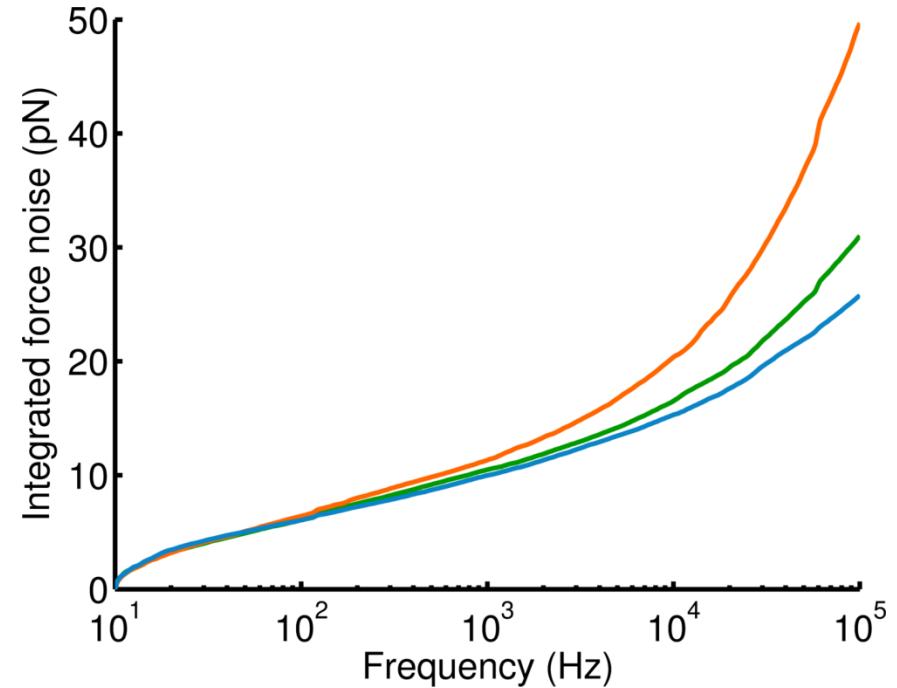
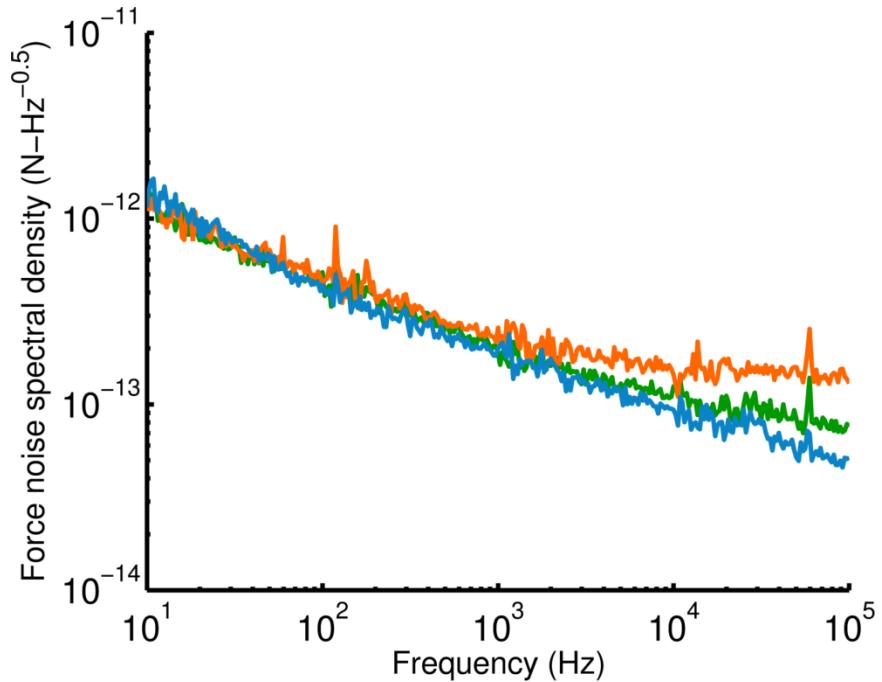
# FGAs are bad (for thin, n-type piezos)



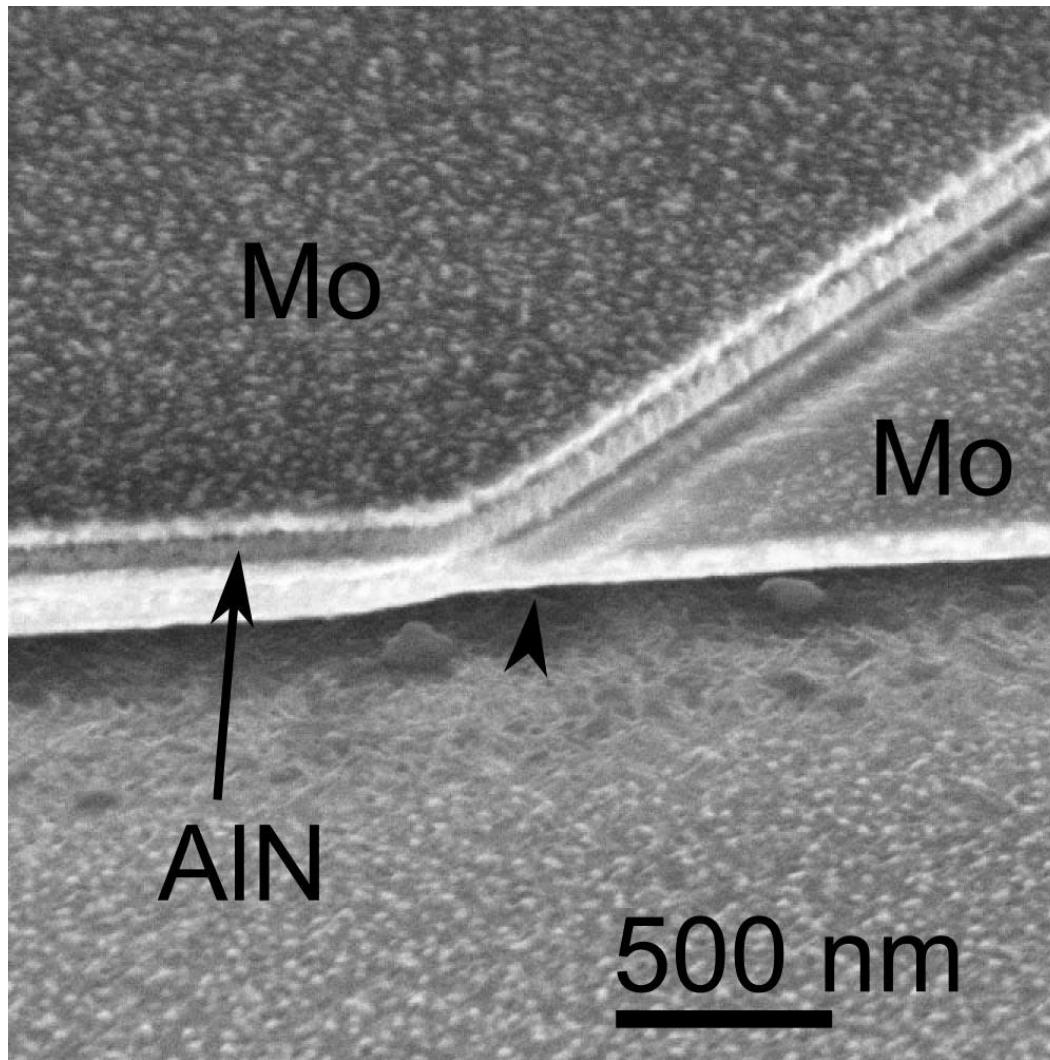
# FGAs are bad (for thin, n-type piezos)



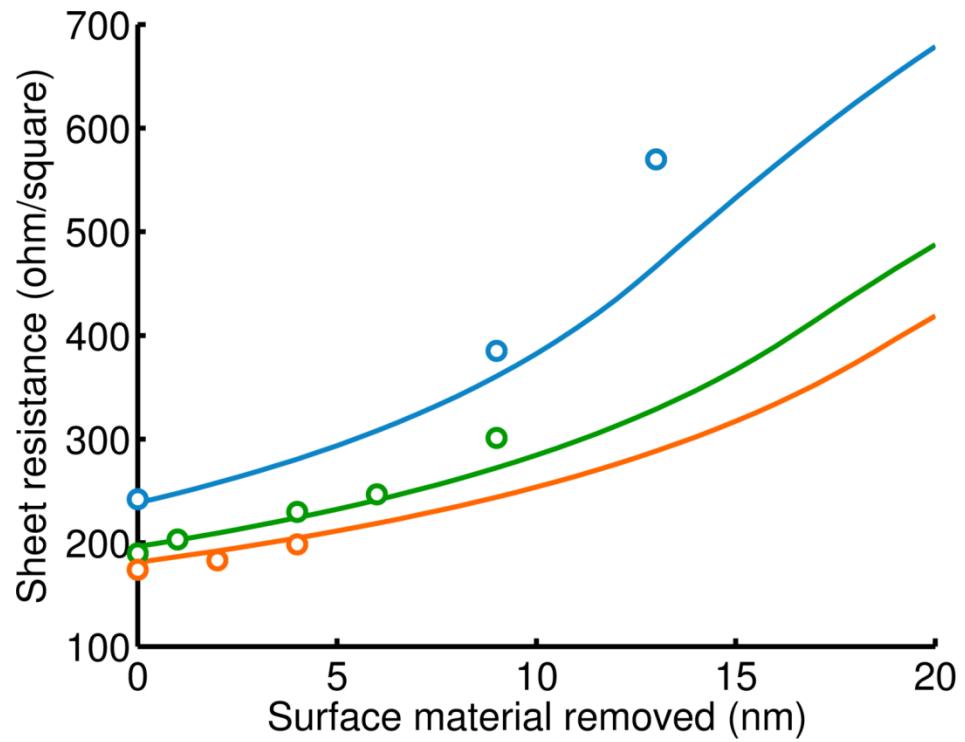
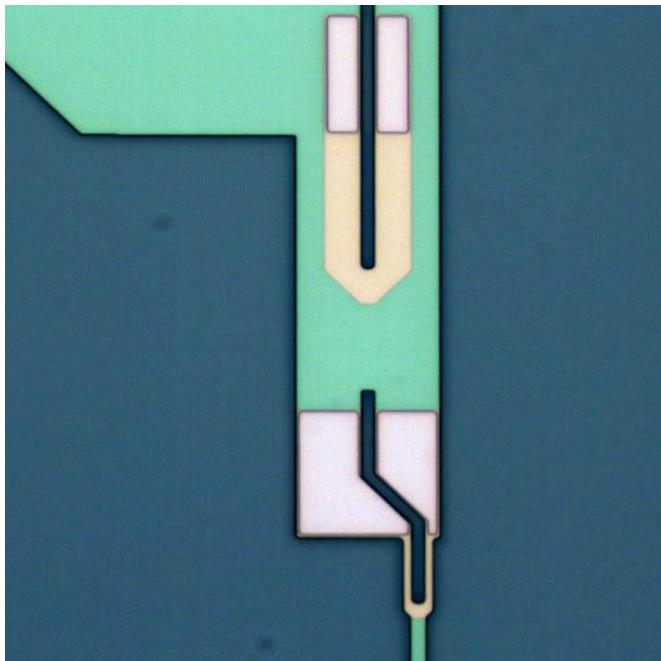
# Effect of bridge bias



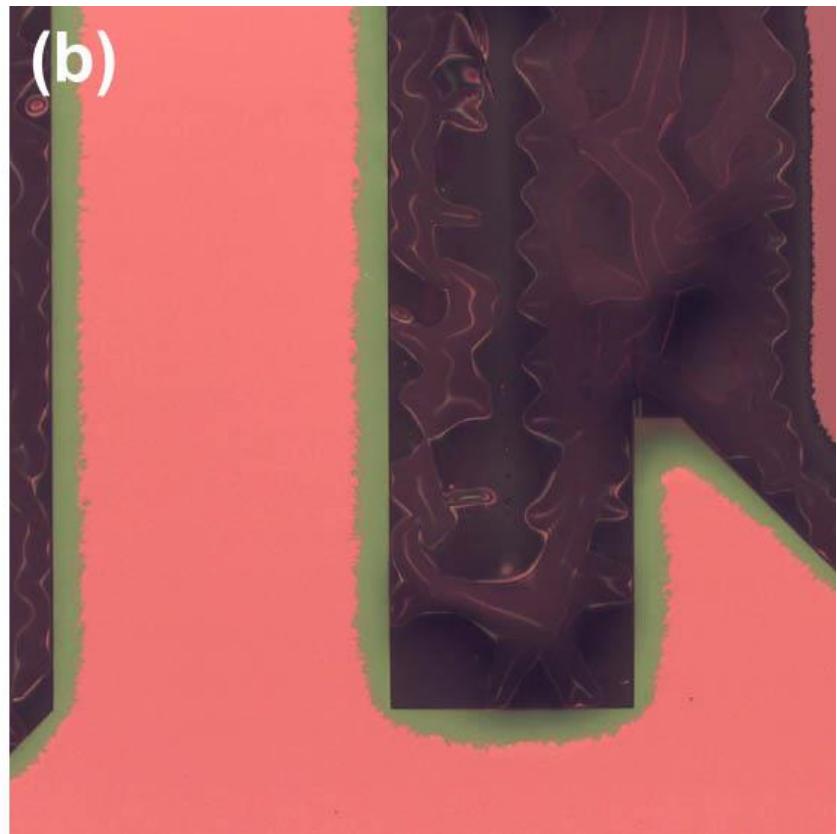
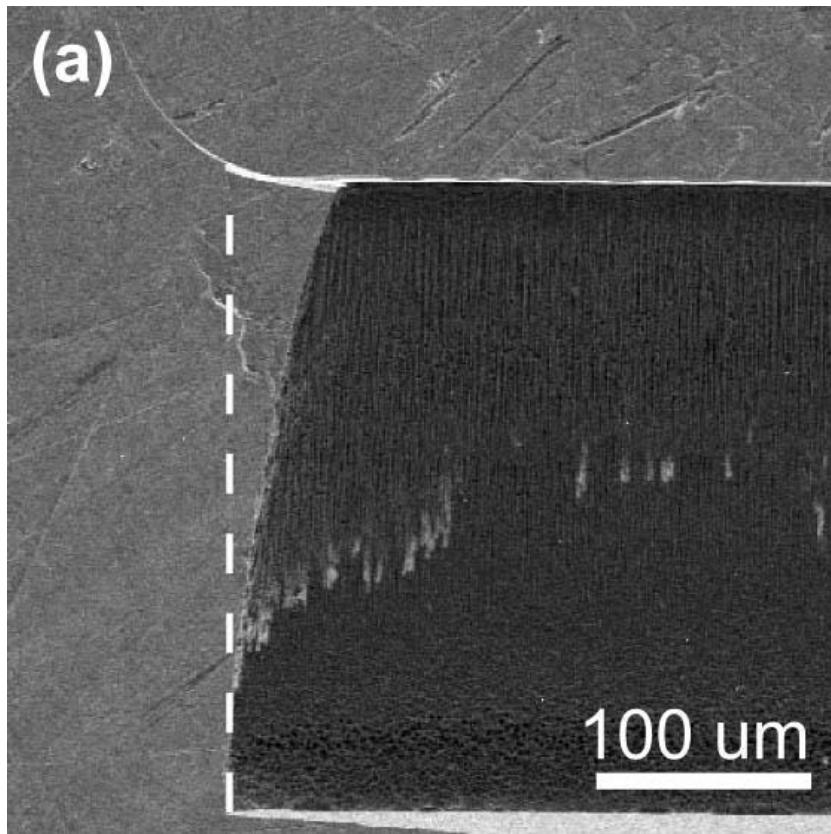
# Etching the AlN/Mo stack



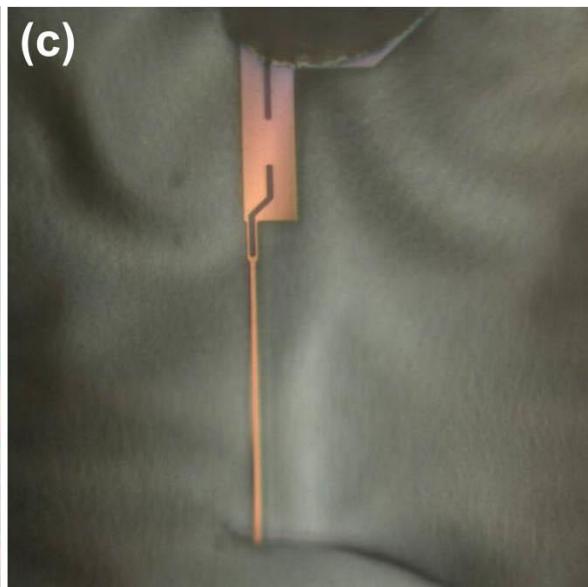
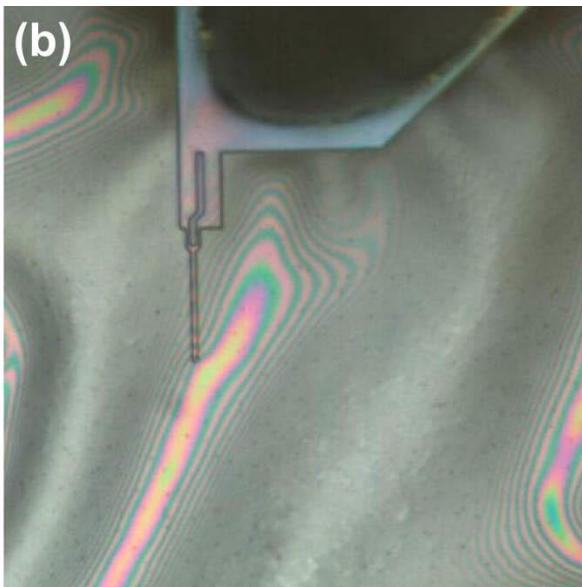
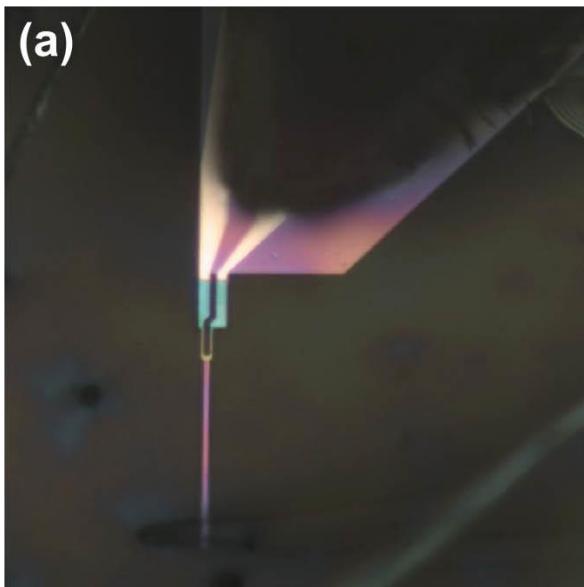
# Fabricating thin devices



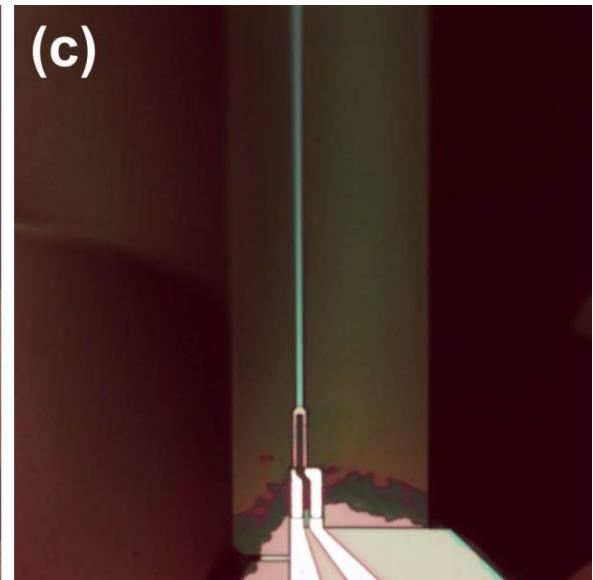
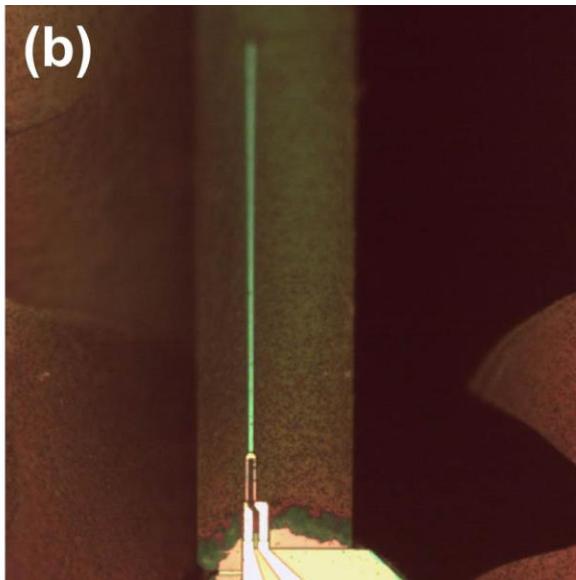
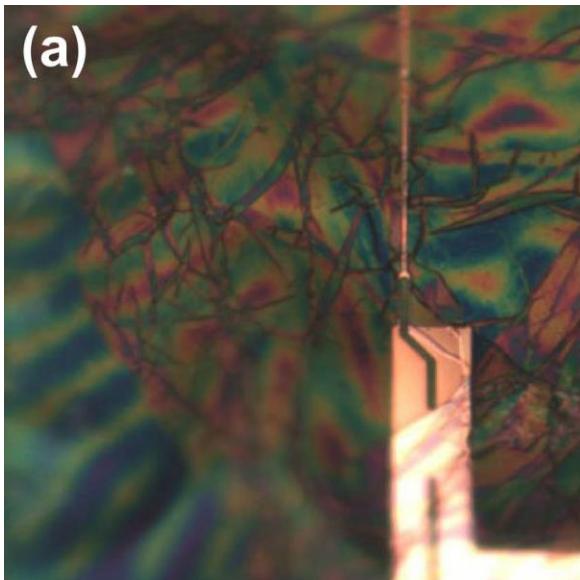
# DRIE Issues



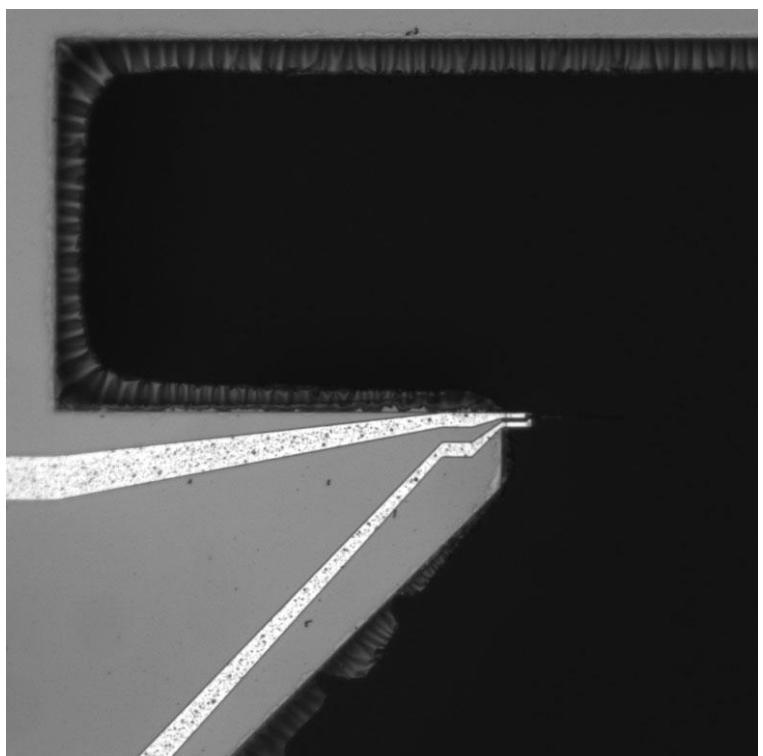
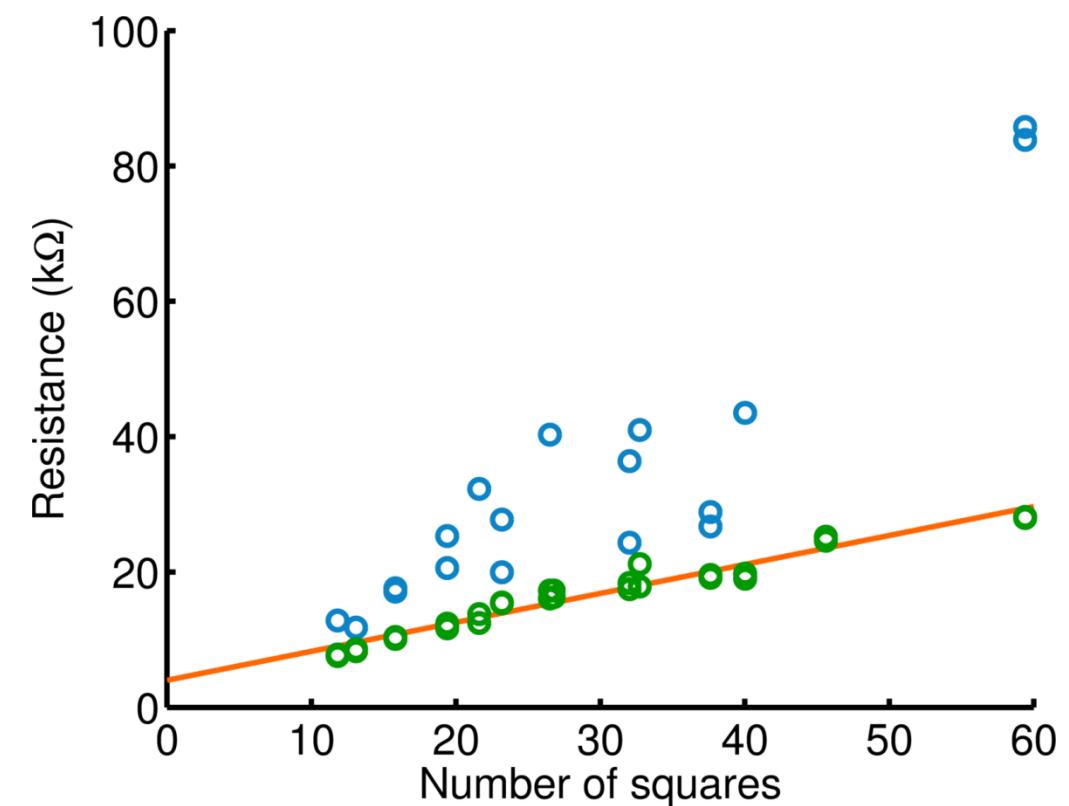
# DRIE undercut vs. trench width



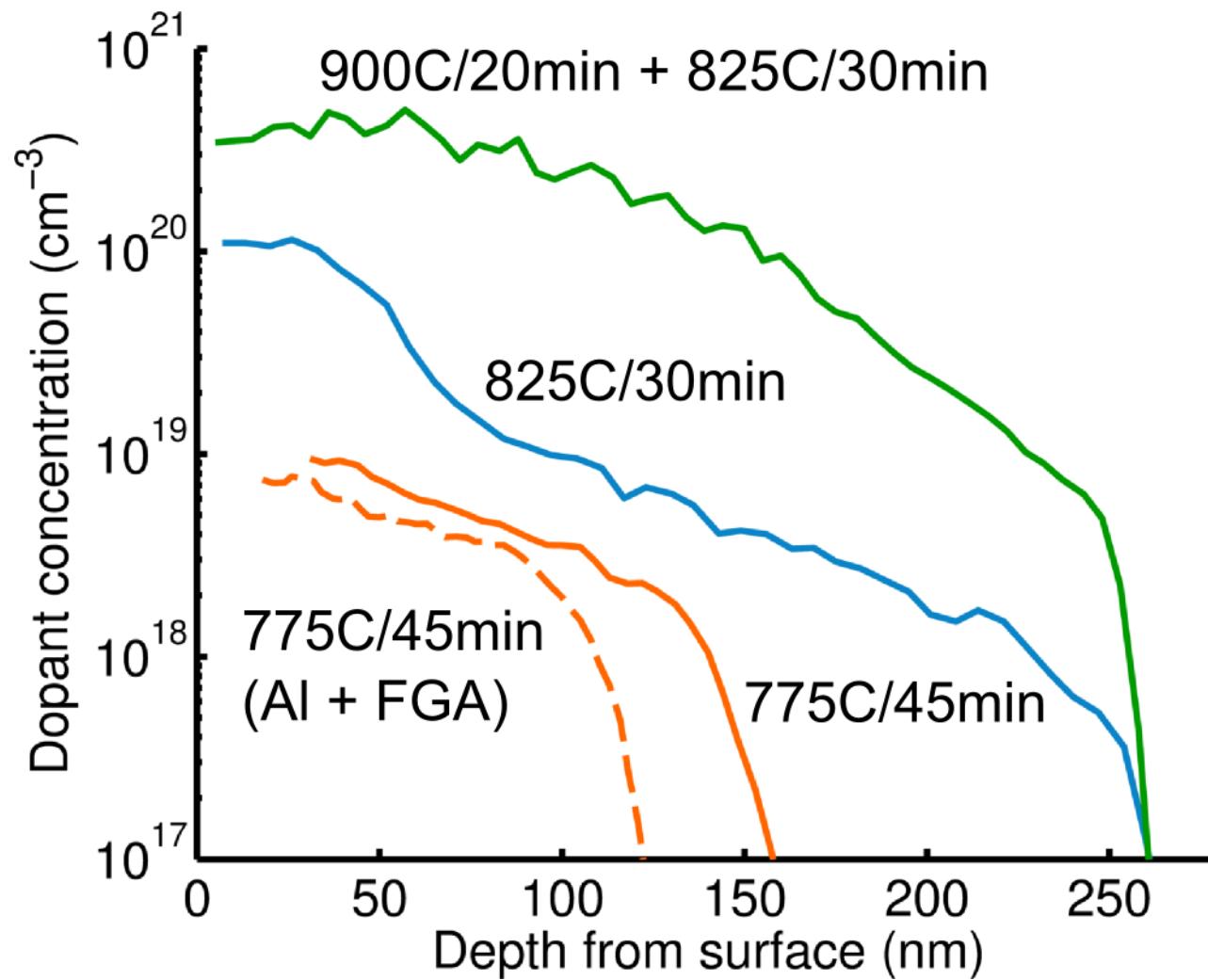
# DRIE polymer cleanup



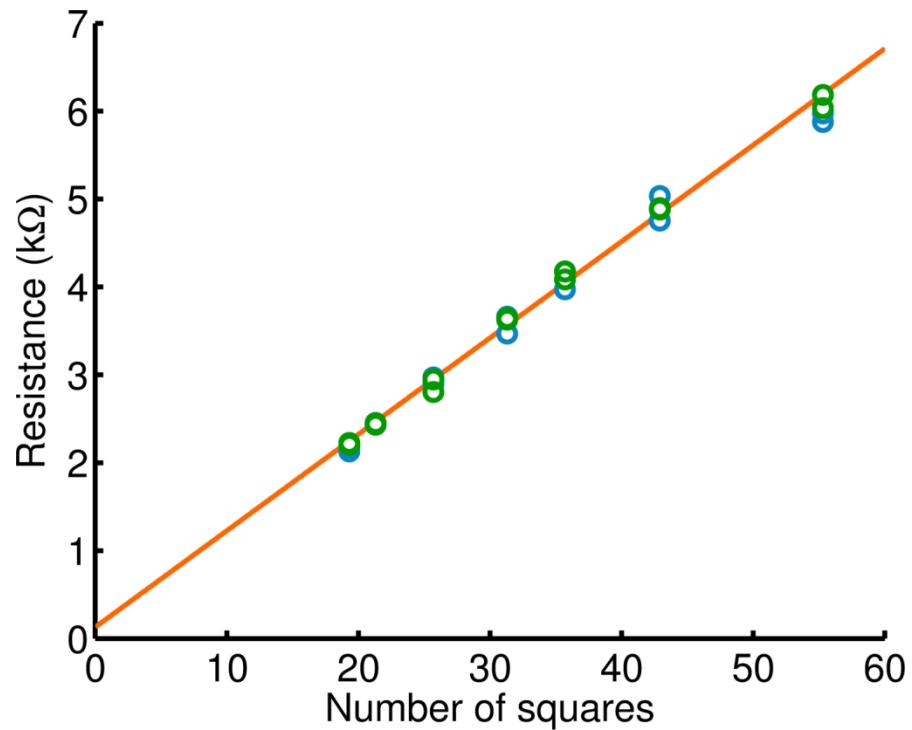
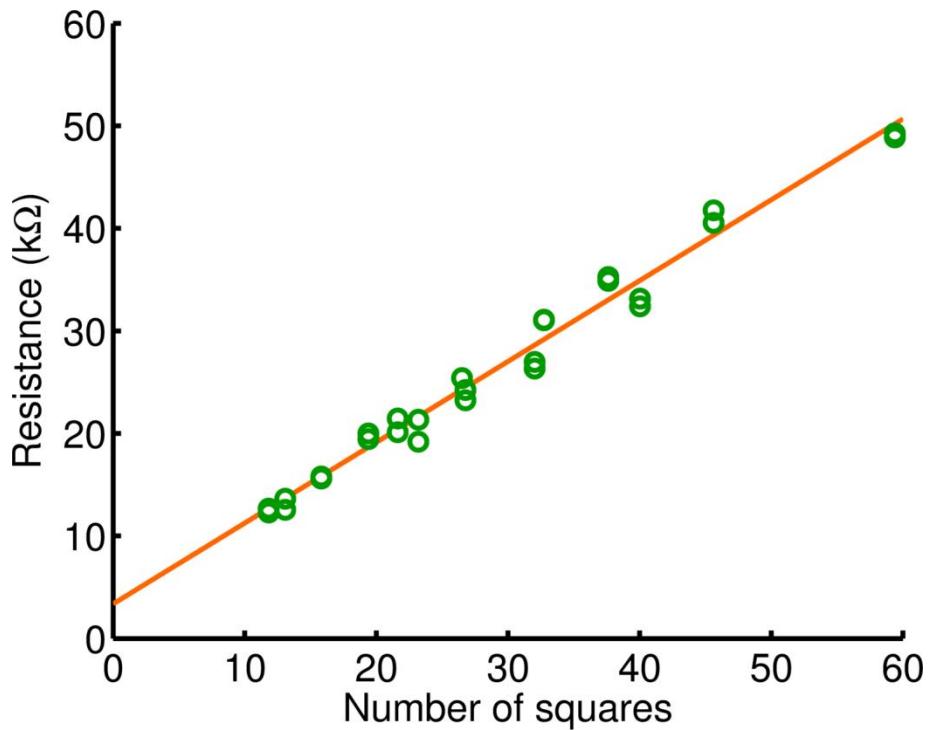
# RIE BOX release issues



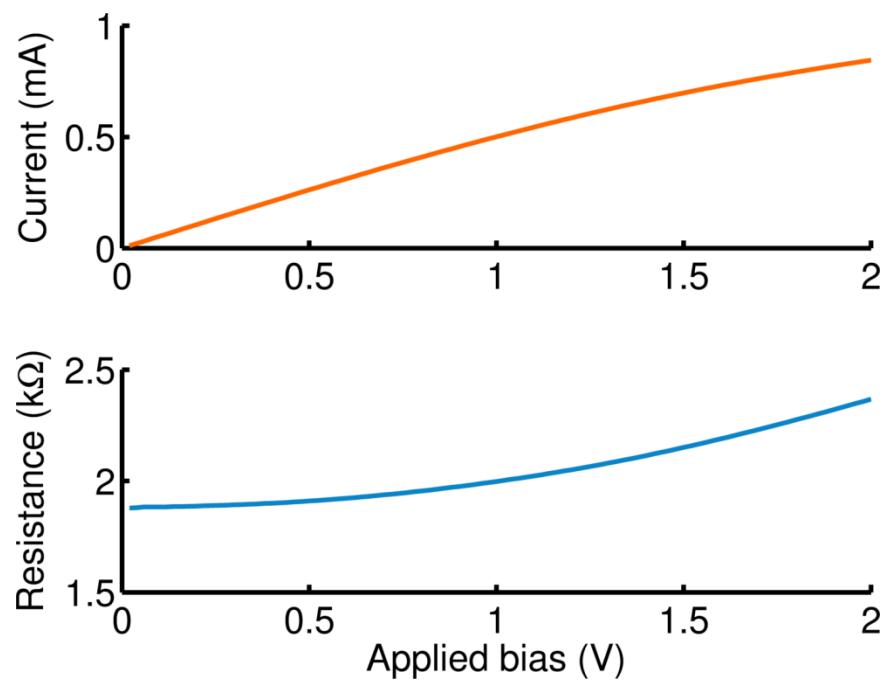
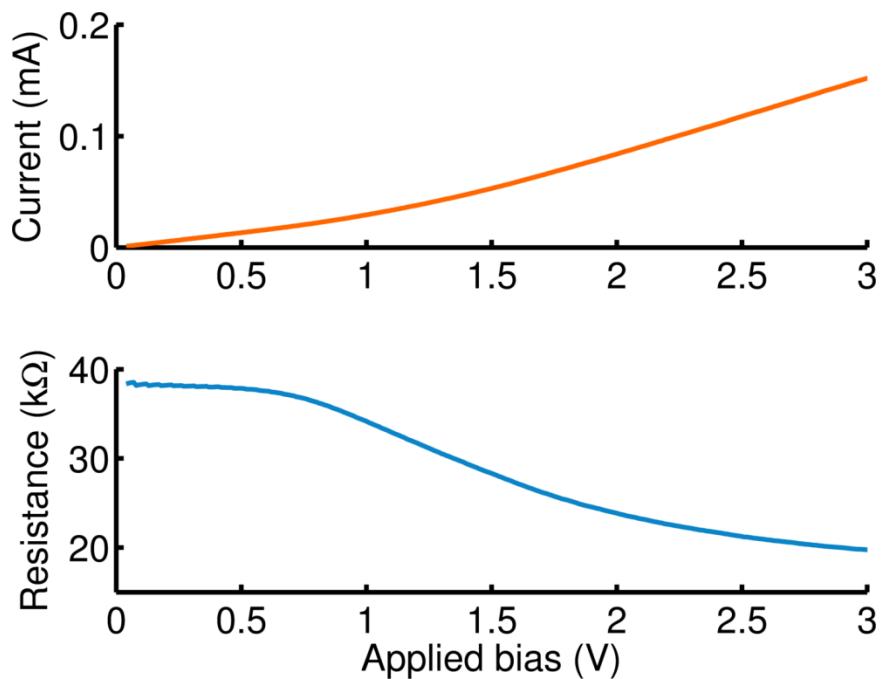
# Why the extra doping step?



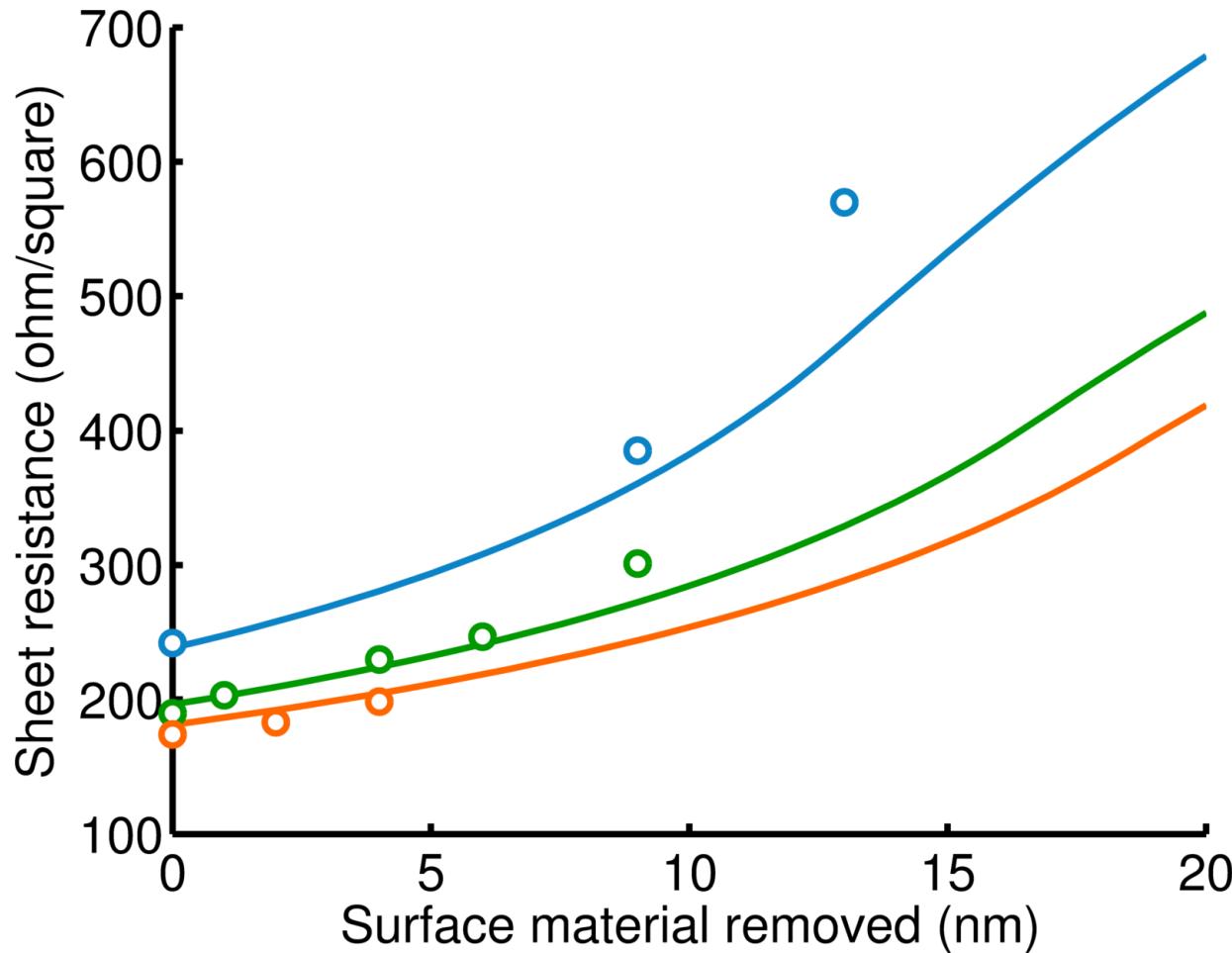
# Initial vs. optimized PR processes



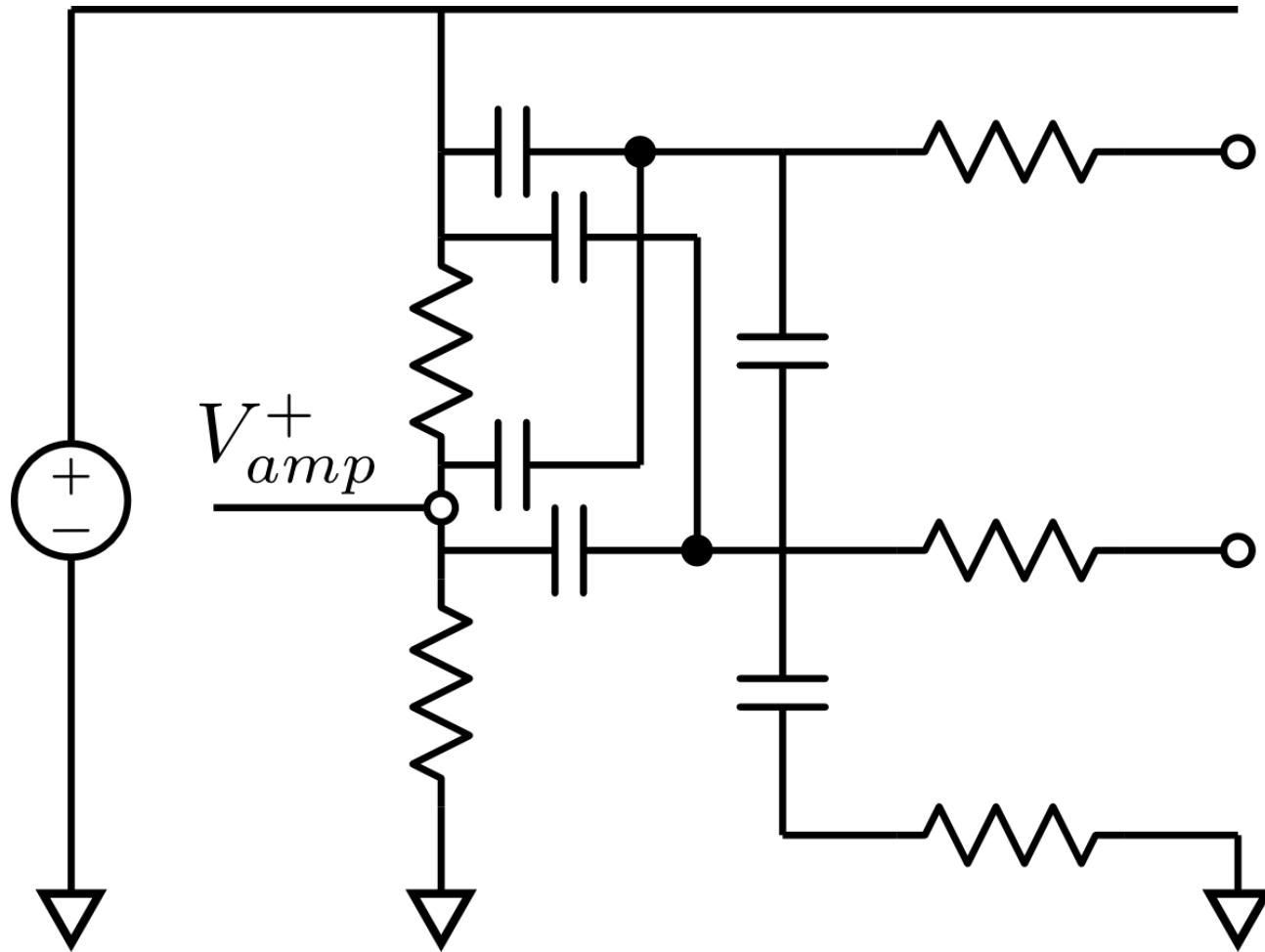
# Initial vs. optimized PR process



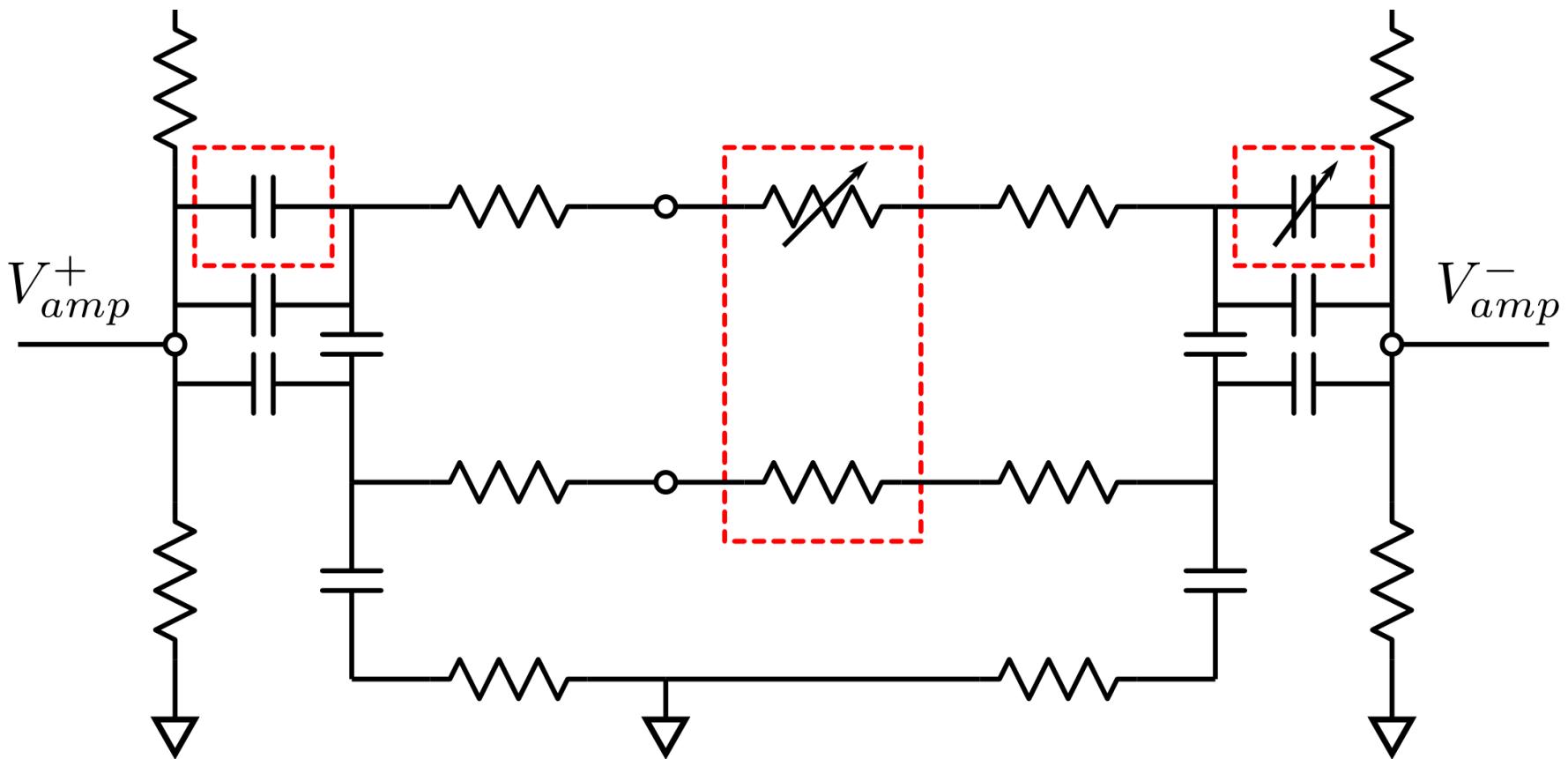
# The trouble with thin piezoresistors



# Crosstalk compensation



# Crosstalk compensation



# Actuator-patch crosstalk

